

Outline

2:00 pm: Introduction & Welcome

2:15 pm: Camera

2:45 pm: Boom

3:15 pm: Mirror Boxes

3:45 pm: On-board Software

4:15 pm: Electronics

Mission Overview

Maria Sakovsky

Motivation: Building Large Space Telescopes

- Mirror dia. of current and planned space telescopes limited by constraints of a single launch
 - Hubble (1990): Ø 2.4 m
 - JWST (2018): Ø 6.5 m
 - HDST (2030+): Ø 11.7 m
- New paradigms needed for Ø 30 m+ segmented primary:
 - Autonomous assembly in orbit
 - Active ultralight mirror segments
- Active mirrors relax tolerances for assembly and manufacturing, correct thermal distortions
- Modular, robust, low-cost architecture



JWST



HDST

Caltech

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AAReST Objectives

- Demonstrate key technologies:
 - Autonomous assembly and reconfiguration of modular spacecraft carrying mirror segments
 - Active, lightweight deformable mirrors operating as segments in a primary
- Operate for as long as necessary to accomplish the objectives (~90 days)
- Gather engineering data to enable development of the next system

AAReST Spacecraft



AAReST Spacecraft

CoreSat

Power, Comm., Telescope ADCS

Caltech



AAReST Spacecraft

MirrorSat (×1)

Reconfigurable free-flyers
U. of Surrey

CoreSat

Power, Comm., Telescope ADCS
Caltech



MirrorSat (×1)

Reconfigurable free-flyers
IIST

AAReST Spacecraft

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CoreSat

Power, Comm., Telescope ADCS
Caltech

Deformable Mirrors (×2)

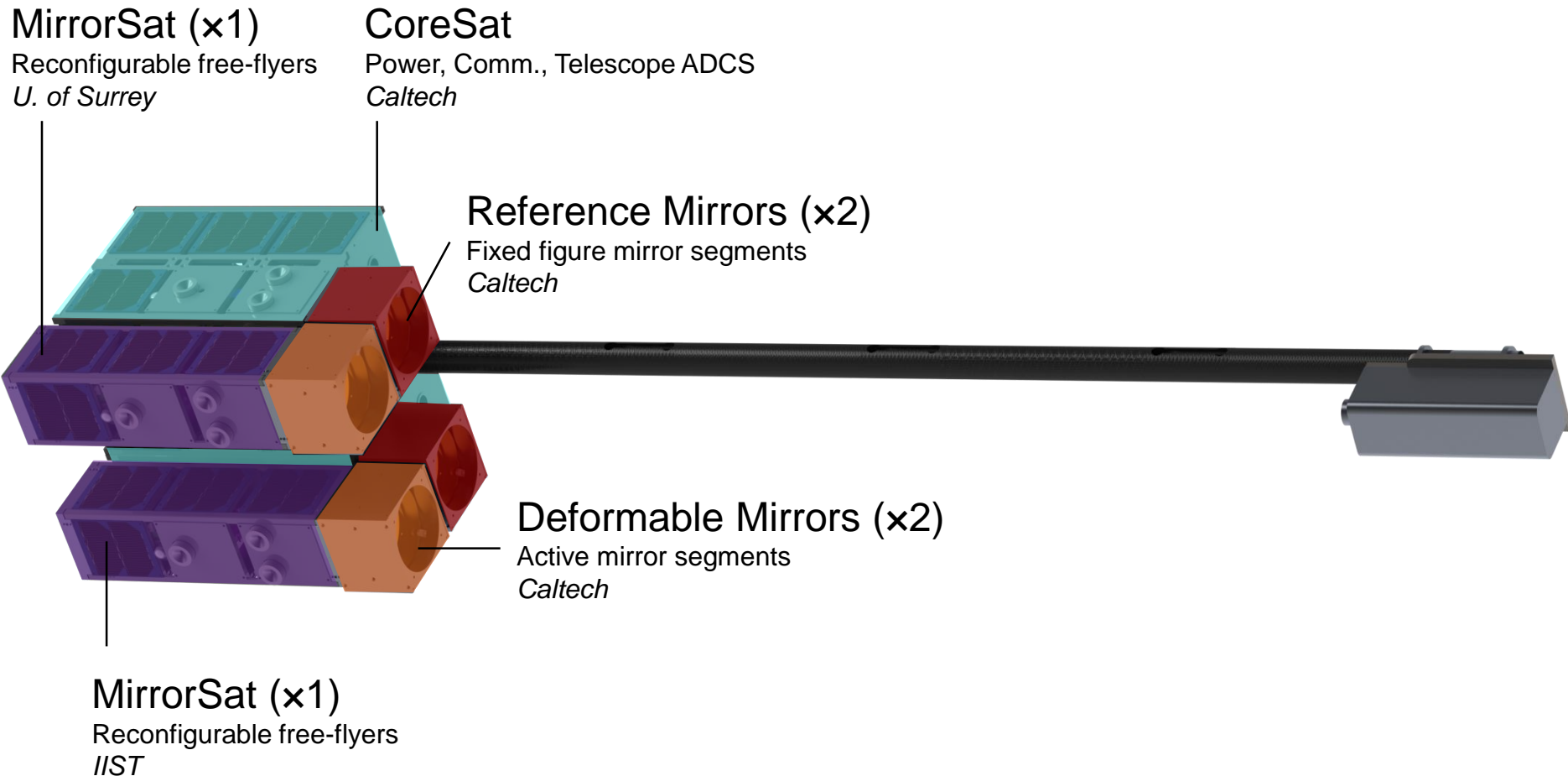
Active mirror segments
Caltech

MirrorSat (×1)

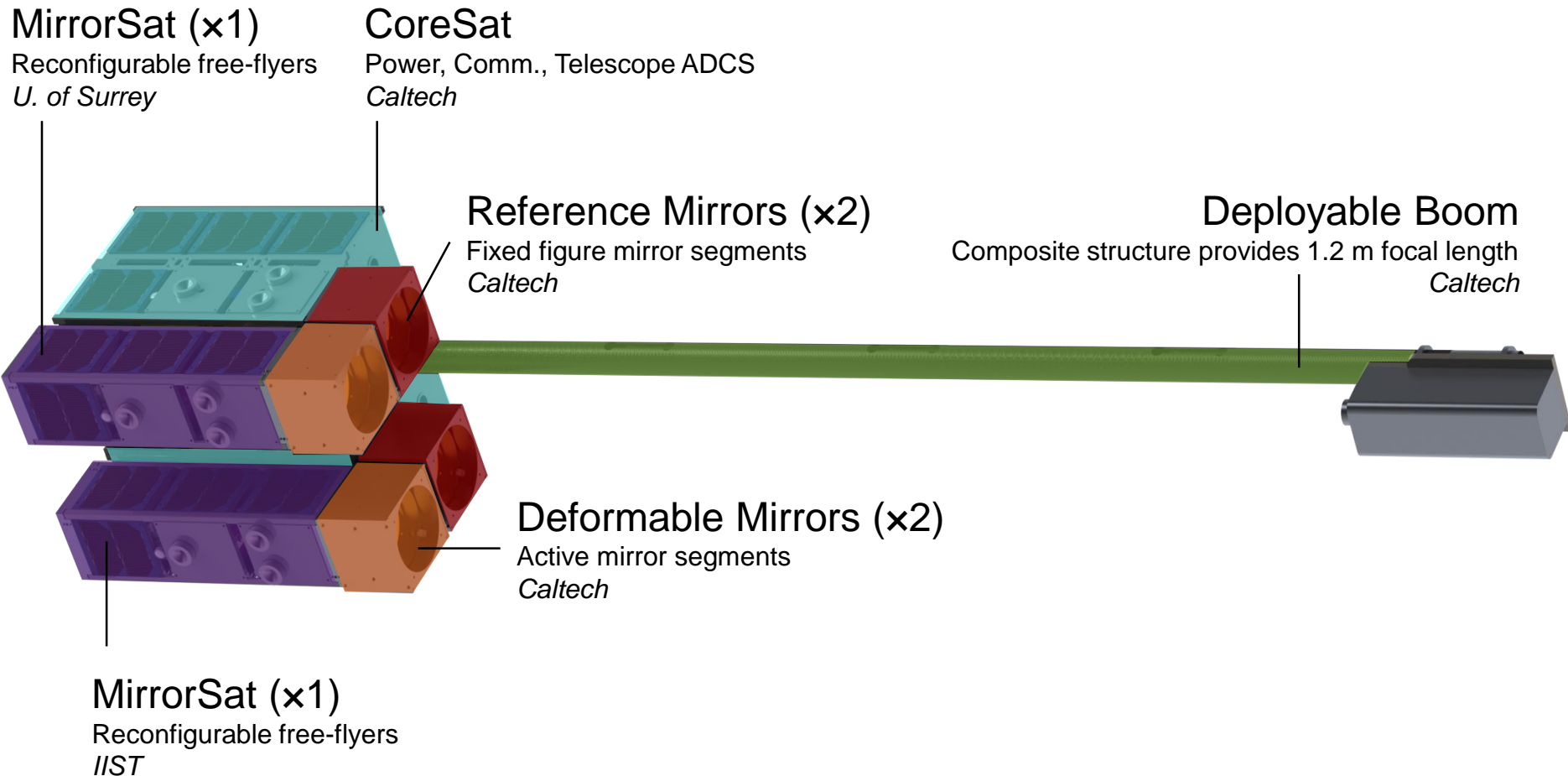
Reconfigurable free-flyers
IIST



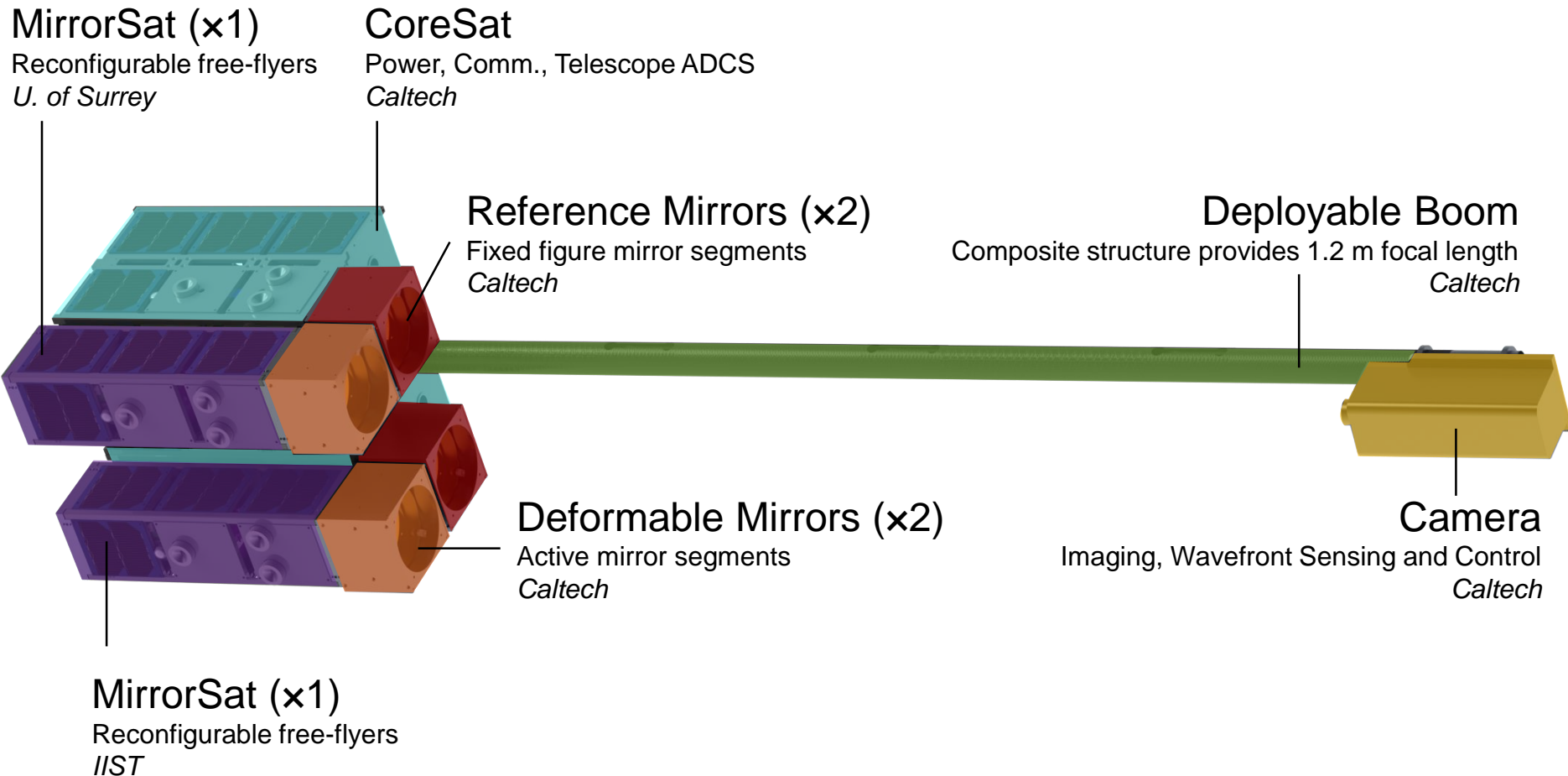
AAReST Spacecraft



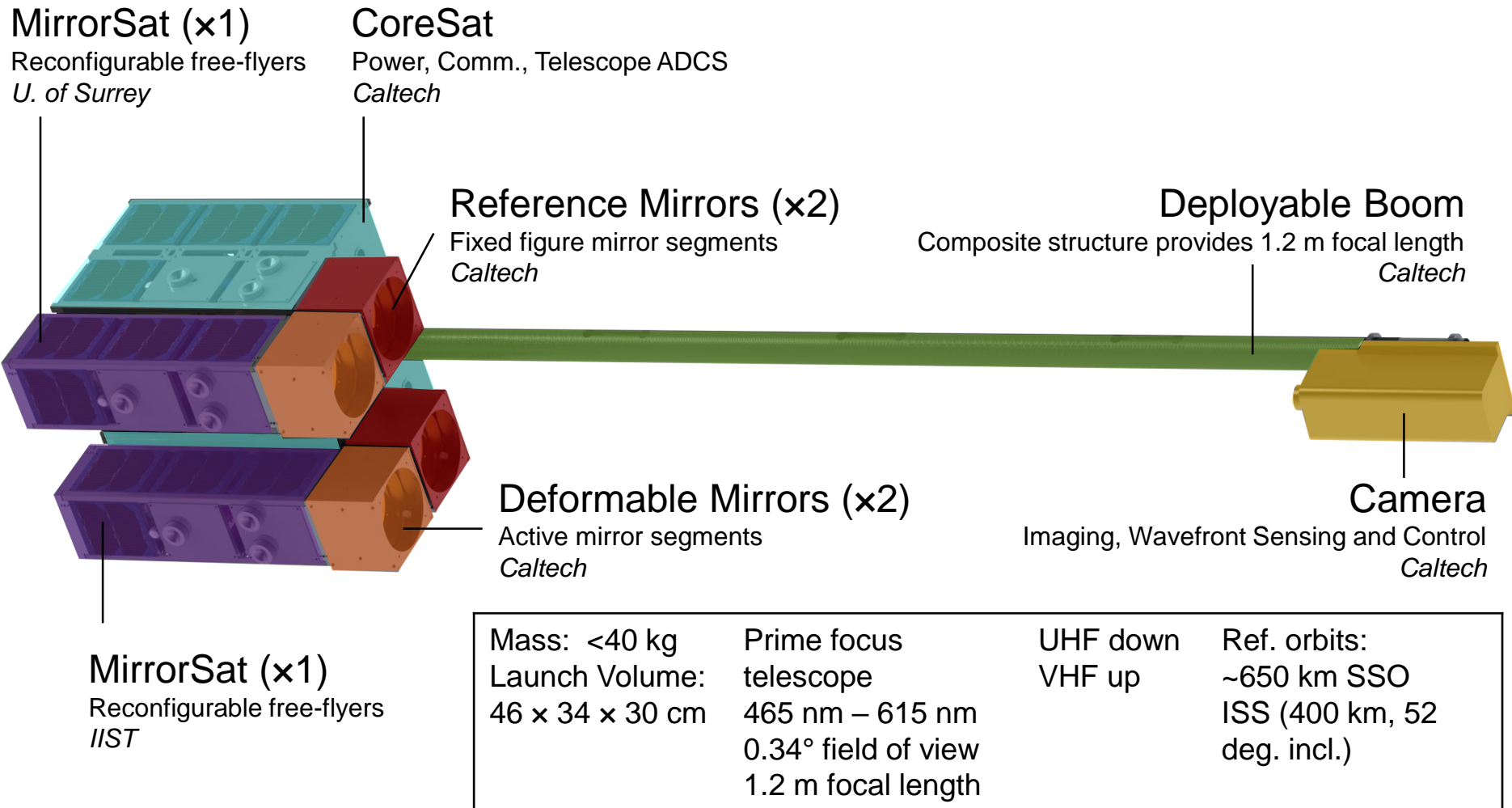
AAReST Spacecraft



AAReST Spacecraft



AAReST Spacecraft

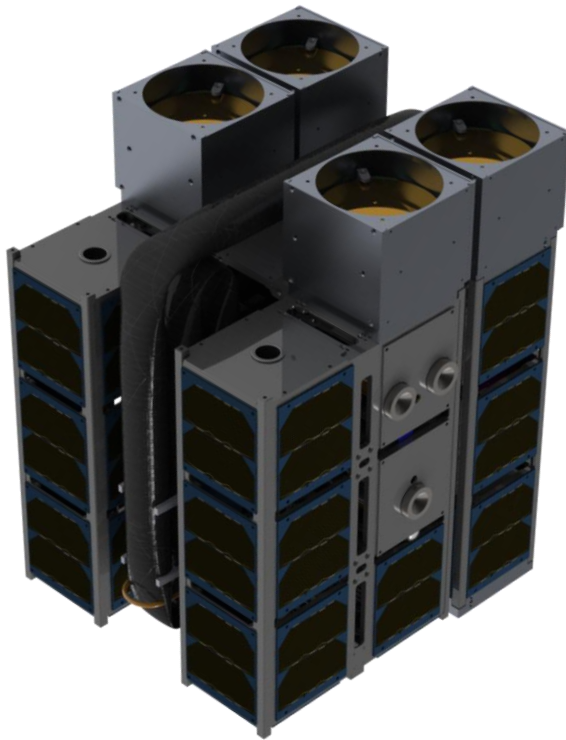


Mission Requirements

- Minimum mission
 1. Produce one focused image from a deformable mirror
 - 80% encircled energy radius from point source $< 25 \mu\text{m}$
 2. Perform at least one in-flight autonomous spacecraft reconfiguration maneuver to demonstrate space assembly capability
- Extended mission
 1. Produce one focused image from a deformable mirror after reconfiguration
 2. Coalign images to improve SNR and demonstrate precursor to co-phasing
 3. Produce at least two images of other sources (e.g. Earth and Moon) for outreach purposes

Concept of Operations

1. Launch	2. Telescope Deployment	3. Telescope Calibration & Imaging	4. Reconfiguration	5. Telescope Recalibration & Imaging	6. Extended Mission
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Launch in a compact, stowed volume

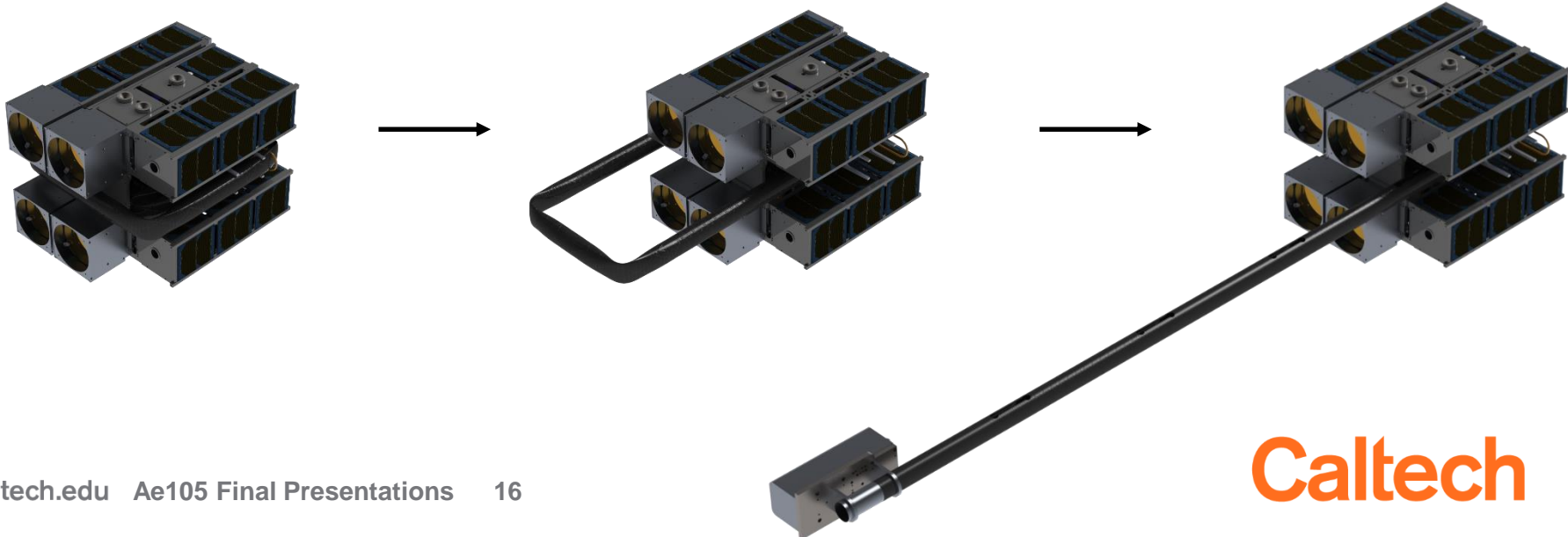
- 46 cm x 34 cm x 30 cm

Concept of Operations

1.	2.	3.	4.	5.	6.
Launch	Telescope Deployment	Telescope Calibration & Imaging	Reconfiguration	Telescope Recalibration & Imaging	Extended Mission

- Turn on, verify satellite components
- Stabilize attitude, temperature

- Deploy boom in two stages:
 1. Boom segments unfold
 2. Camera is released
- Uncage deformable mirrors



Concept of Operations

1.	2.	3.	4.	5.	6.
Launch	Telescope Deployment	Telescope Calibration & Imaging	Reconfiguration	Telescope Recalibration & Imaging	Extended Mission

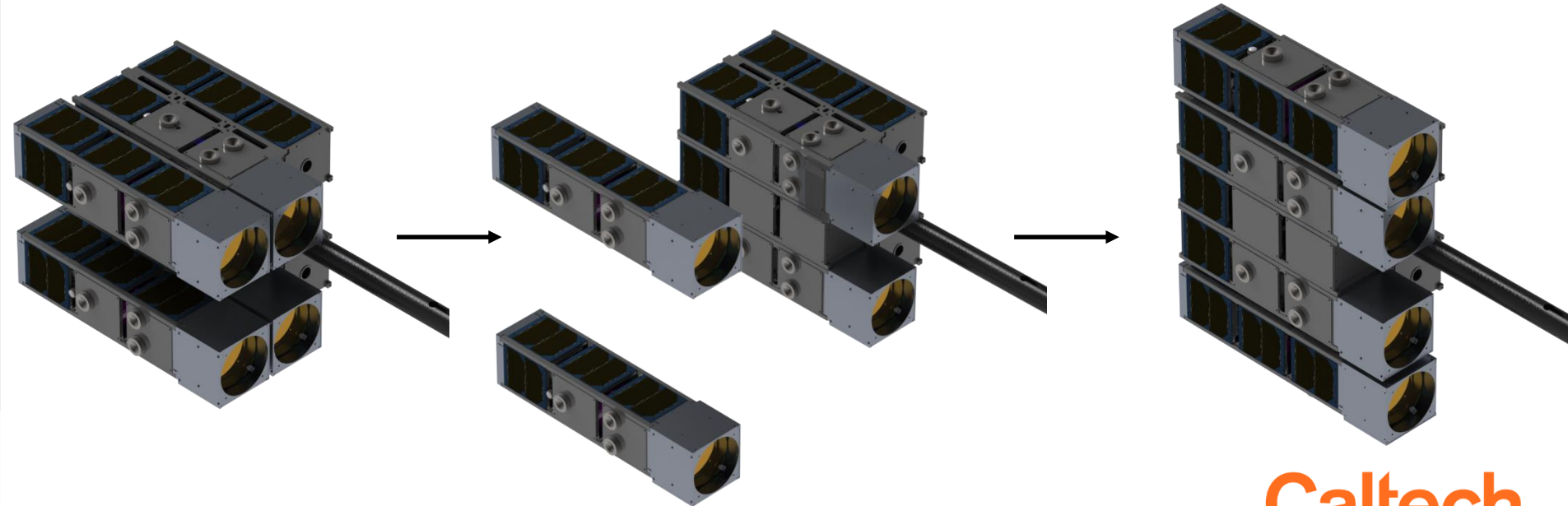


- Telescope points to a bright reference star
- Calibrate:
 - Segment tip/tilt/piston
 - Deformable mirror surface figure
- Camera provides feedback for segment calibration

Concept of Operations

1.	2.	3.	4.	5.	6.
Launch	Telescope Deployment	Telescope Calibration & Imaging	Reconfiguration	Telescope Recalibration & Imaging	Extended Mission

- MirrorSats release from CoreSat (one at a time)
- Fly out ~1 m
- Re-dock into “wide” configuration



Concept of Operations

1. Launch	2. Telescope Deployment	3. Telescope Calibration & Imaging	4. Reconfiguration	5. Telescope Recalibration & Imaging	6. Extended Mission
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- Telescope points to a bright reference star
- Calibrate:
 - Segment tip/tilt/piston
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Concept of Operations

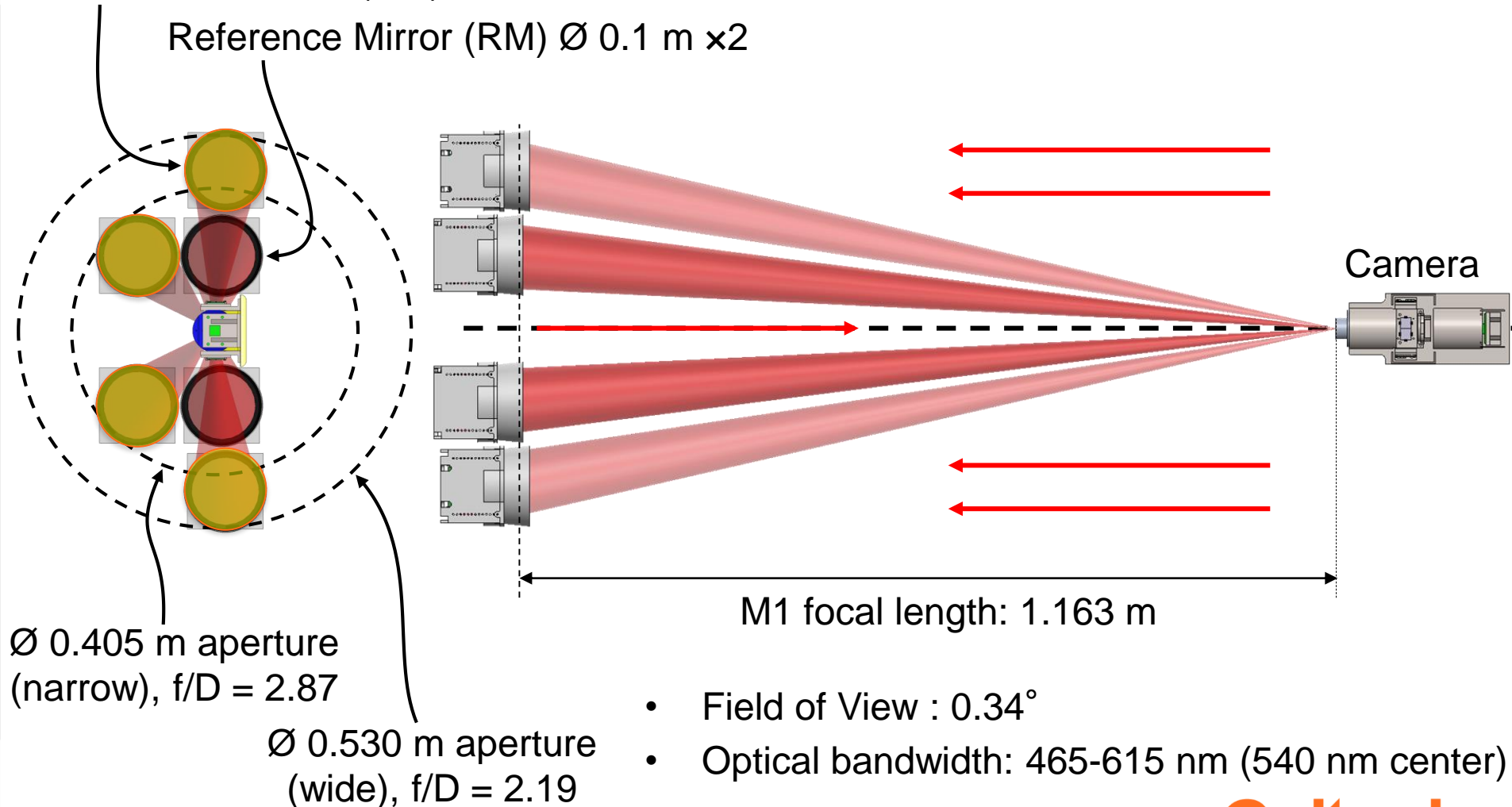
1. Launch	2. Telescope Deployment	3. Telescope Calibration & Imaging	4. Reconfiguration	5. Telescope Recalibration & Imaging	6. Extended Mission
--------------	-------------------------------	---	-----------------------	---	---------------------------

- Co-align star images from different segments to improve SNR
 - Pre-cursor to co-phasing
- Produce images of extended sources (e.g. Moon, Earth) for outreach

AAReST Optical Overview

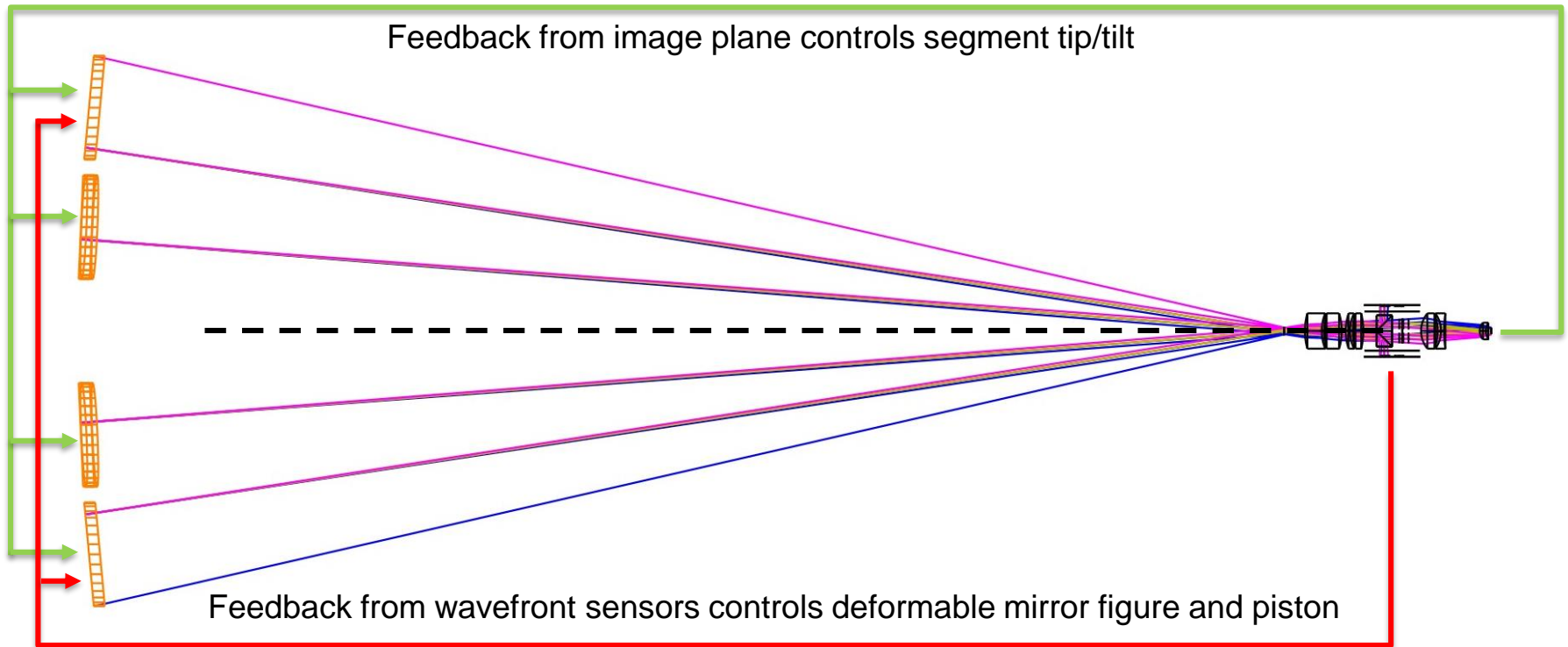
Deformable Mirror (DM) Ø 0.1 m x2

Reference Mirror (RM) Ø 0.1 m x2



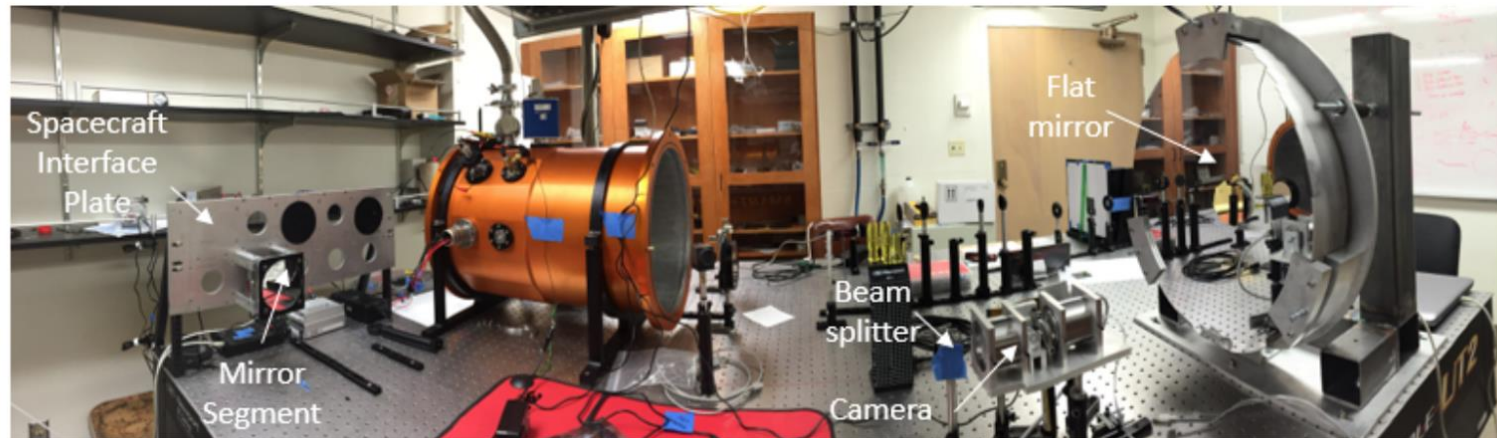
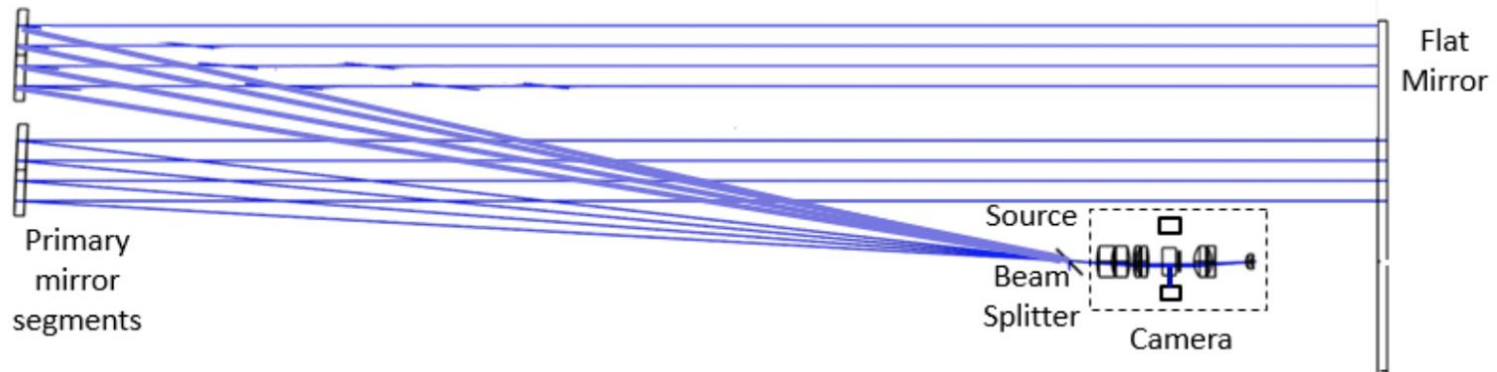
Telescope Alignment and Control

- Actuators:
 - 3 rigid body motion (RBM) actuators per segment
 - 41 piezoelectric actuators per deformable mirror
- Sensors:
 - Image plane camera
 - Shack-Hartmann Wavefront Sensors (SHWS)

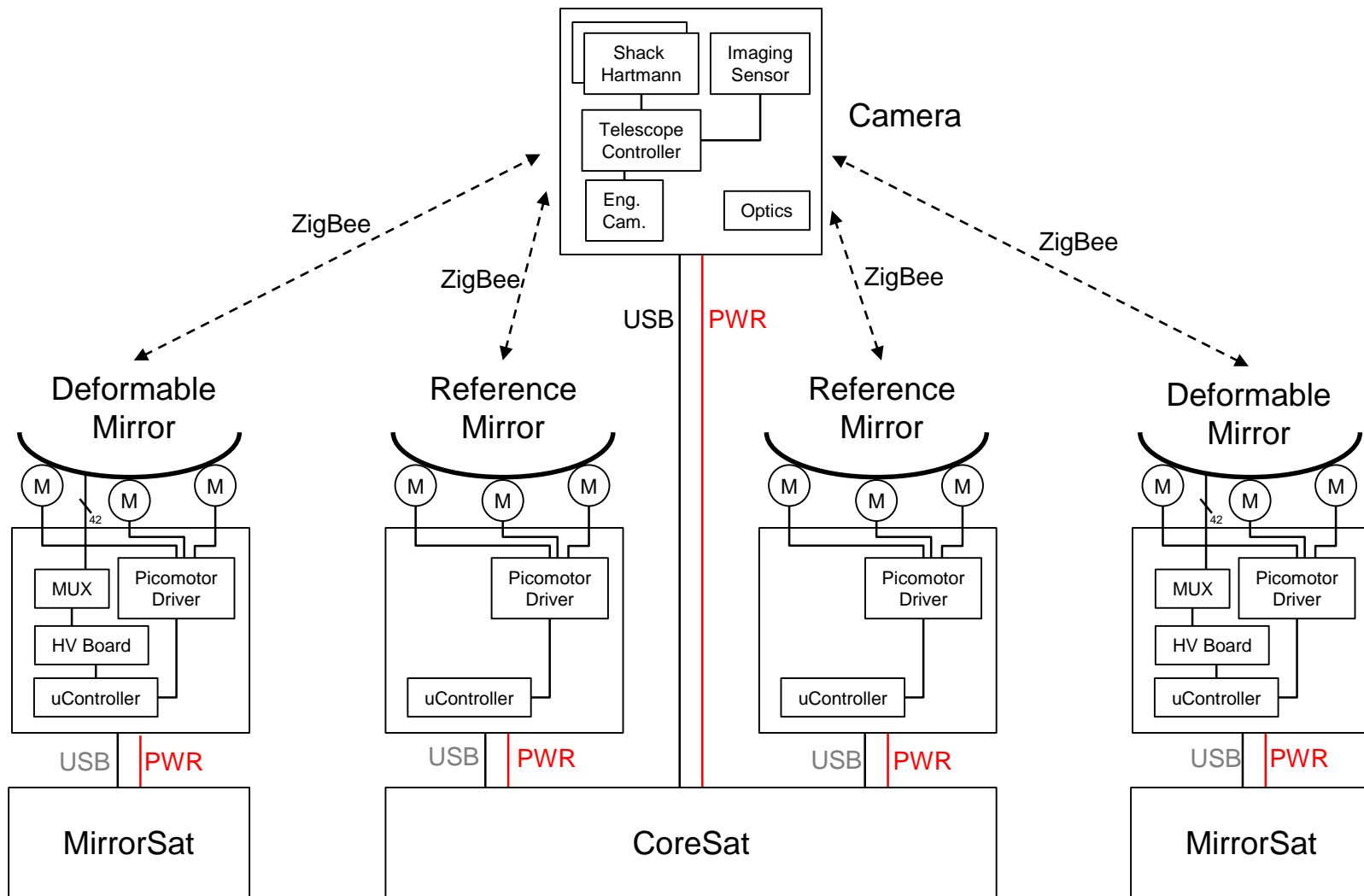


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AAReST Payload Block Diagram



Team Responsibilities

- Caltech
 - Deformable mirrors
 - Telescope system
 - Boom
 - CoreSat
- University of Surrey
 - MirrorSat x1
 - Docking system
 - Mission ops
- Indian Institute of Space Science and Technology
 - MirrorSat x1
- JPL
 - Class instructors
 - Project management

Caltech Team

- Ae105 class designs, builds, analyzes, tests components
- Ae205 class provides mentorship and guidance
- JPL class instructors, project manager
- JPL provides mirror manufacturing facilities
- Postdocs, upper-year grad students, SURF students provide focused support

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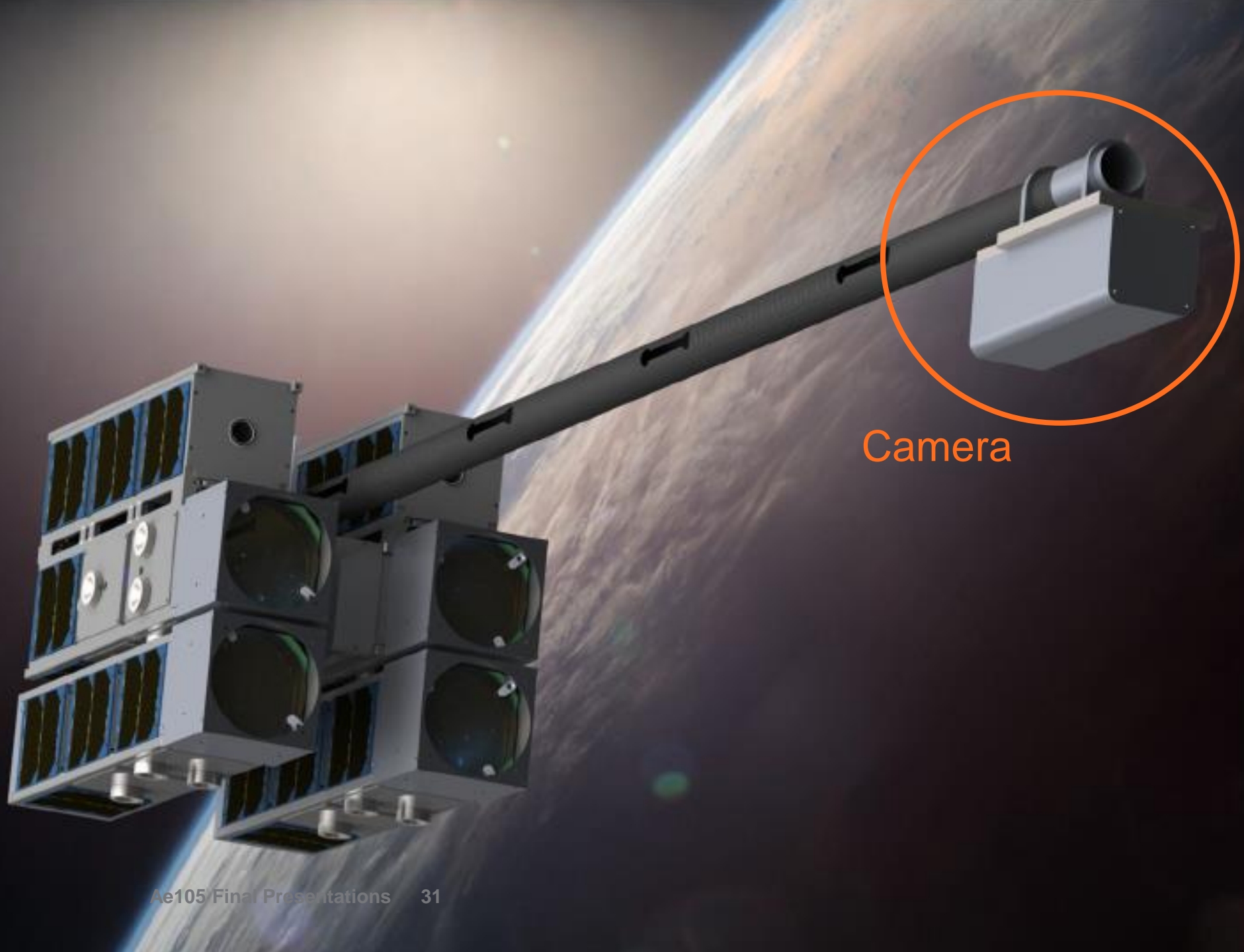
3:45 pm: On-board Software

4:15 pm: Electronics

AAReST Camera Team

Frederick Berl
Carlos Gonzalez
Kimberly Liu
Erika Schibber
William Yu

Mentor: Maria Sakovsky

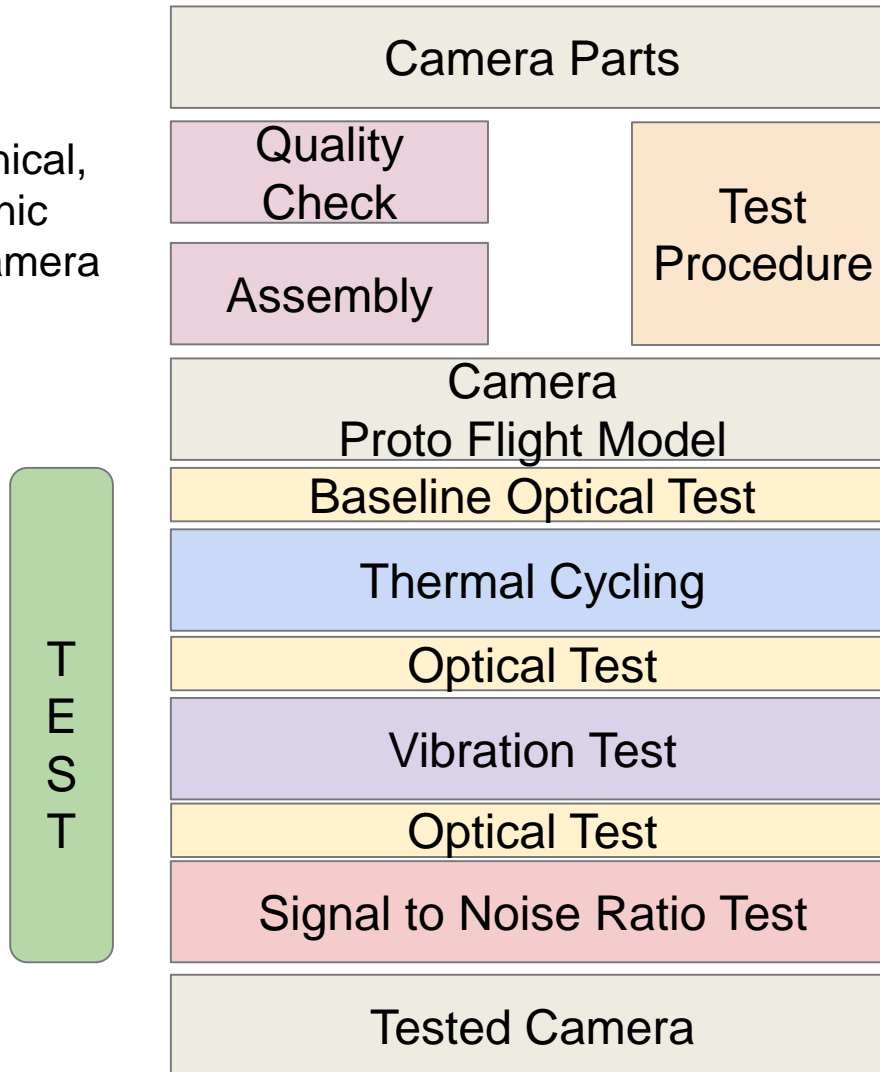


Camera

Project Workflow

Goals:

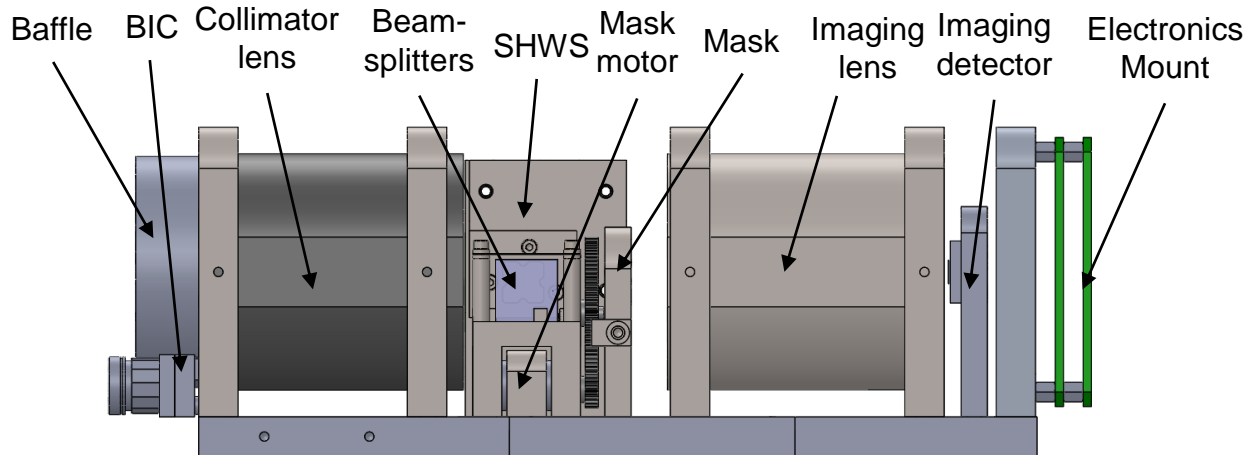
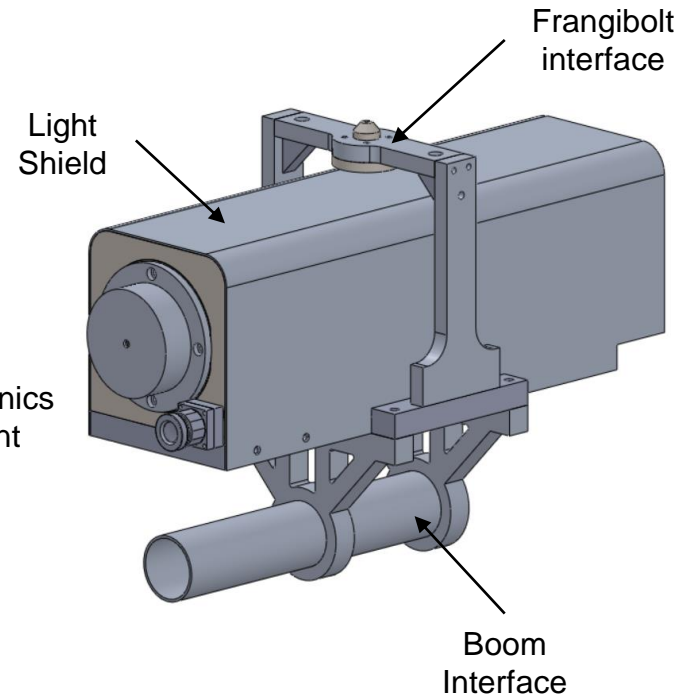
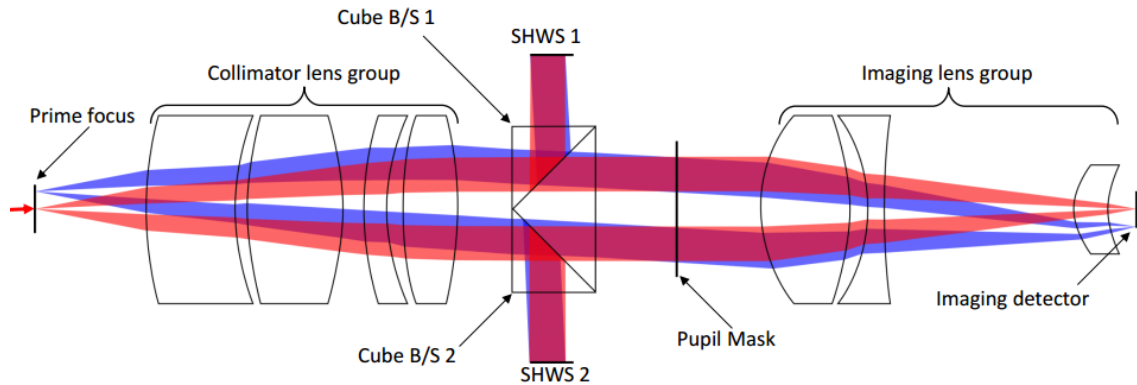
Integrate the mechanical, optical and electronic components of the camera



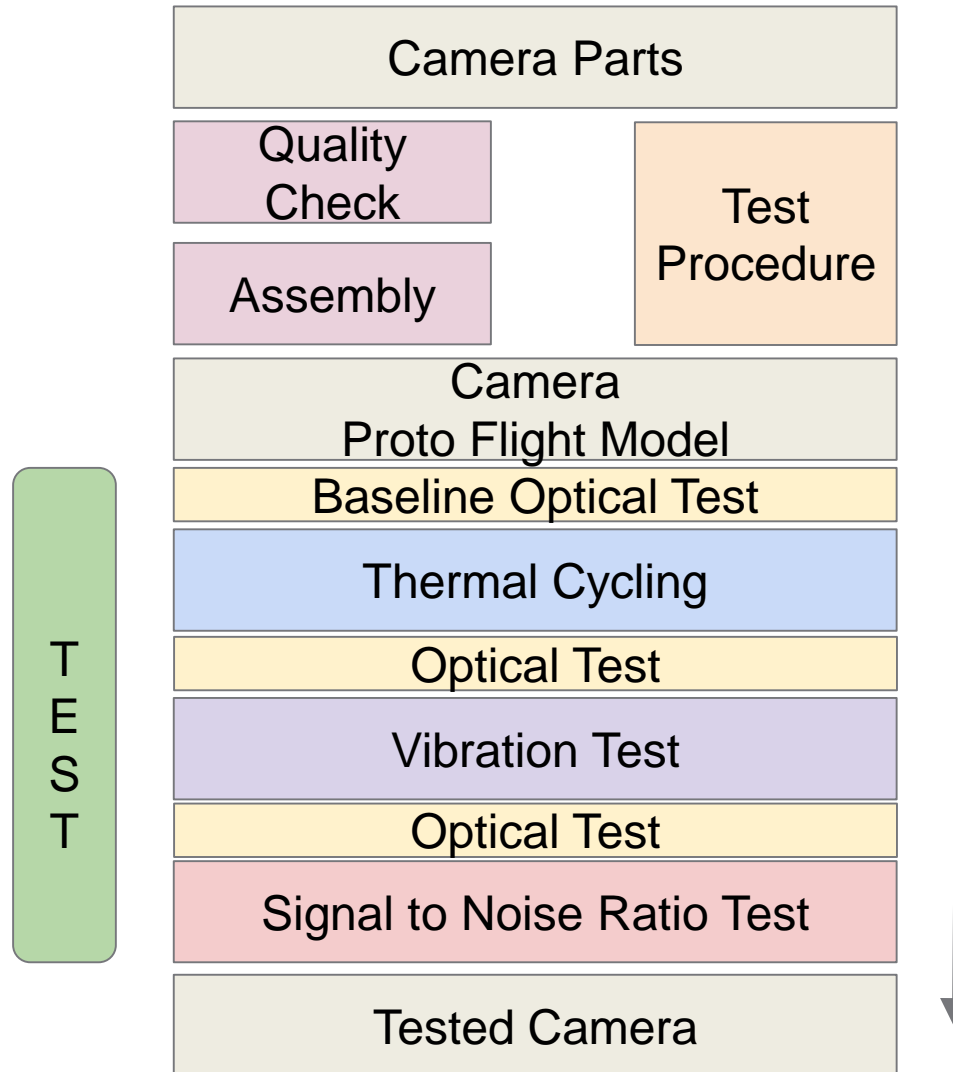
Goal:
Create assembly and test procedures

Goal:
Test the camera to verify it work as expected and won't break during launch

The Camera



Project Workflow

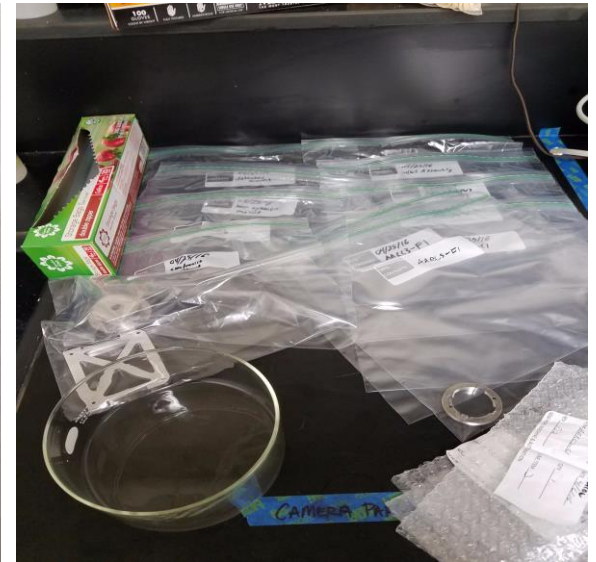
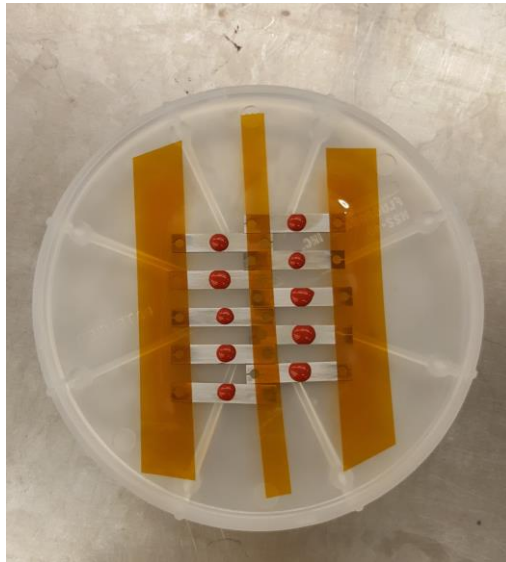


Assembly and Quality Check: Tasks

- Design assembly procedures
 - ✓ Created a set of comprehensive procedures
 - Cleaning, RTV application, and Assembly/Clean room procedures
- Quality Checking
 - ✓ Measured every part and checked if it was within specifications
 - ✓ Made sure parts fit together
 - Sent out parts that very clearly weren't within spec to be fixed (i.e. parts that didn't fit together)
- Camera Assembly
 - ✓ Fully assemble all available parts in the clean room using the relevant procedures

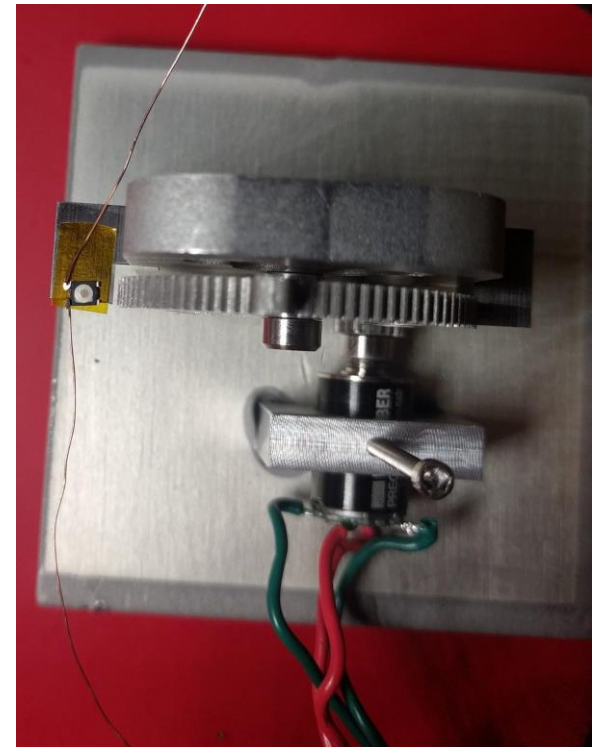
Assembly and Quality Check: RTV Test and Cleaning

Procedures are in place to apply RTV silicone, as well as to clean the parts and minimize their exposure to dust.



Mask Test

- Mask mechanism verification
 - ✓ Verify mask is rotated by stepper motor
 - ✓ Design limit switch mechanism
 - ▲ Find consistent mask rotation step sequence
- Stepper motor does not have enough torque to affect limit switch
 - Using two strips of conducting tape
- Mask jams occasionally during rotation
 - Postpone test until bearing is inserted



Assembly and Quality Check: Assembled Camera



Mass Budget

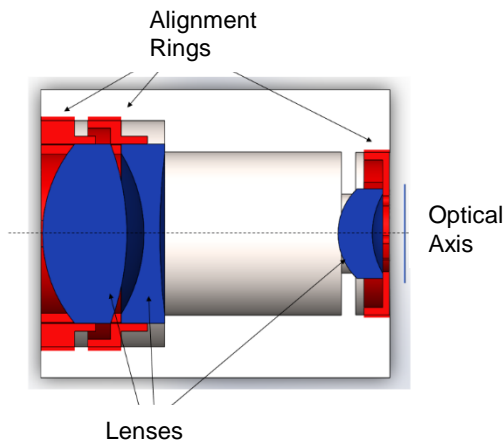
Camera Team Mass Budget				
Component	As Designed (g)	Margin (%)	As Designed + Margin (g)	Measured (g)
Metrology Plate	482	5	506	458
Collimator, Focal Group, and Beam Splitters	1238	5	1300	1148
Lens Mounts (4x)	320	5	336	304
Electronics Package (Al)	253	30	327	252
Fasteners & Wiring	181	20	217	181
SHWS Board and Mount (2x)	308	5	323	302
Light Shielding and Baffle	155	5	163	150
Boom Inspection Camera	17	5	18	17
Image Detector w/ Mount	45	5	48	44
Mask and Motor Assembly (Al)	48	5	51	54
Frangibolt and Boom Bracket (Al)	218	5	229	218
Total	3263		3517	3128

Assembly and Quality Check: Deviations from test-as-you-fly

Cleaning Procedures

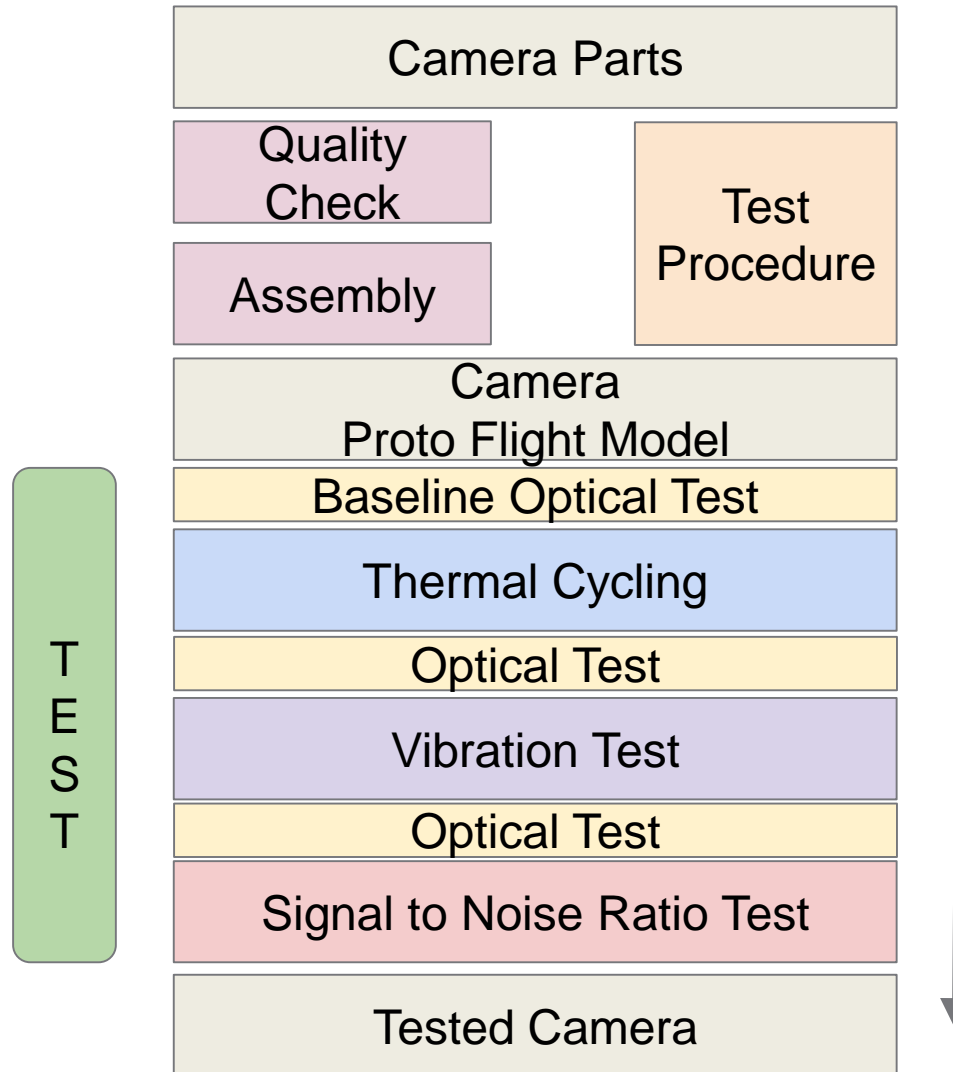
Item	Reason	Impact	Action
<i>Isopropyl Alcohol leaves residue</i>	The IPA was meant to be dried with compressed air	Low	Dry with compressed air/nitrogen

Assembly Procedures



Item	Reason	Impact	Action
<i>Bolt stuck in titanium plate (lens barrel assembly)</i>	Defective bolt snapped while torqueing	Low	Glue long rod to the bolt unscrew it
<i>Beam splitters not properly mounted</i>	One detent does not screw in all the way	Low	Get a new detent
<i>RTV spacer on lens R3 (Spacer AARC6)</i>	Lens was loose	Low	Send barrel back to shop

Project Workflow

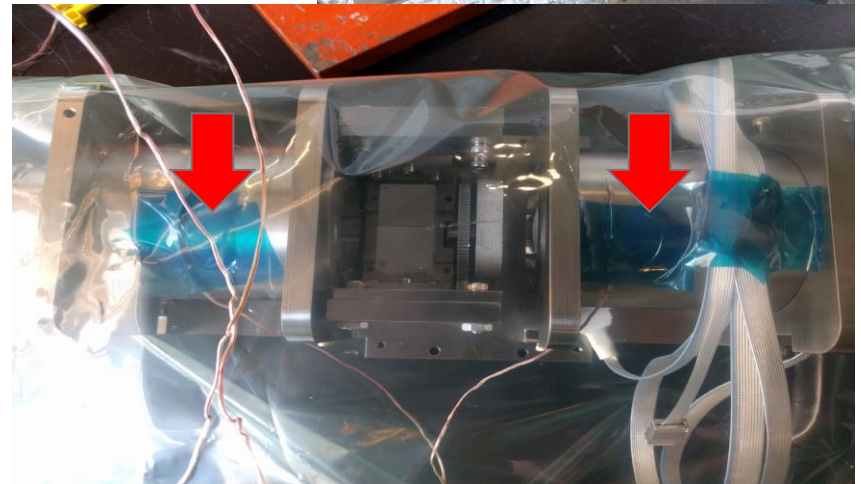


Thermal: Tasks

- Design test procedures
 - ✓ Research effects of condensation and ambient pressure
 - ✓ Finish procedures document
- Thermal testing
 - ▲ Preliminary tests
 - ▲ Full test
 - ✓ Post-test structural/optical verification

Thermal: Setup

- Equipment:
 - Instron 500 Series Environmental Chamber
 - Not under vacuum
 - Possibility of condensation
- Set up:
 - Vacuum bag
 - Tape seal
 - Nitrogen purge
 - Two thermocouples



Thermal: Test Procedure

Optical
Baseline
Test

Prelim
Test 1

Optical
Test

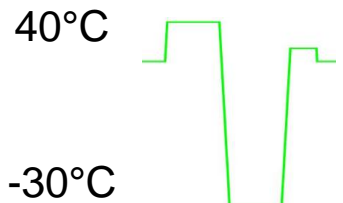
Prelim
Test 2

Optical
Test

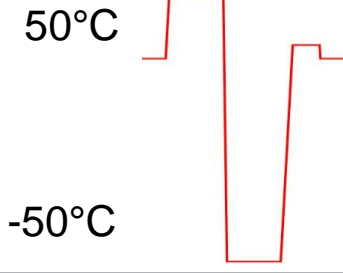
Full
Test

Optical
Test

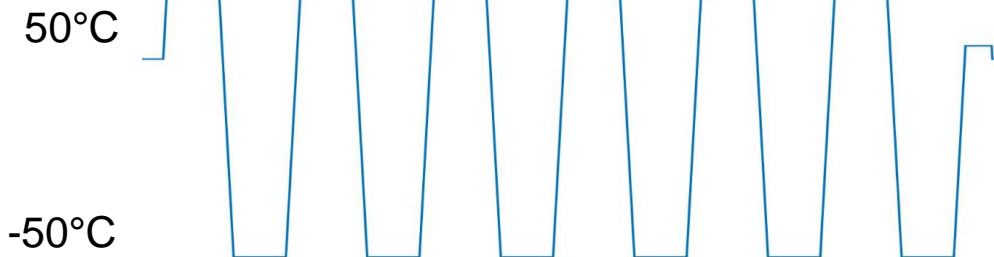
Prelim
Test 1



Prelim
Test 2

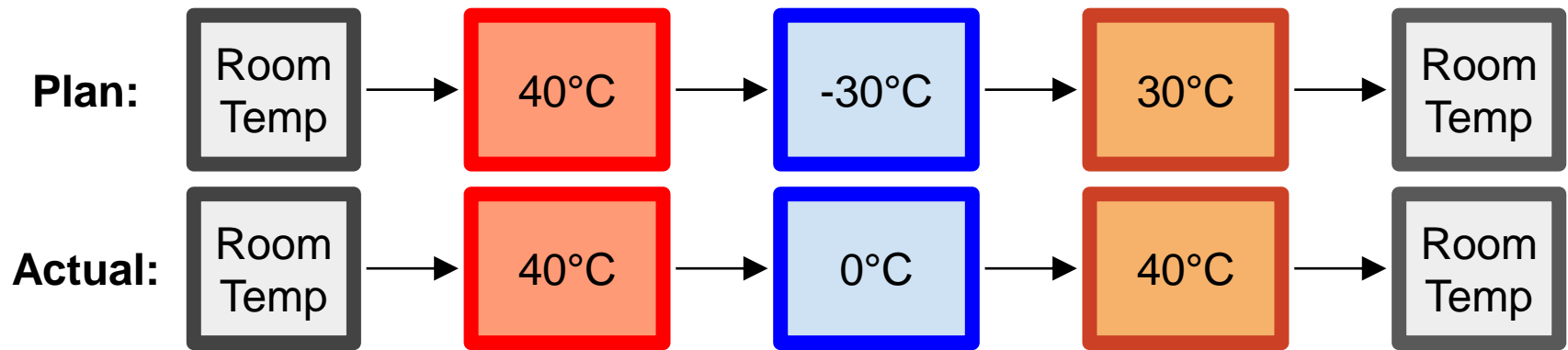


Full
Test



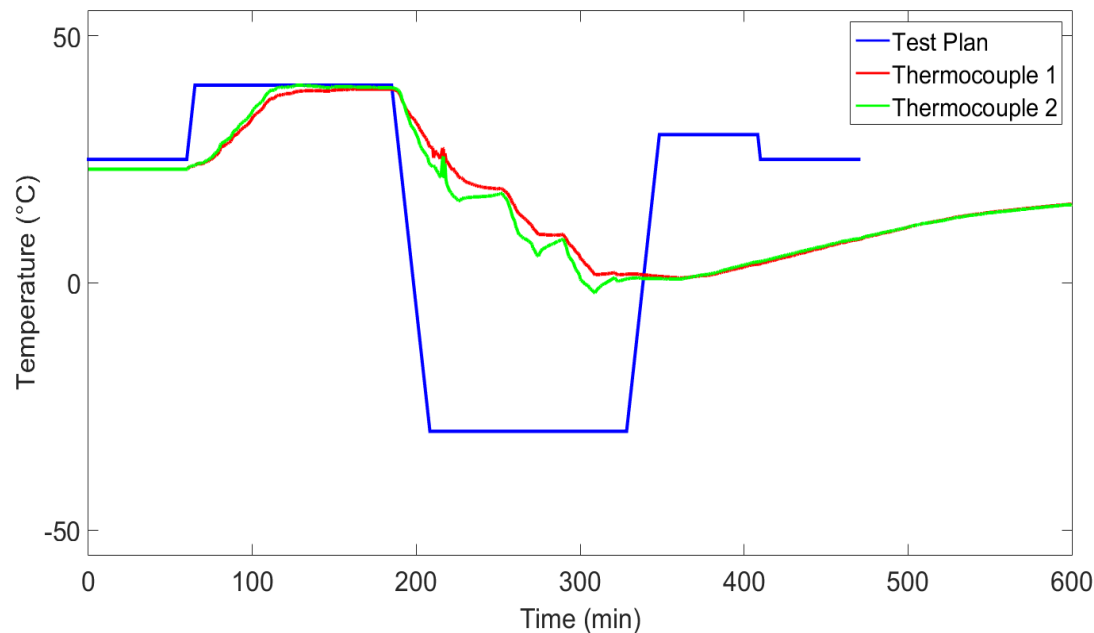
- Two low level preliminary tests
- 2 hour dwell time
- 3°C/min ramp rate
- Finish with bake at 30°C to eliminate condensation

Thermal: Test Procedure

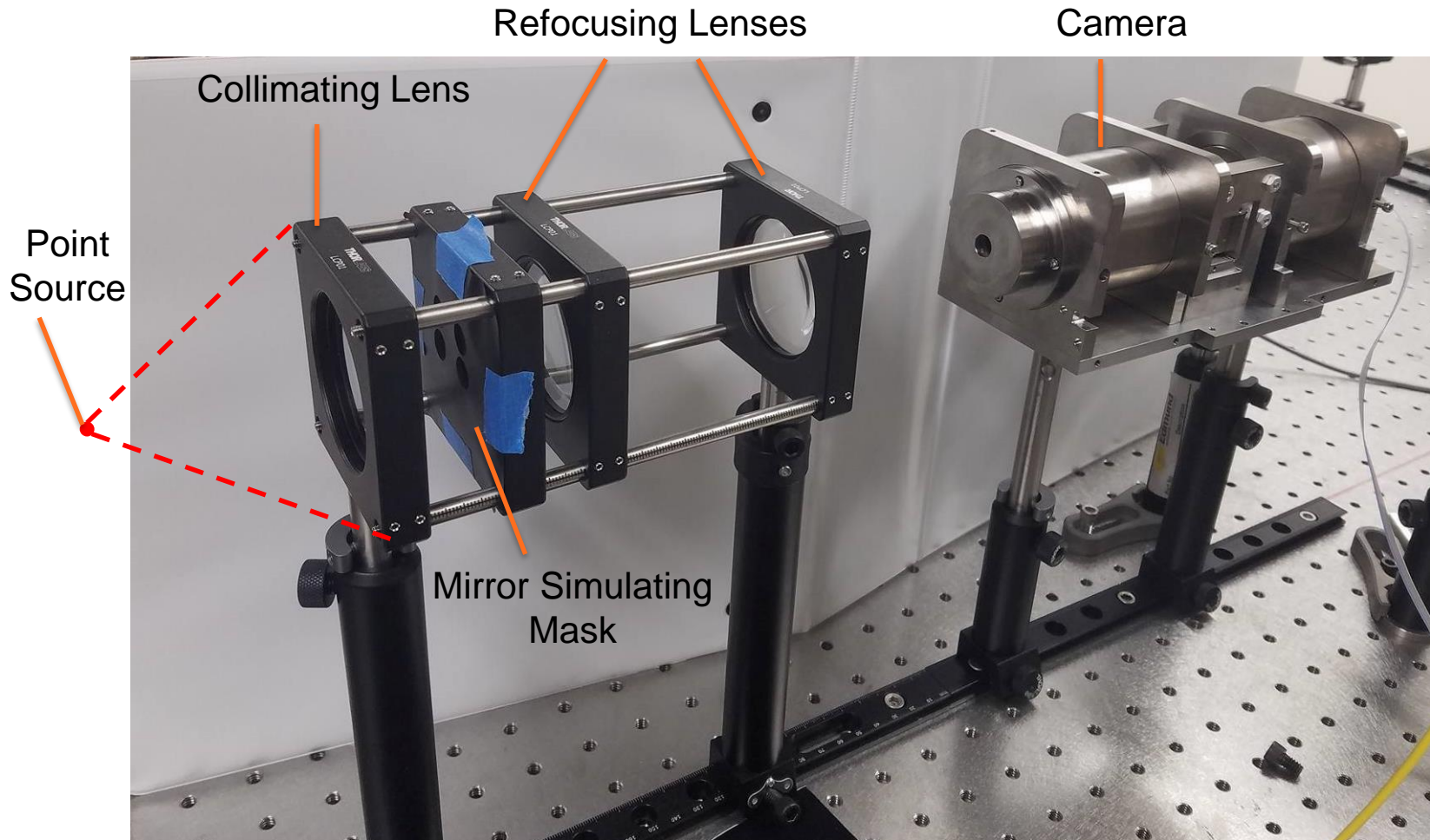


Plan vs Actual

- Thermal lag:
~ 0.15°C/min
1 hour dwell time
- Thermocouples show
5°C gradient across
camera
- Slow conducting
nitrogen in bag



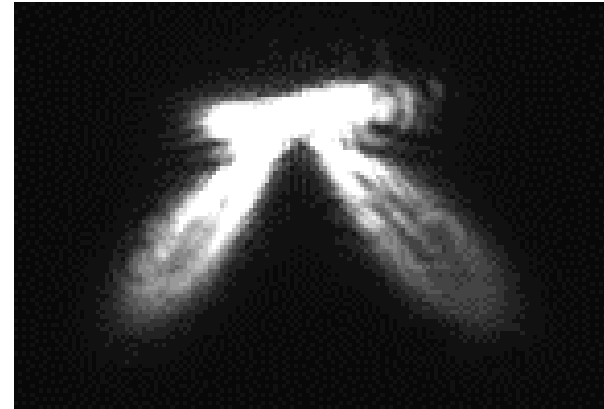
Thermal: Optical Test Setup



Thermal: Optical Test



Pre Thermal



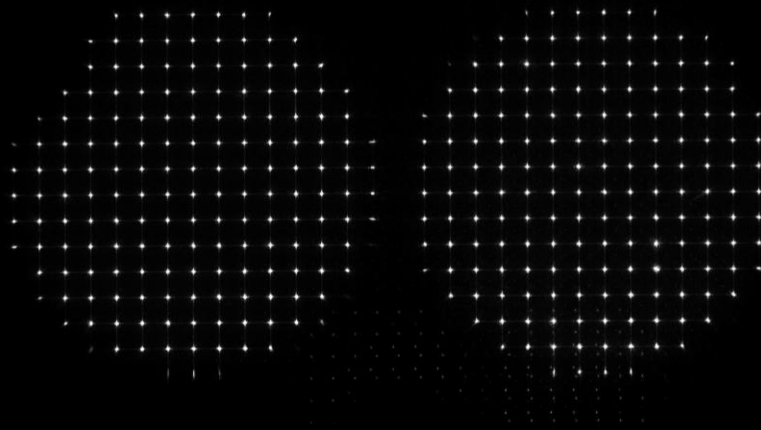
Post Thermal

Imaging Detector Spot Size Comparison

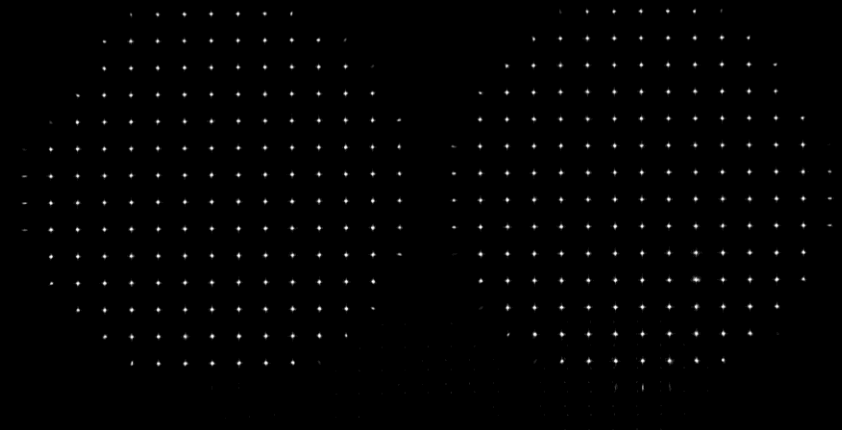
Simulated	Pre-thermal	Post-thermal
400 x 260 μm	$\sim 350 \times 230 \mu\text{m}$	$\sim 350 \times 230 \mu\text{m}$

Thermal: Optical Test

Pre Thermal



Post Thermal



SHWS Spot Number Comparison

	Predicted	Pre Thermal	Post Thermal
Mirror 1	~153	153	151
Mirror 2	~153	152	153

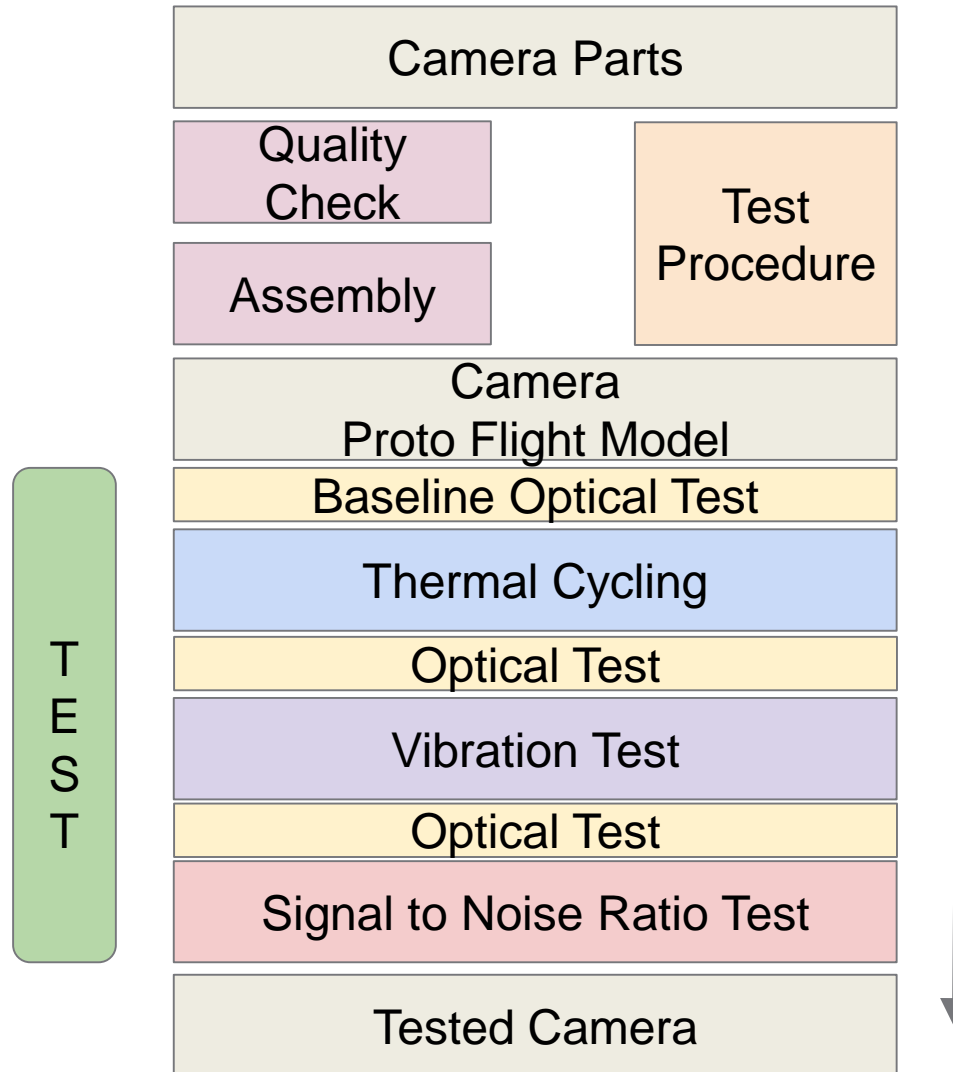
SHWS Spot Size Comparison

- Diffraction limited
= 4 pixels diameter
- Measured
= ~4-5 pixel diameter

Thermal: P/F Criteria

Criteria	Result
<ul style="list-style-type: none">• Heating/cooling rates	Out of Spec
<ul style="list-style-type: none">• No signs of condensation on interior of vacuum bag	Some condensation, no adverse effects noted
<ul style="list-style-type: none">• No obvious physical damage	Pass
<ul style="list-style-type: none">• No loose parts	Pass
<ul style="list-style-type: none">• Optical performance meets the requirements	Pass

Project Workflow



Vibration Testing: Tasks

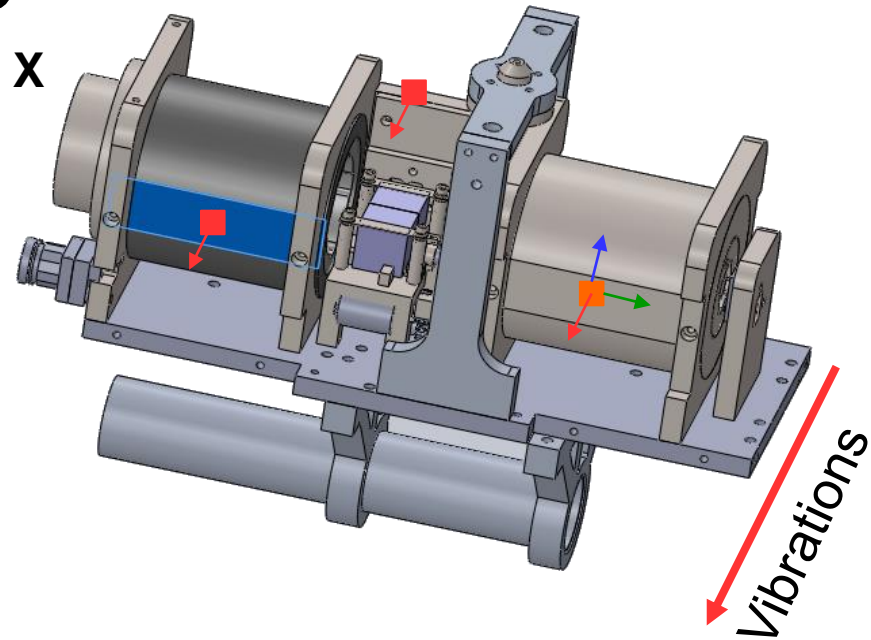
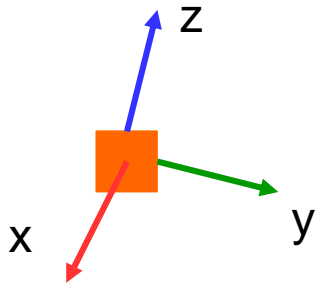
- Test preparation
 - ✓ Create procedures document
 - ✓ Manufacture camera mounts
- Vibration tests
 - ▲ Set up and run vibration test
 - ▲ Post-test optical verification



Vibration Testing: Instruments

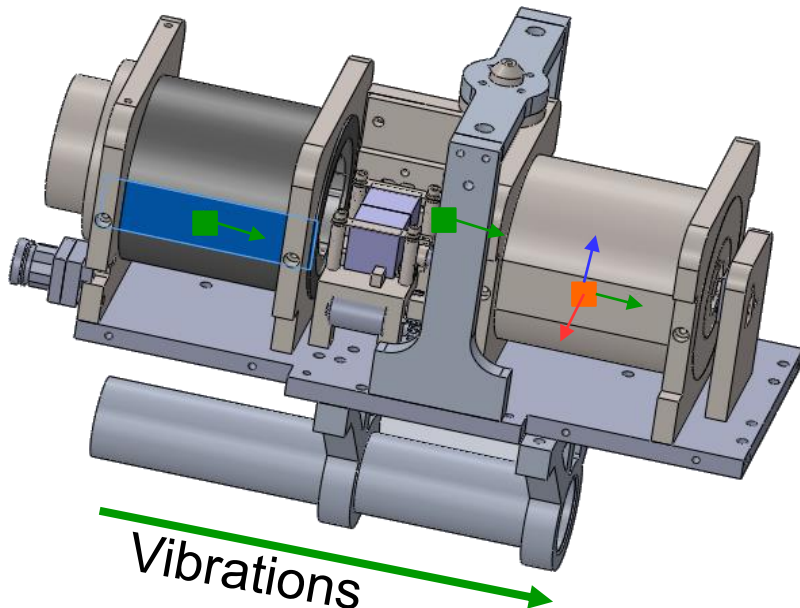
Vibration X to camera X

Lens barrel 1: triaxial
Lens barrel 2: uniaxial
SHWS: uniaxial
Interface plate: triaxial

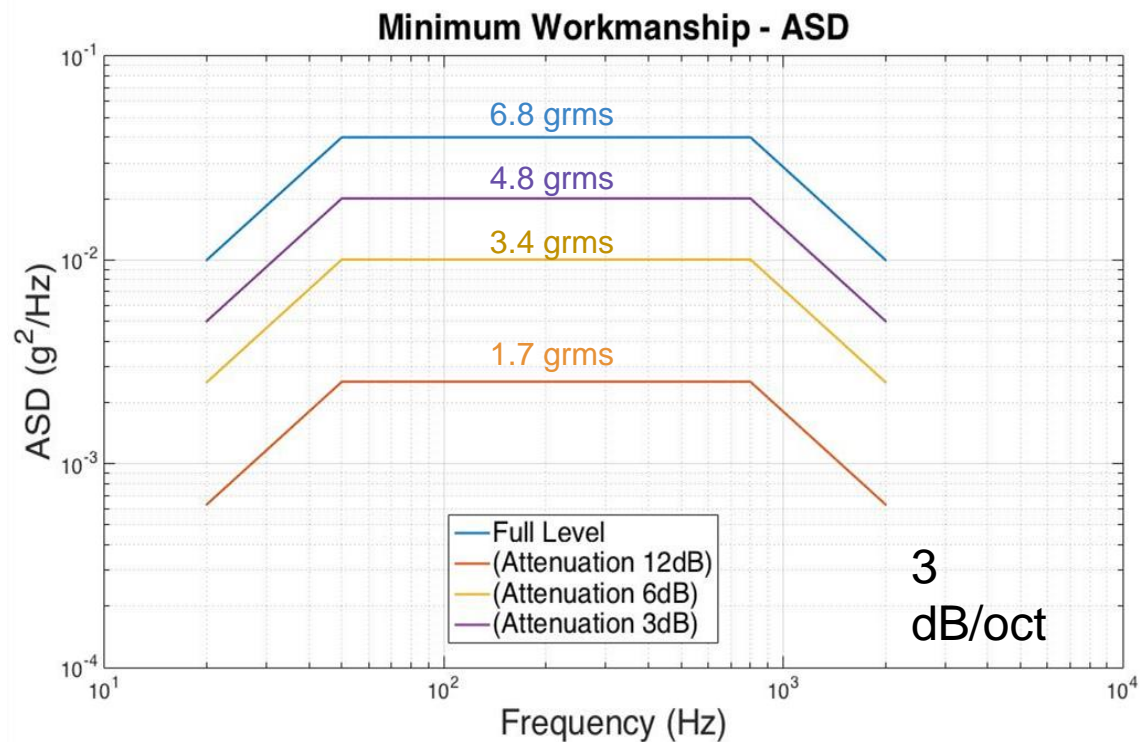
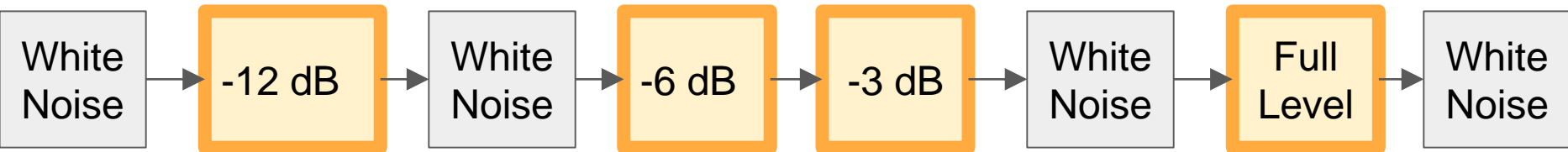


Vibration X to camera Y

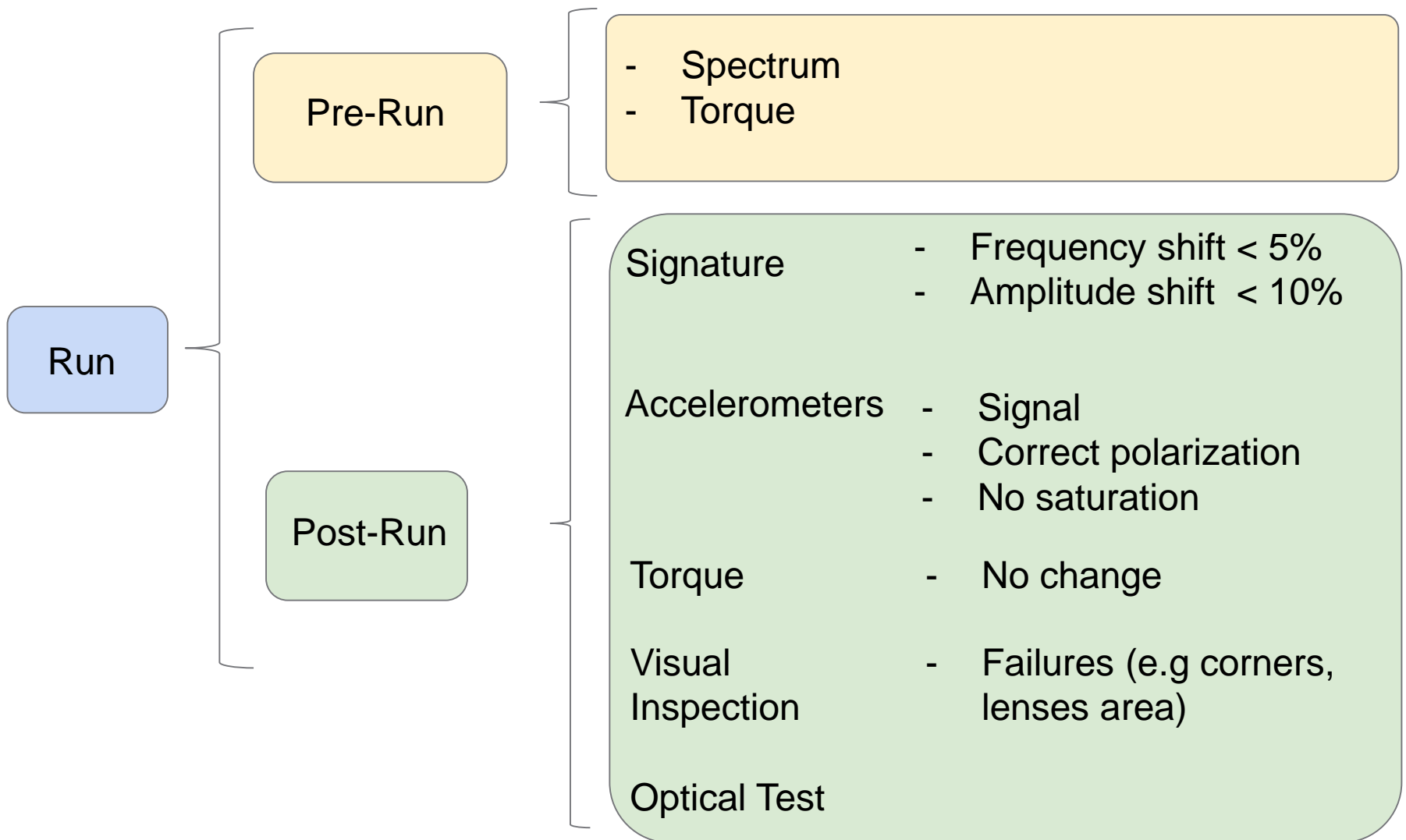
Lens barrel 1: triaxial
Lens barrel 2: uniaxial
Mask: uniaxial
Interface plate: triaxial



Vibration Testing: Test Sequence and Input Profiles



Vibration Testing: Checks

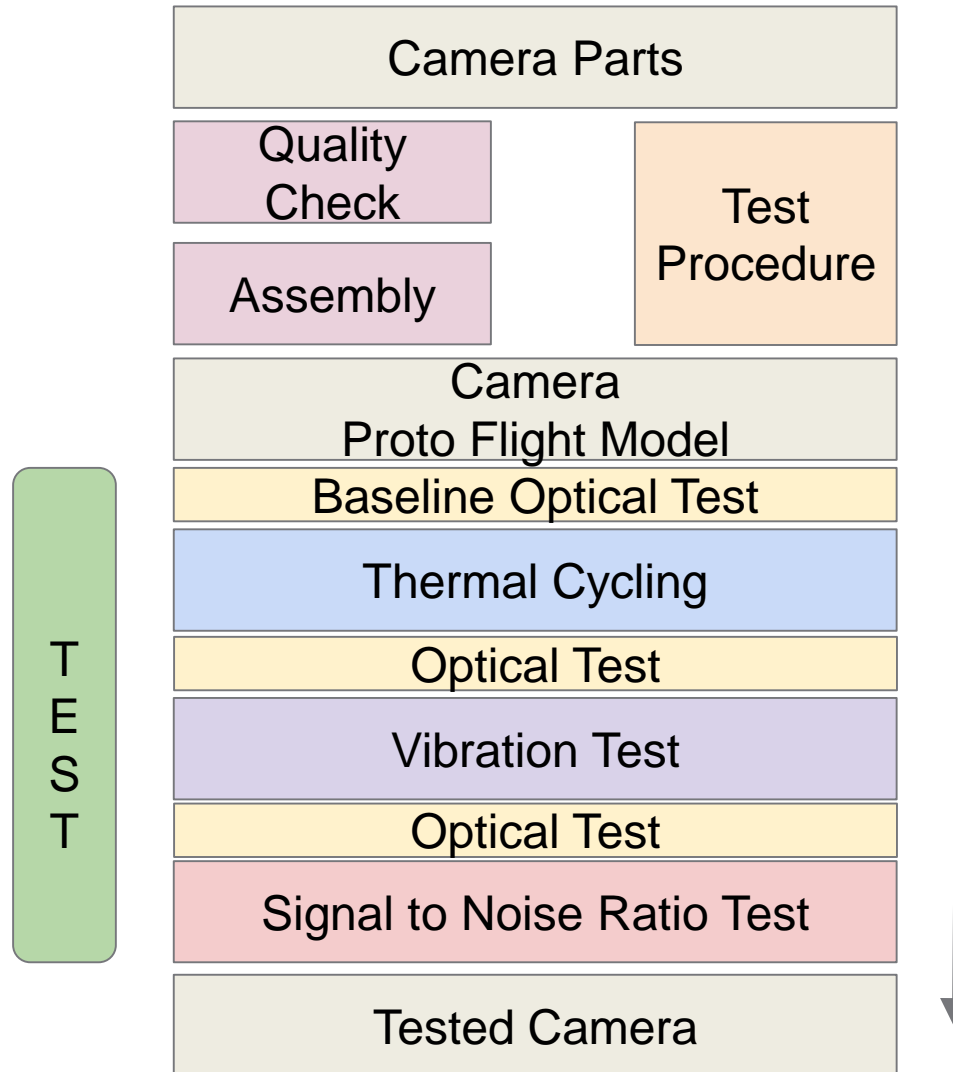


Vibration Test: Flight Deviations from test-as-you-fly

Item	Reason	Impact	Action
<i>Electronic boards not included</i>	PCB and other electronics not ready yet	Low	Dummy PCBs to be used
<i>Boundary conditions do not match flight</i>	One plane of contact during test	Medium	
<i>Vibration table has strong resonance at 1500 Hz</i>	Vibration table needs maintenance	High	Postpone test for maintenance
<i>Vibration table produces large Y- and Z-axis vibrations</i>	Vibration table needs maintenance	High	Postpone test for maintenance



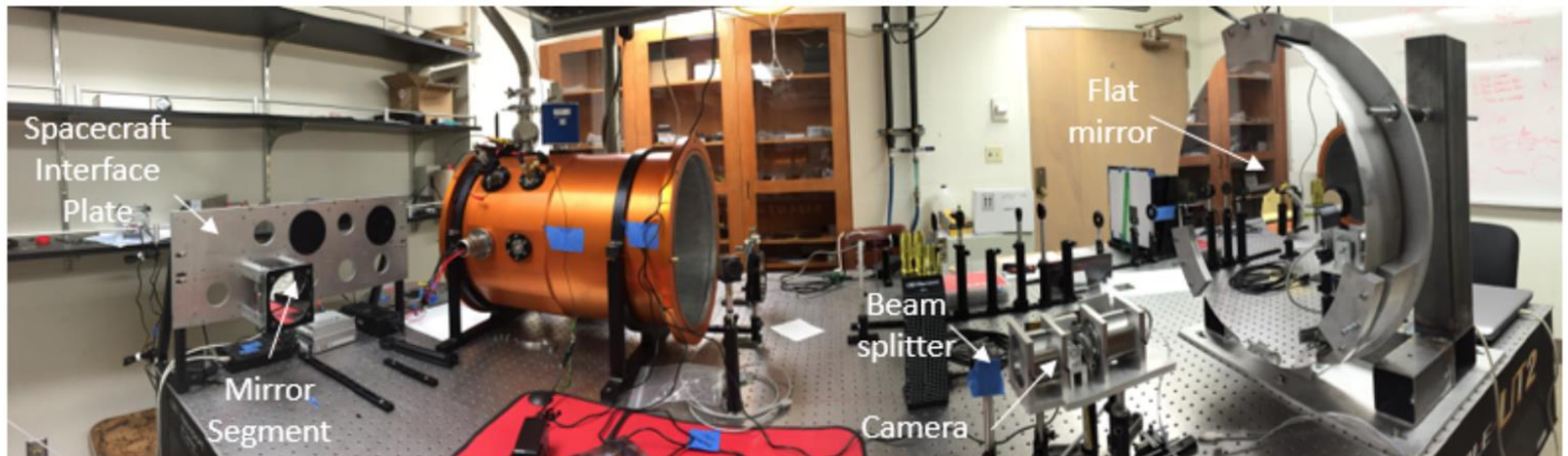
Project Workflow



Signal to Noise Ratio Test

Goal: Verify $\text{SNR} > 100$ for the camera

How? Use a calibrated photodiode to measure intensity of white light source and adjust until it matches our expected star



Signal to Noise Ratio: Setup

1 Align mirrors

2 Align photodiode at prime focus

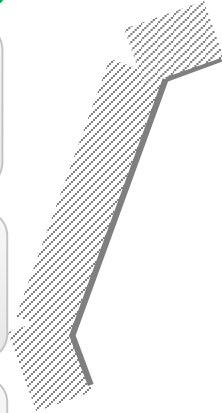
3 Red Laser → White Light Source

4 Vary intensity white light until desired voltage is reached

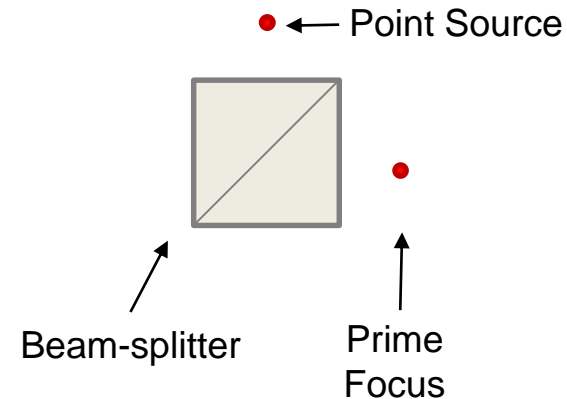
5 Photodiode → Camera

6 Take picture and calculate SNR

AAReST Rigid Mirror



Flat Mirror



Signal to Noise Ratio: Setup

1 Align mirrors

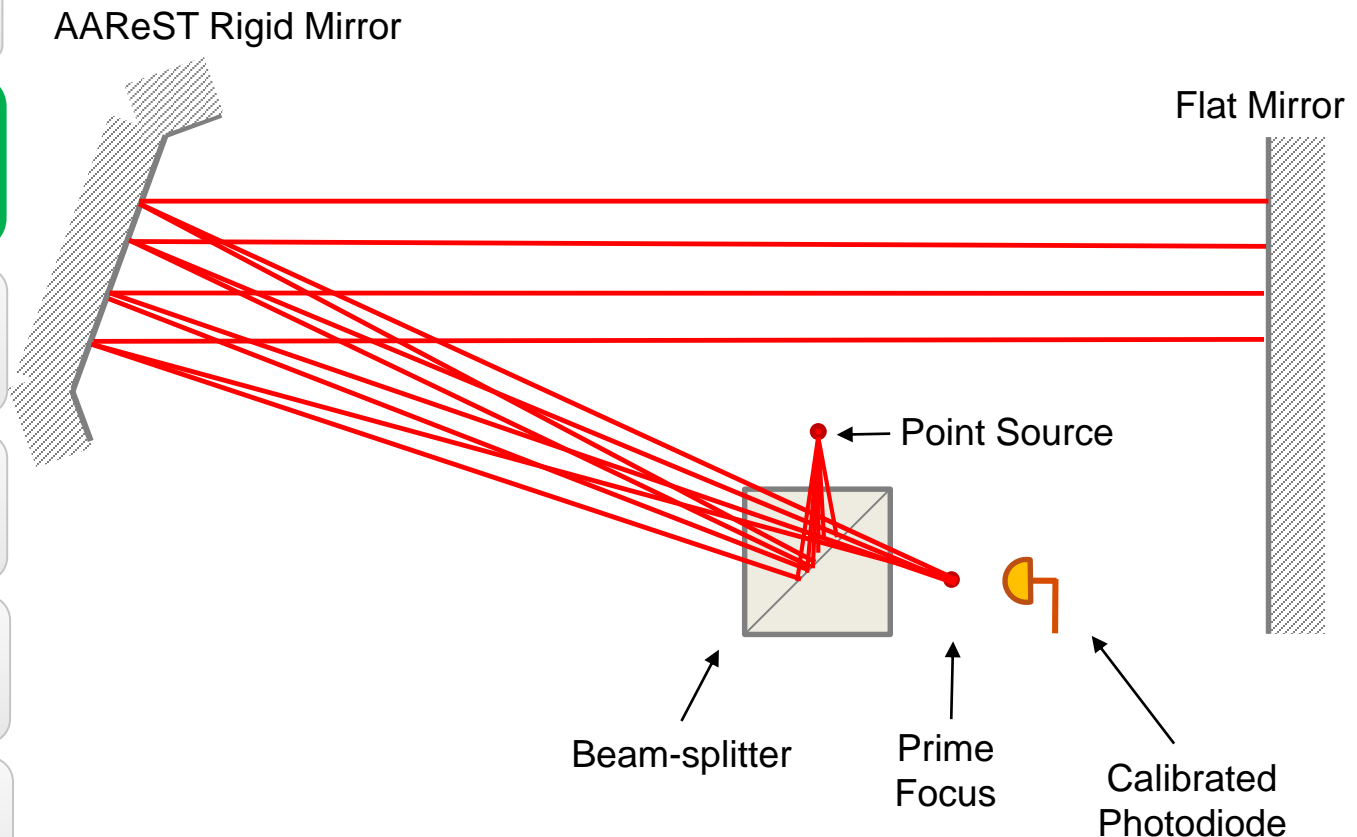
2 Align photodiode at prime focus

3 Red Laser → White Light Source

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Signal to Noise Ratio: Setup

1 Align mirrors

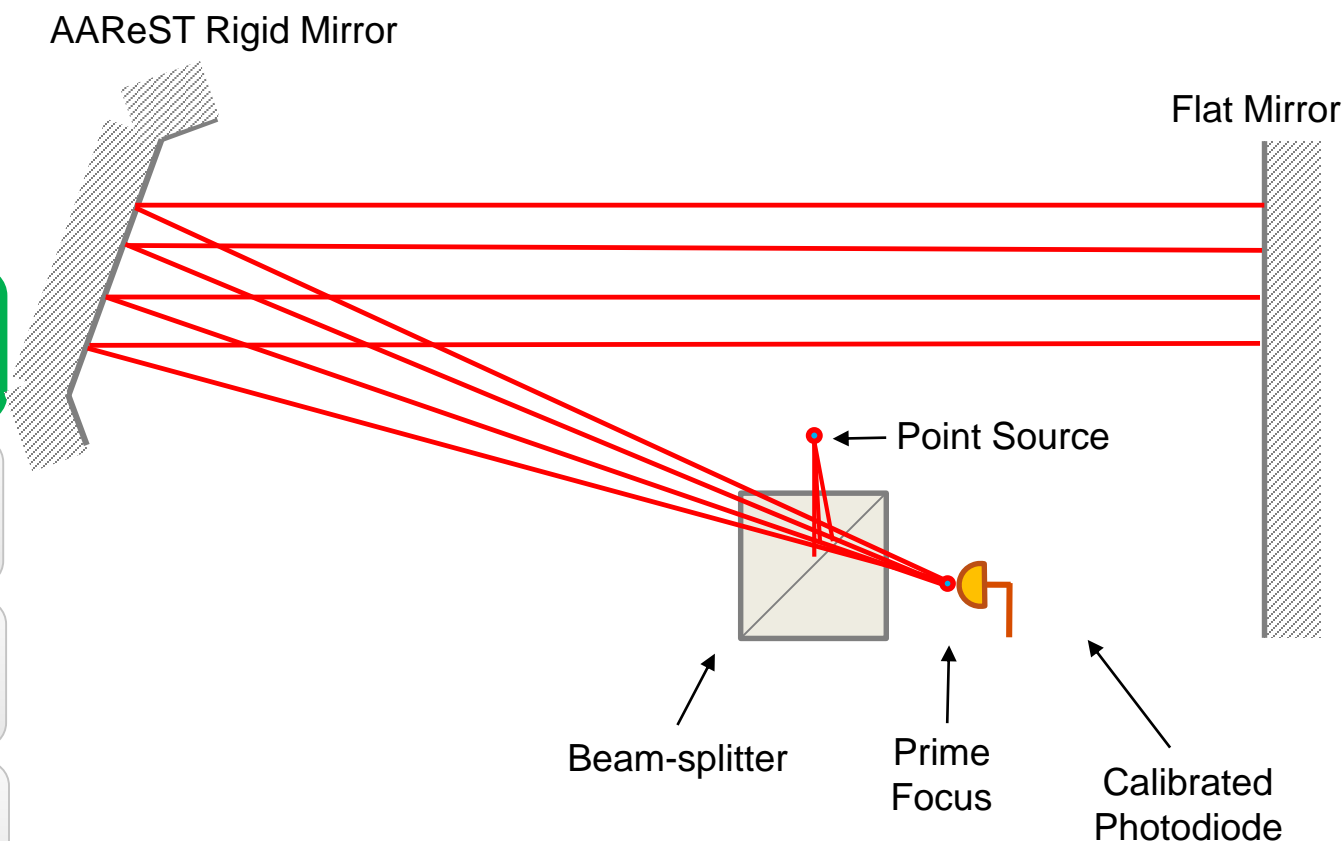
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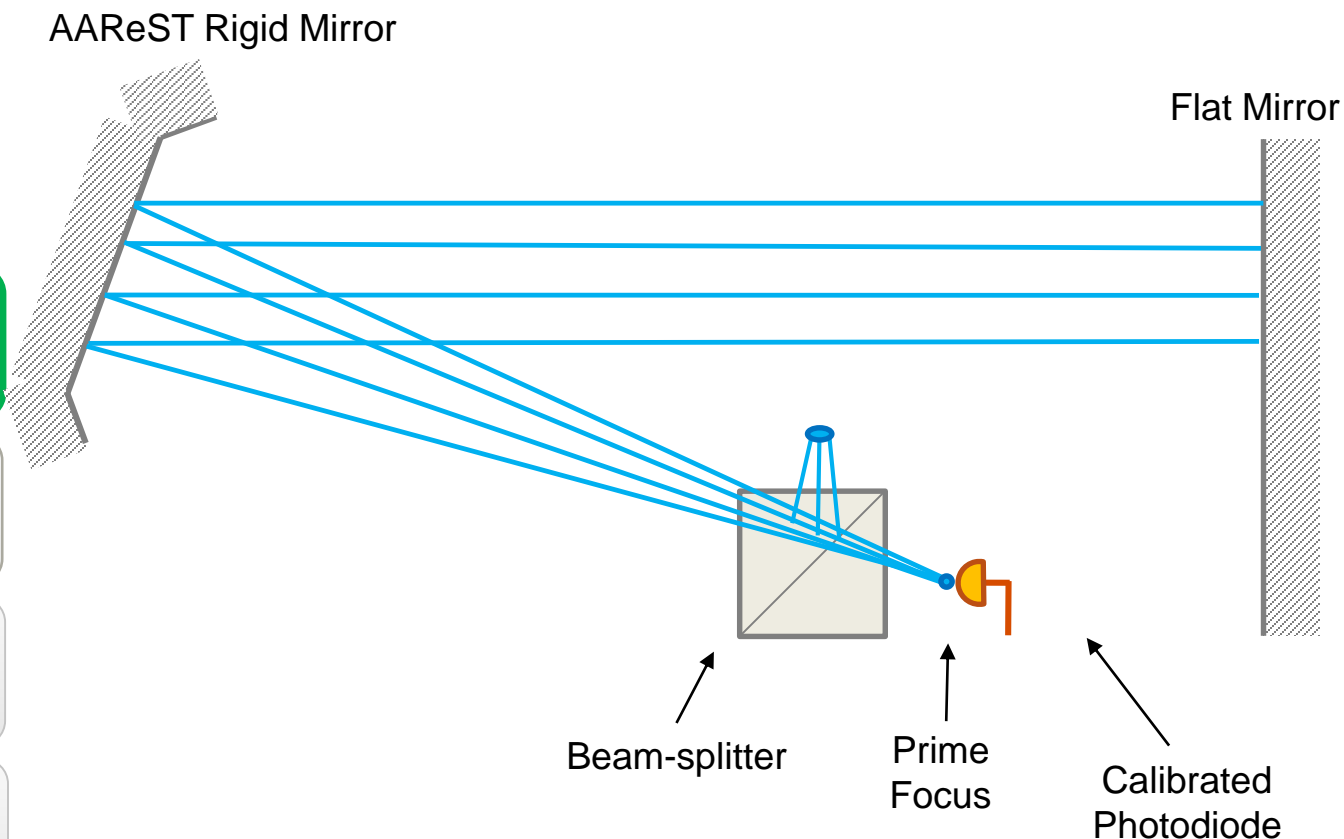
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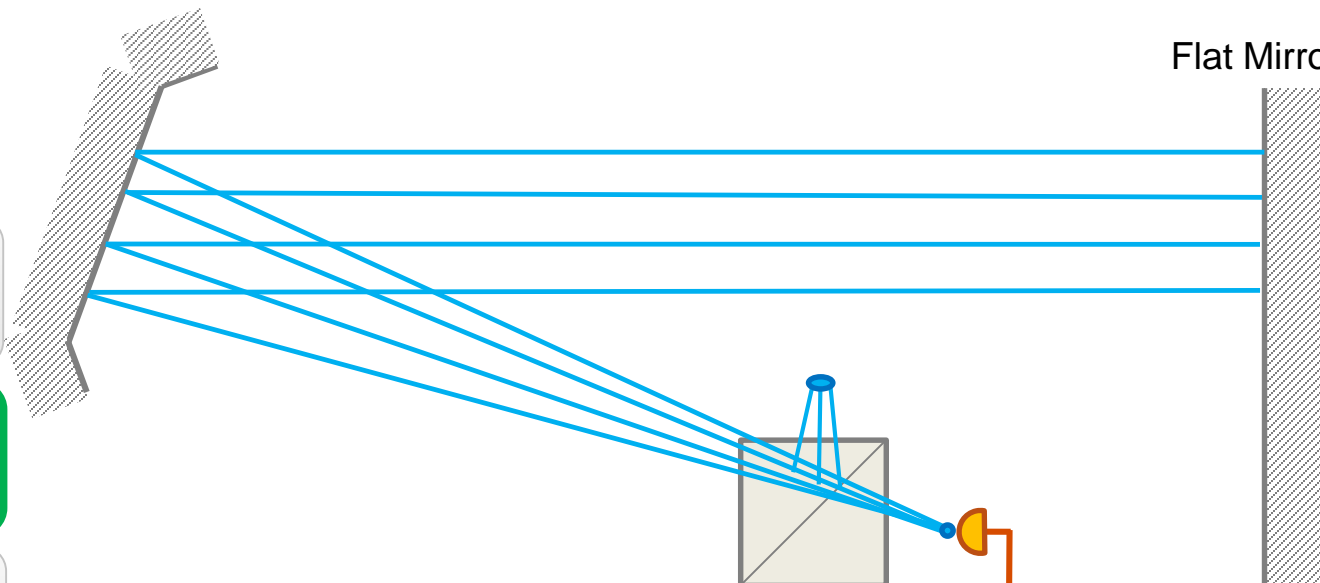
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AAReST Rigid Mirror

Flat Mirror



Desired Voltage

2.6 mV

Filtered Voltage

1.8 mV

Signal to Noise Ratio: Setup

1 Align mirrors

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3 Red Laser → White Light Source

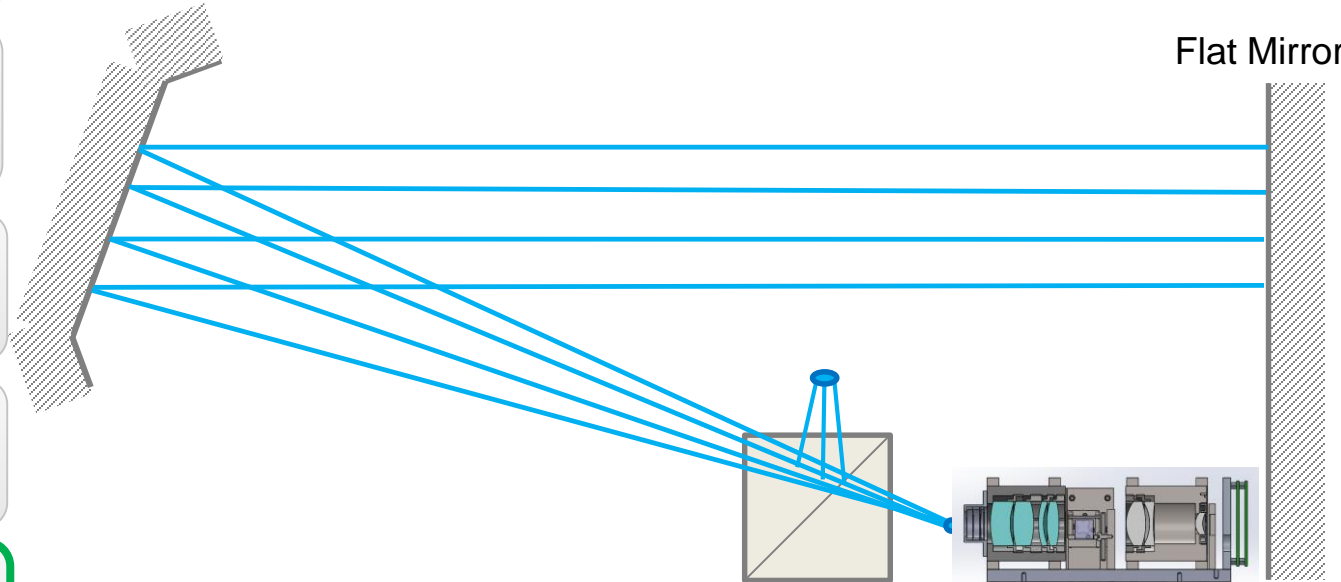
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AAReST Rigid Mirror

Flat Mirror



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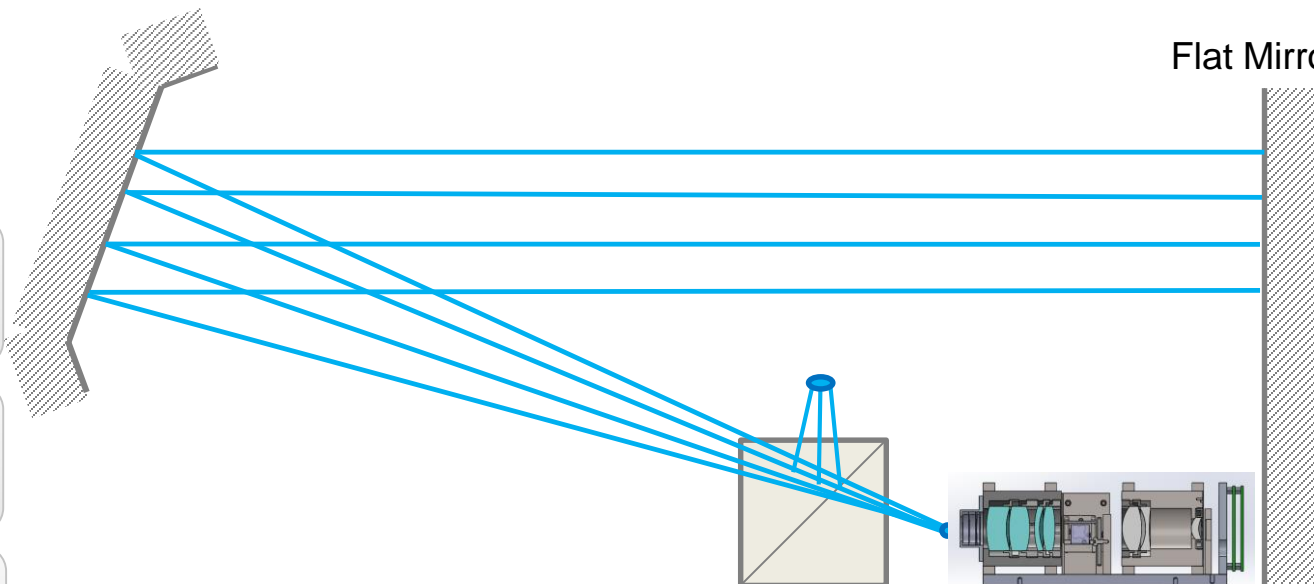
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5 Photodiode → Camera

6 Take picture and calculate SNR

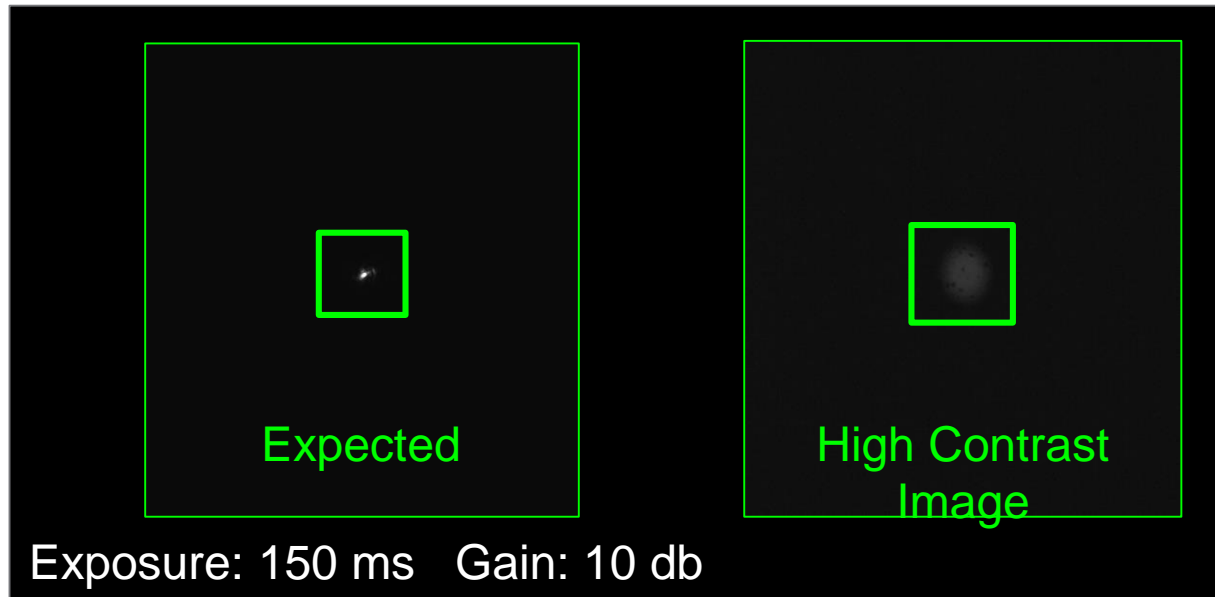
AAReST Rigid Mirror

Flat Mirror



Picture and SNR Calculation!

SNR Calculation



$$\text{SNR} = \frac{\text{mean}(\text{Signal} - \text{Background})}{\text{RMS}(\text{Background})}$$

Criteria	Result
SNR > 100	51.89

Test deviations:

- Light not point source
 - Mask blocks larger beams from image detector
- Incorrect intensity: light source too dim

Summary: Status of Tests

Test	Comments	Status
Optical Baseline	New camera images consistent with previous	Pass
Thermal	Thermal lag	Need to improve setup
Mechanical	Reliable step sequence	Missing bearing
Vibration	No vibration modes of table in test frequency range	Vibration table out of service
SNR	Point light source intensity	Inadequate optical fiber

	Pass
	In-Progress

	Postponed
	Fail

Summary: Future Work

- ☐ Thermal testing w/ new setup
- ☐ Vibration testing w/ fixed table
- ☐ SNR measurement w/ correct light intensity
- ☐ Integrate electronics
- ☐ Integrate light shielding
- ☐ Finalize external interfaces
- ☐ Integration to satellite

Thank you!

Questions?

Outline

2:00 pm: Introduction & Welcome

2:15 pm: Camera

2:45 pm: Boom

3:15 pm: Mirror Boxes

3:45 pm: On-board Software

4:15 pm: Electronics

Boom Subsystem Validation Team

Fabien Royer

Federico Presutti

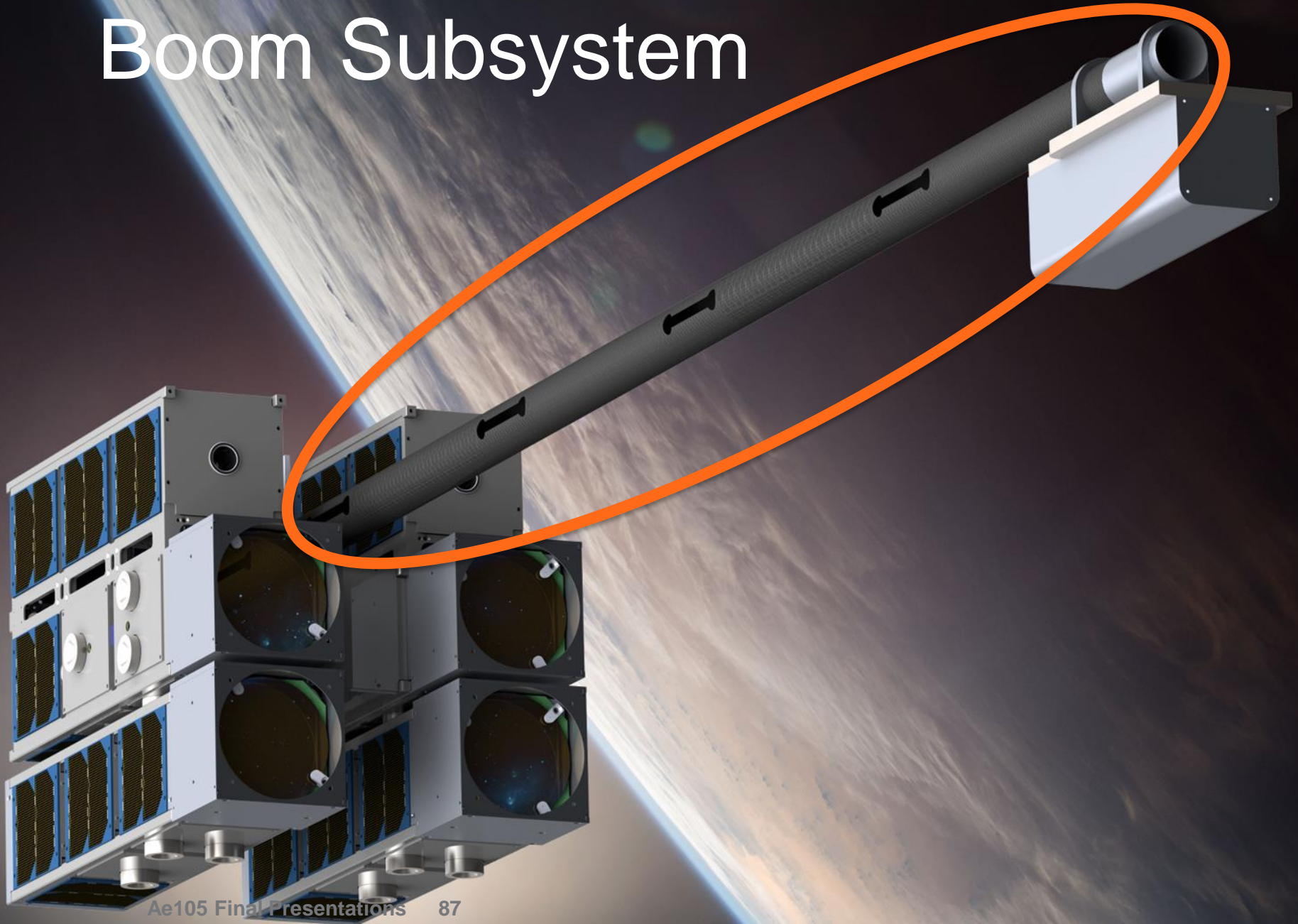
Joaquin Garcia-Suarez

Thomas Peterson

Mentor:

Christophe Leclerc

Boom Subsystem



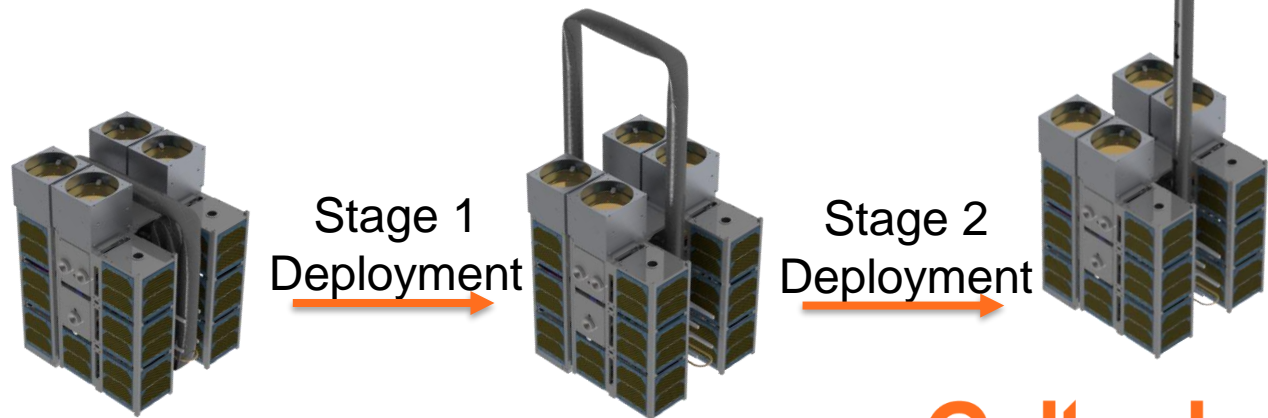
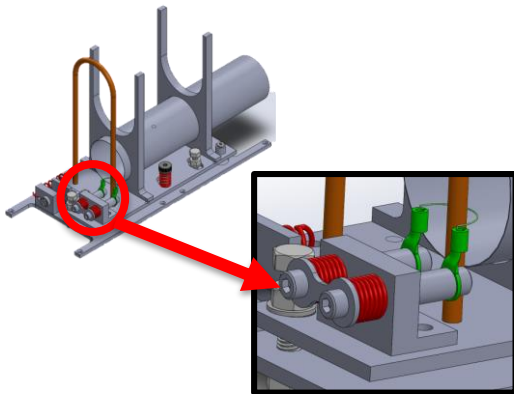
Boom Subsystem Overview

Introduction

- The hinged composite boom is responsible for bearing and deploying the camera
- Newest boom designed last year; some features to be retested

Team Responsibilities:

- Validate structural integrity and proper deployment of boom subsystem
- Ensure repeatability of boom alignment for optical applications
- Define structural details of boom connection to CoreSat



Tasks Overview

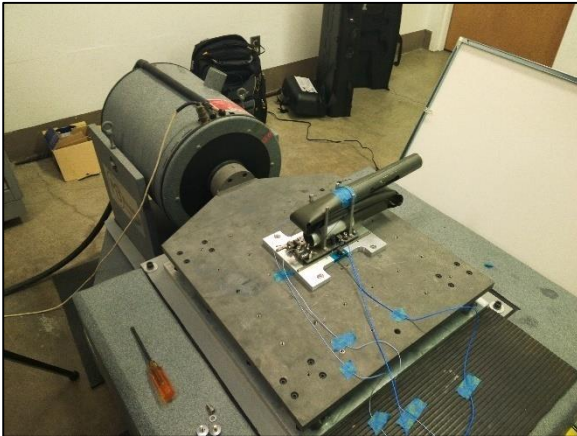
Boom-mount
connection design



Stage 2 Deployment
Testing



Vibration Testing

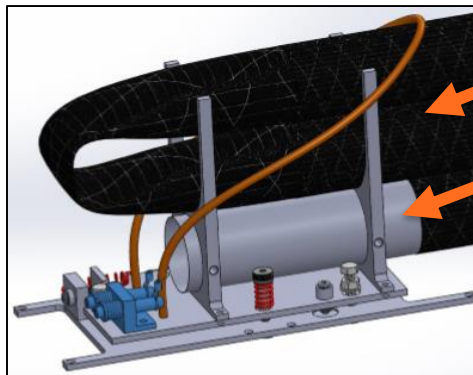


Accuracy Testing



Boom-Mount Interface Design

Objective: design the final connection to survive LEO conditions



Composite Boom

Aluminum Mandrel

Aluminum CTE

21.8 ppm/°C

Boom CTE

Axial

~1.0 ppm/°C

Circum.

21 ppm/°C

Deal with **CTE mismatch**

- Stresses arise at the interface due to different deformations of the materials
- Operation thermal conditions: **+60°C to -60°C**

Our choice:

LOCTITE EA 9394 AERO
Epoxy Paste Adhesive
(KNOWN AS Hysol EA 9394)

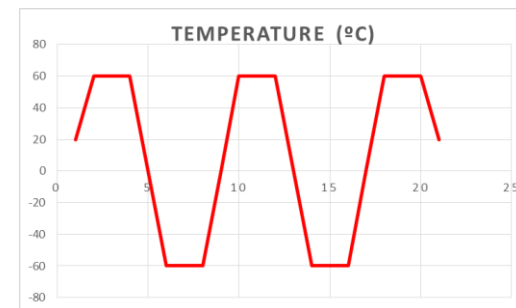
- Appropriate thermal and mechanical properties and low outgassing

Design of Boom-Mount Fixation



Testing structural integrity of the connection:

- Prepared connection sample for test (following bonding procedure)
- Used environmental chamber to test thermal cycle
- Mechanical load applied



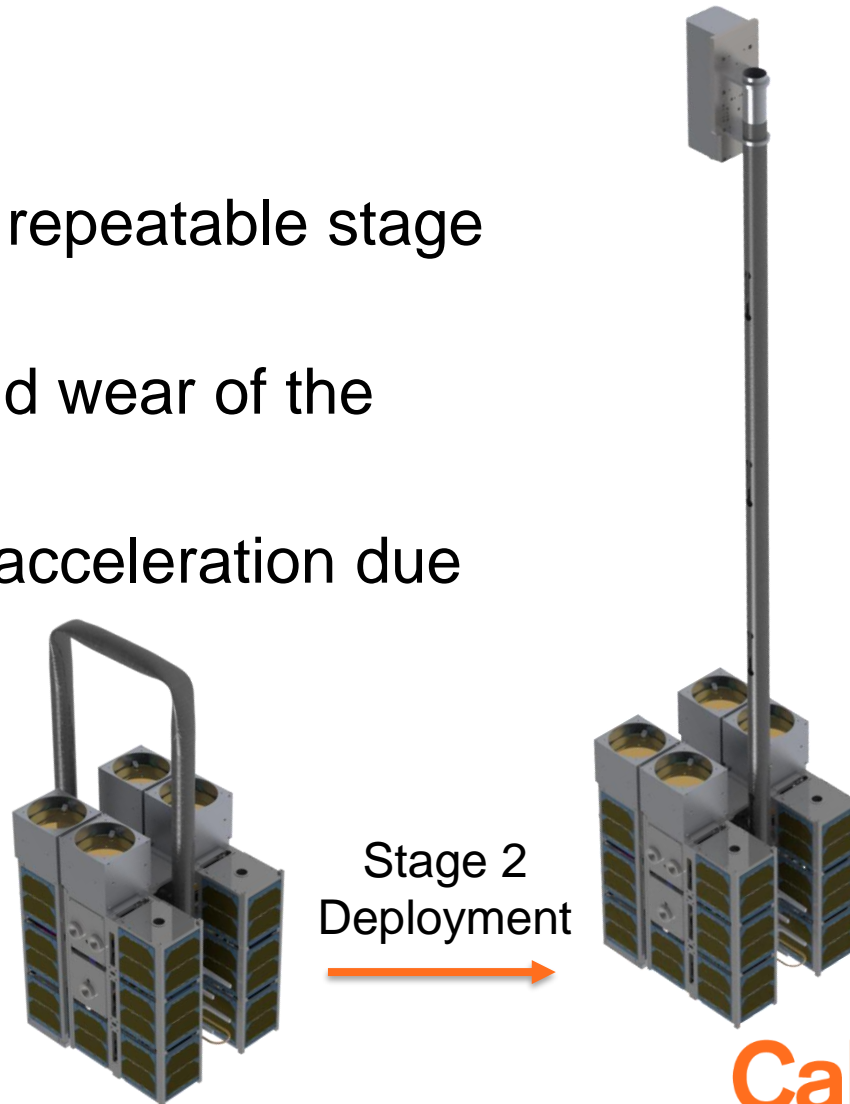
Conclusions:

- Expected mechanical and thermal loads do not trigger failure

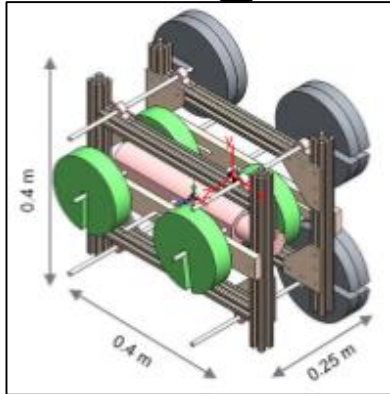
Stage 2 Deployment Test

Objectives:

- Ensure a reliable and repeatable stage 2 deployment
- Track deterioration and wear of the composite boom
- Determine maximum acceleration due to deployment

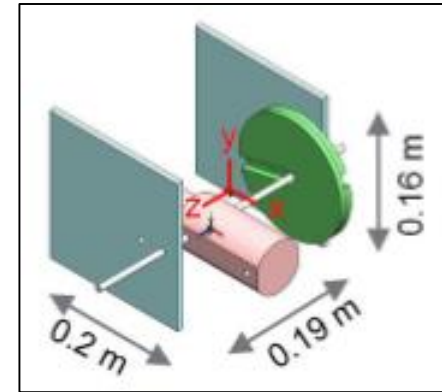


Stage 2 Deployment Testing



CoreSat mass model

Part	Mass (kg)	
	2014	2016
Camera	2.98	3.43
CoreSat	27.74	27.74



Camera mass model



Stage 2 Deployment Results

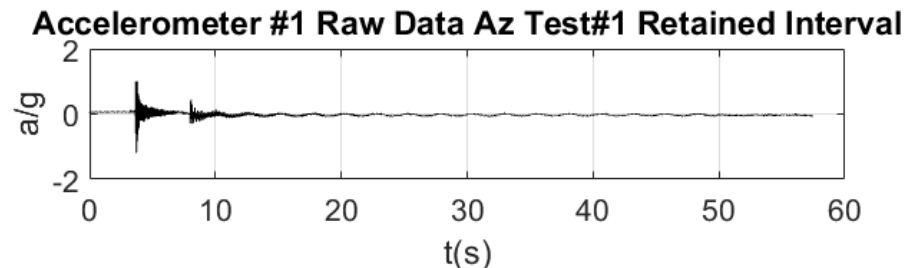
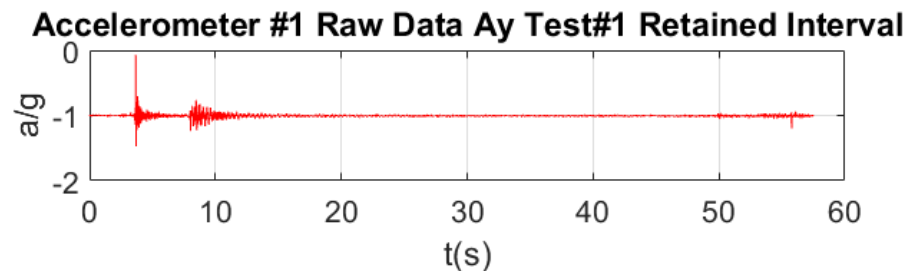
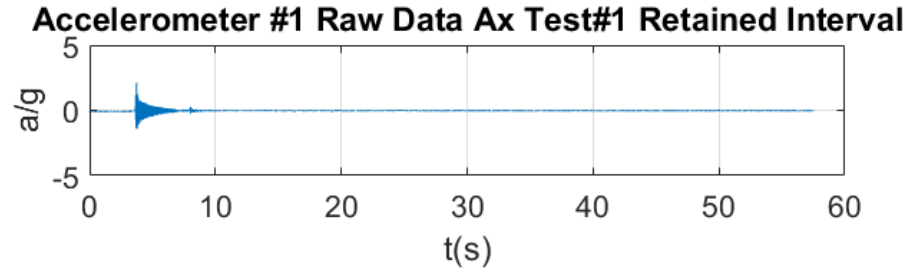
- Boom deterioration:
 - Tests will be performed preflight; need to be sure tests will not compromise boom and deployment
 - First sign of wear of the composite matrix after the third test (3 cycles folding/deployment)
 - By seventh test, no cracks had formed on the boom, but more visible signs of wear on the matrix
- Repetitive deployment pattern:
 - In agreement with previous tests (2014)
 - In disagreement with computer simulations; needs updating



Boom hinge by
final test

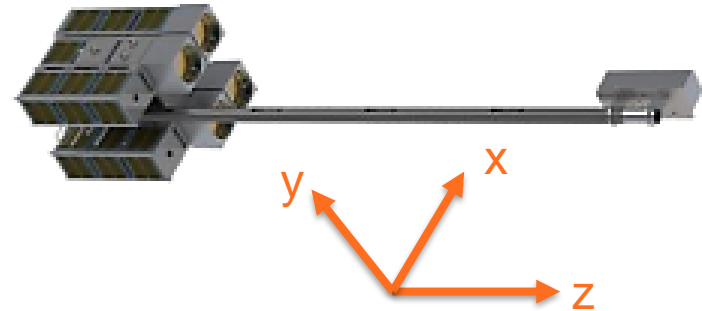
Stage 2 Deployment Results

- Maximum accelerations on camera:
 - About **1g**
 - Loads due to deployment are expected to be smaller than those during to launch
 - Ex: at least 2g axial and lateral shocks expected from Delta IV rocket launch



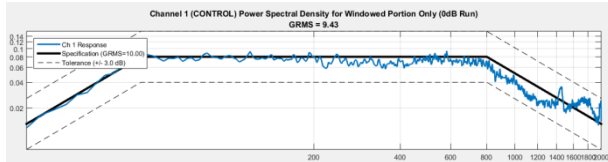
Boom Natural Frequencies

- Discrete Fourier Transform of acceleration profile was used to analyze boom natural frequencies
- Need to avoid disturbances from satellite components inducing vibrations at natural frequencies (e.g. reaction wheel)



Observed Frequency (Hz)	Inferred Corresponding Mode	Approximate Decay Time (s)
3	Torsion around boom axis + bending in xz plane	5
11	Torsion higher mode	5
13	Bending in xz plane	20

Vibration Testing Objectives



Survive launch vibration phase

Acceptance level test
(10 gRMS, 30g peak)

Random vibration
Input direction:

- X-axis
- Y-axis

Accurate position of the camera

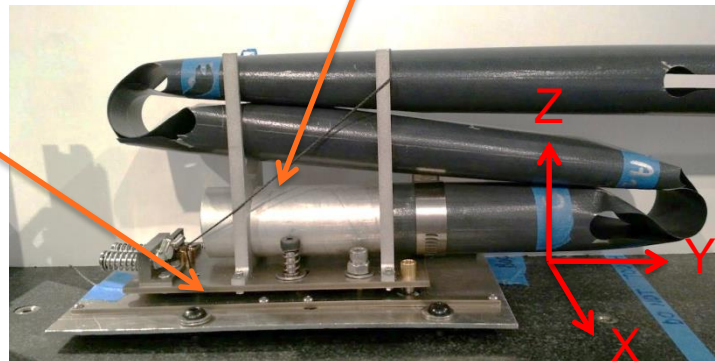
Vibration induced displacements of the adjustable components

Separation device functional

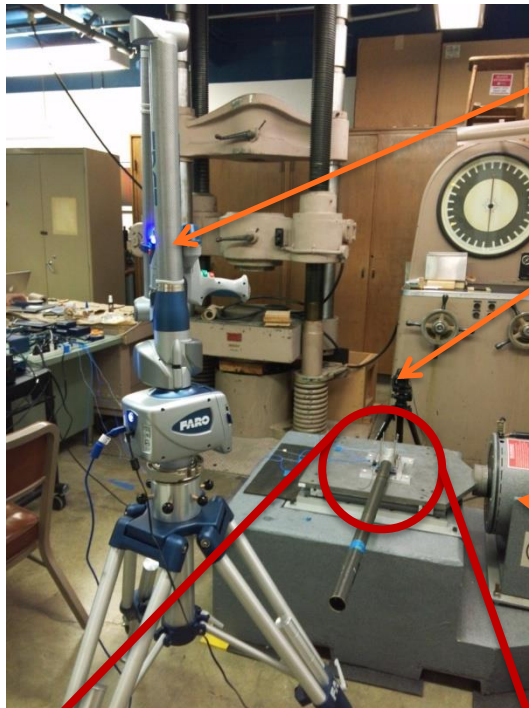
Evolution of the Vectran cable tension

System undamaged

Structural integrity and mechanical response



Testing setup and interface

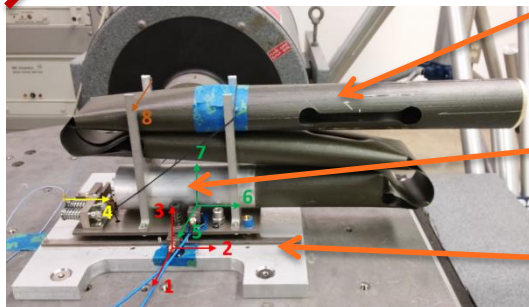


FARO Arm

Camera

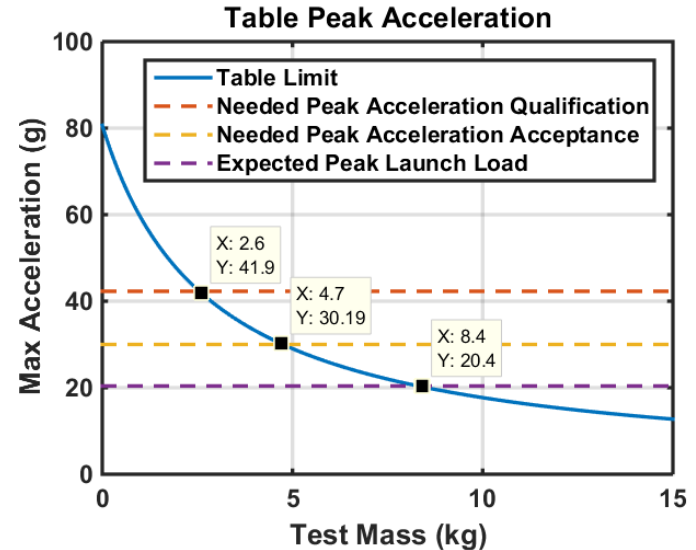
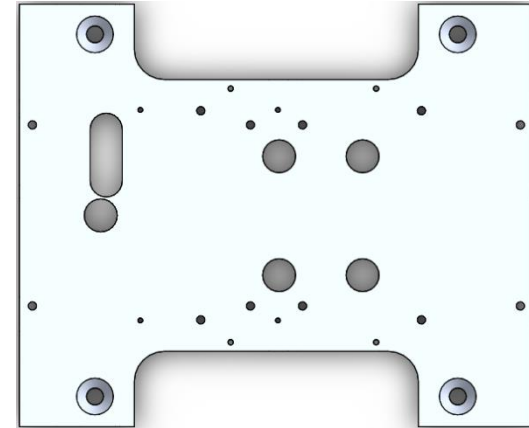
Shaker

Boom



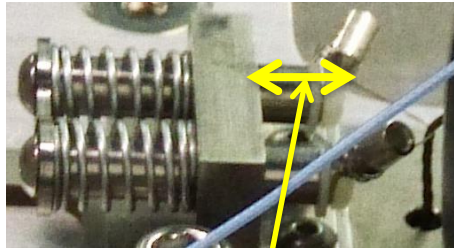
Kinematic mount

Interface

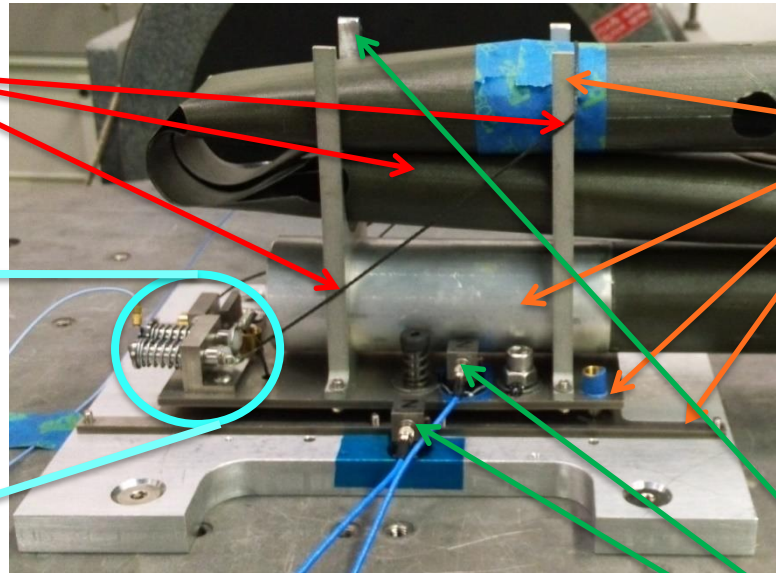


Results: observations

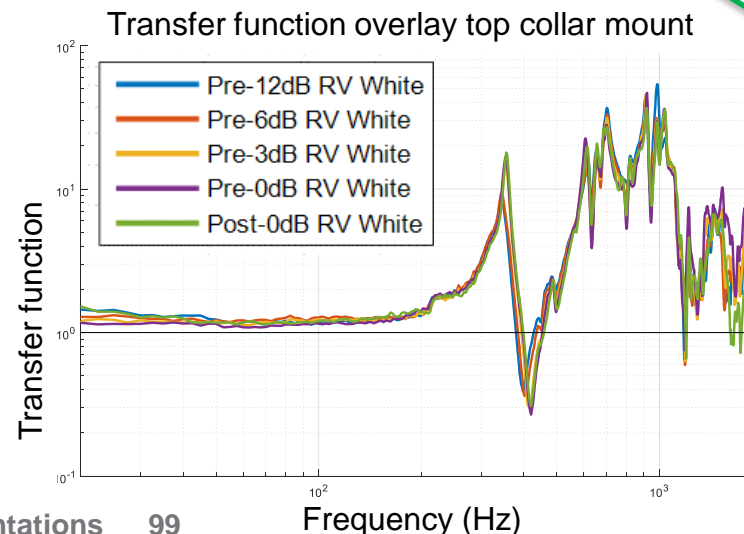
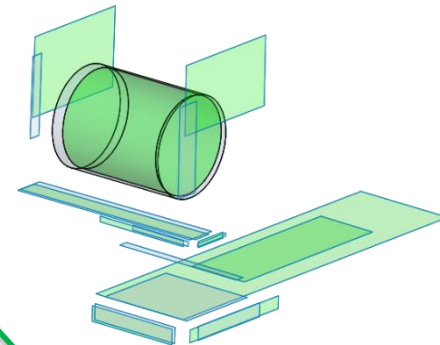
Thorough visual inspection



Stroke of the separation device:
Tension of the Vectran cable



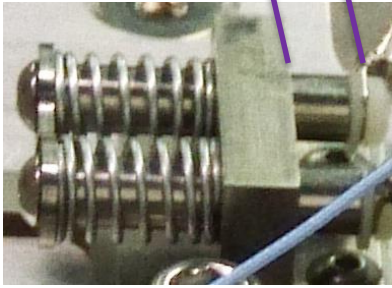
Faro arm measurements:
relative displacements



Accelerometers:
Structural integrity

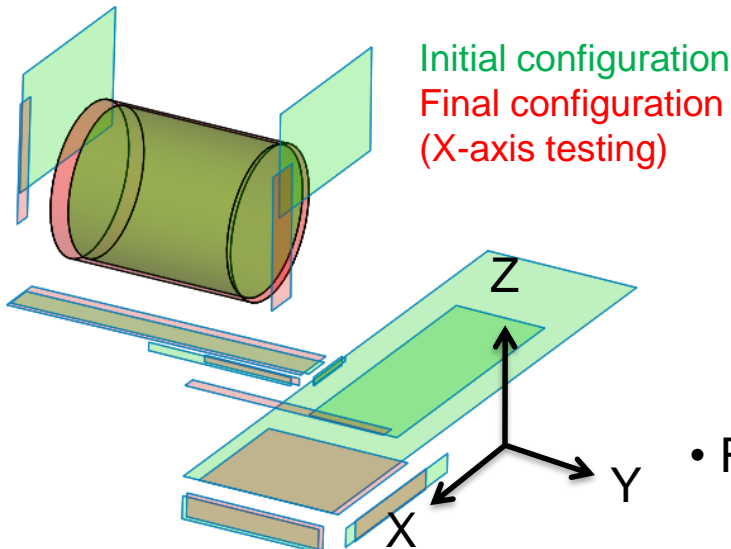
Quantitative results

Stroke



Stroke X-axis test (mm)	Stroke Y-axis test (mm)	Relative loss of stroke X-axis test (%)	Relative loss of stroke Y-axis test (%)
5.58	7.08	16.9	6.2

- Requirement: final stroke > 3mm



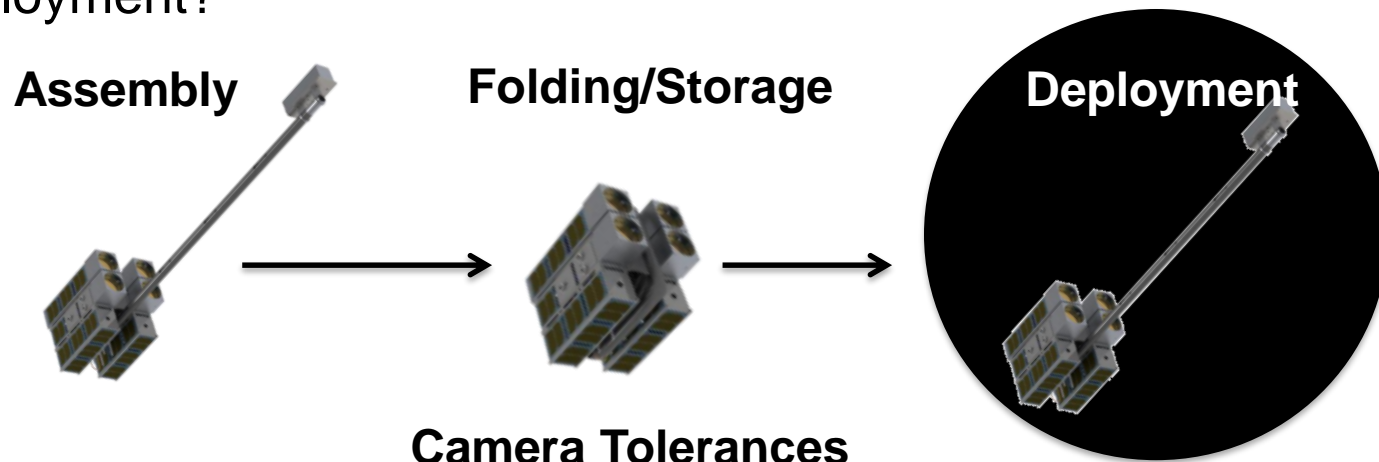
Displacements Y-axis testing	
Mandrel axis linear displacement (mm)	dx: 0.032, dz:0.009 (dy: 0.052)
Mandrel axis angular displacement (°)	0.037
Camera displacement (modulus) (mm)	0.9 mm

- Requirement: lateral displacement < ± 3 mm



Accuracy Testing Criteria

- Verify the **repeatability** of camera alignment, after the boom is folded and stored for some time
- If the boom is aligned during assembly, will it still be aligned after deployment?



Camera Tolerances

Requirements	Value
Focal length	$1163 \pm 1 \text{ mm}$
Maximum admissible lateral offset	$\pm 3 \text{ mm}$
Maximum admissible angular offset	$\pm 1^\circ$

Accuracy Testing Methods

- **Challenge:** Boom is 1.5 meters long and flexible; we need to measure position with millimeter accuracy and without touching it.
- **Solution:** FARO Arm measuring device with optical scanning tool.

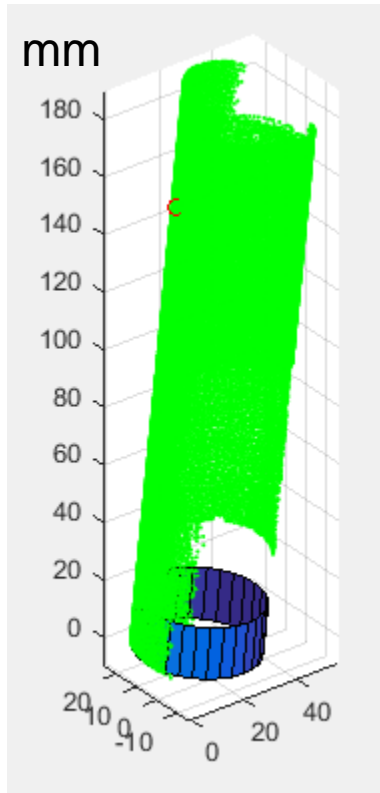


Simulated storing the boom for seven months in folded configuration by aging process – 2000 seconds at 96 C°

Procedure:

1. Scan the camera end of the boom
2. Scan the coreset end of the boom
3. Fit each point cloud to a cylinder in matlab
4. Determine the position of the camera end relative to the coreset end
5. See how the position changes after folding and aging

Accuracy Testing Results



Cylinder Fit to
Point Cloud

	Length Change	Lateral Change	Angular Change
Requirement	$\pm 1\text{ mm}$	$\pm 3\text{ mm}$	$\pm 1^\circ$
Folding	0.1 mm	0.5 mm	0.1°
Aging	3.0 mm	1.0 mm	0.2°

- Axial displacement after aging is larger than expected – 3 mm elongation
- Could be a problem with our measurement system or with the boom itself
- Needs further investigation

Conclusions

- Found a reliable method of performing the boom-mount connections
- Changes in boom do not affect maximum acceleration experienced by boom during stage 2 deployment
- Repeatable pattern of natural frequencies observed in stage 2 deployment
- Kinematic mount validated under vibration environment
- Validated the accuracy of the boom position after folding and storage

Future work

- Analysis of the vibration modes and comparison with the simulations
- Stage 1 and stage 2 deployment tests with aged booms
- Repeat the Stage 2 deployment computer simulation adding constraints to match experimental results
- Error quantification for the vibration test results
- Vibration test of the full system (full boom in launch configuration)
- Investigate large axial displacement of the boom after aging

Thanks for your attention
Any questions?

Outline

2:00 pm: Introduction & Welcome

2:15 pm: Camera

2:45 pm: Boom

3:15 pm: Mirror Boxes

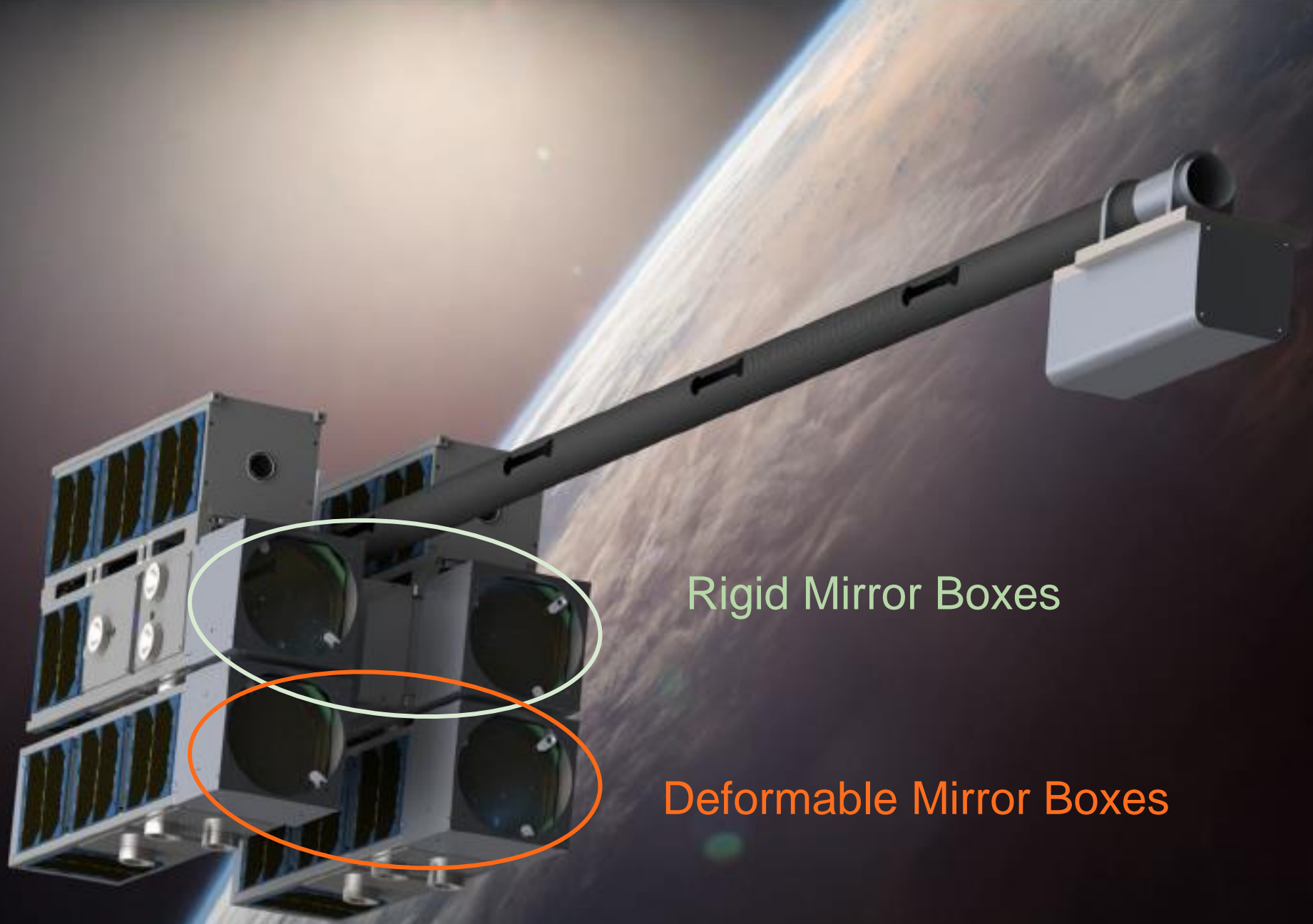
3:45 pm: On-board Software

4:15 pm: Electronics

Mirror Box

Jake Larson, Sheila Murthy, Catherine
Pavlov, Tyler Okamoto, Anand Kumar

Mentor: Serena Ferraro



Rigid Mirror Boxes

Deformable Mirror Boxes

Project Overview

Key Purposes of Mirror Boxes:

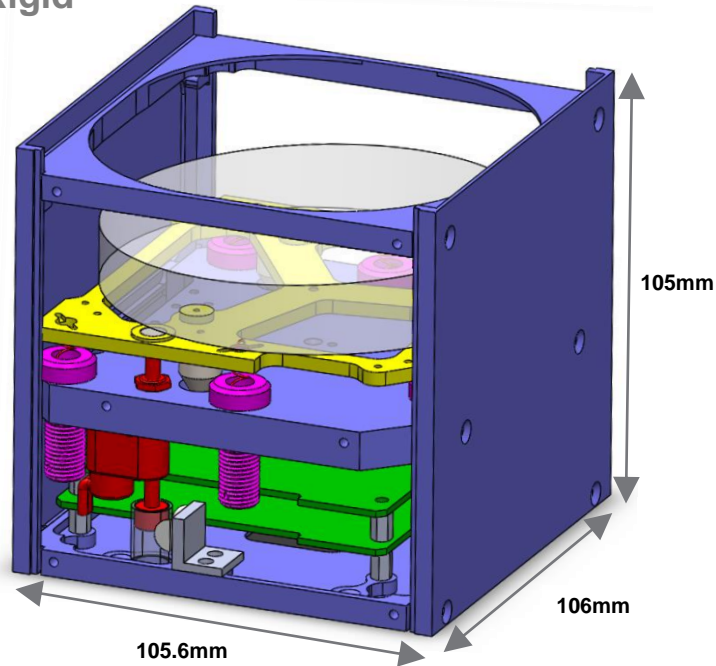
- House mirrors and electronics
- Restrain mirrors during launch
- Provide rigid body rotation and axial motion of the mirrors

Mirror Boxes Objectives:

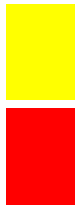
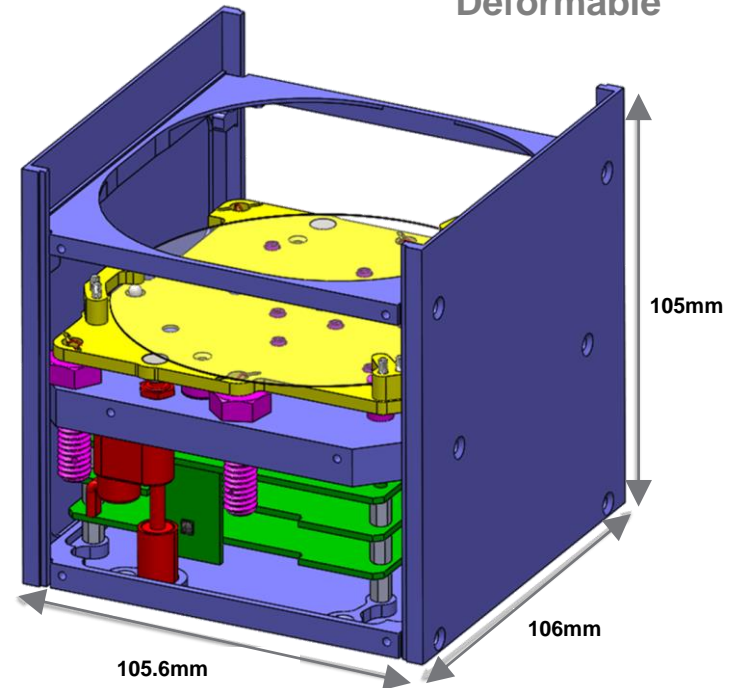
- Develop assembly methods and documentation
- Design and manufacture Mirror Box parts
- Test epoxy and picomotor limit switches
- Perform vibration testing with proto-flight components
- Future work: Perform optical and mechanical testing on both boxes

Mirror Boxes Overview

Rigid



Deformable



Mirrors & Mounts

Picomotors



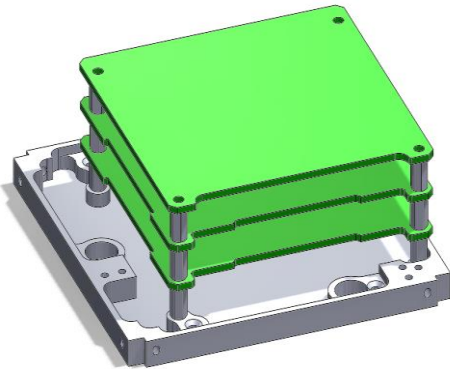
Launch Restraint System

Electronics

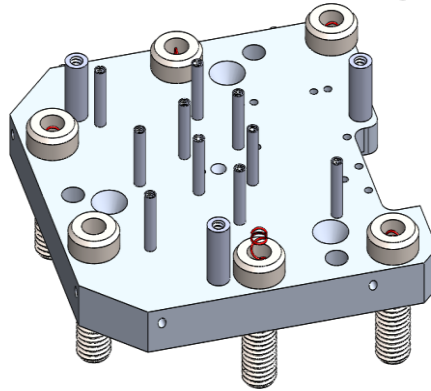


Frame

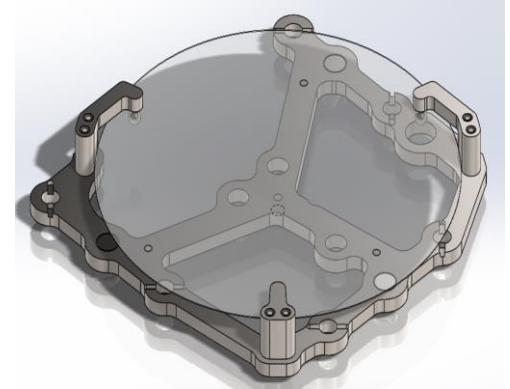
Mirror Box Assembly



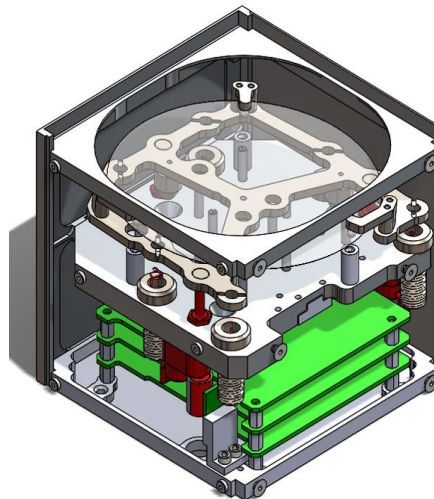
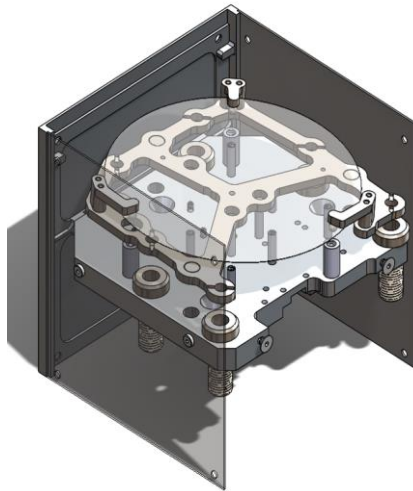
Base with PCBs



Reference Plate



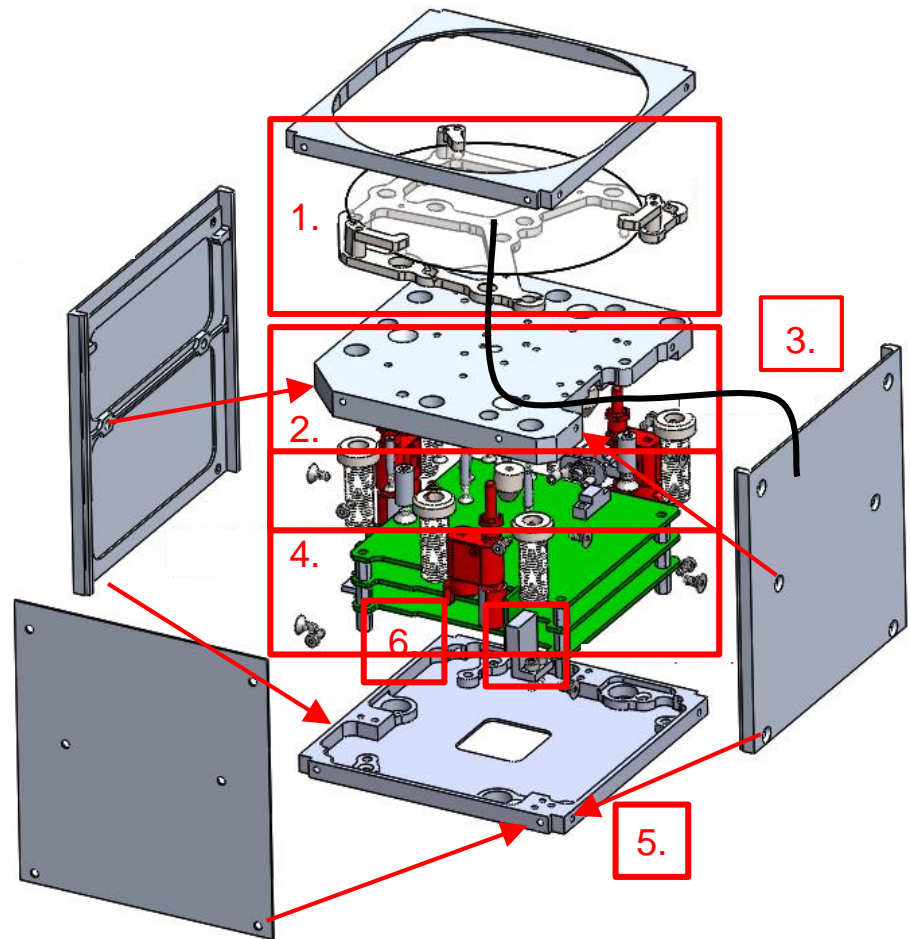
Mirror Plate



- Both boxes are assembled using similar procedures which integrate the three primary subsystems of the boxes
- These procedures are codified in assembly documents

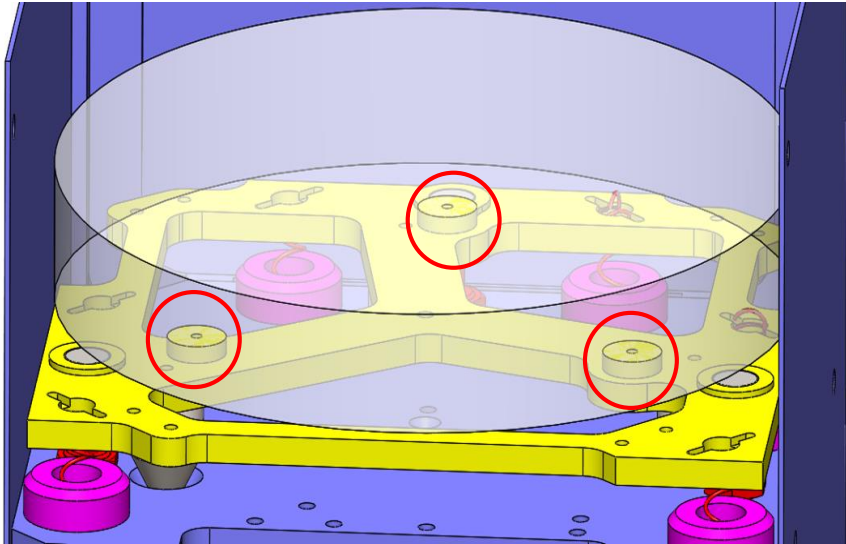
Assembly overview

1. Mirror plate + mirror
2. Reference plate + picomotors
3. Mirror plate + reference plate connected via Vectran™ tensioning
4. Electronics boards mounted on base plate
5. Mirror assembly and walls attached to base plate
6. Optical encoder mounts attached to base plate



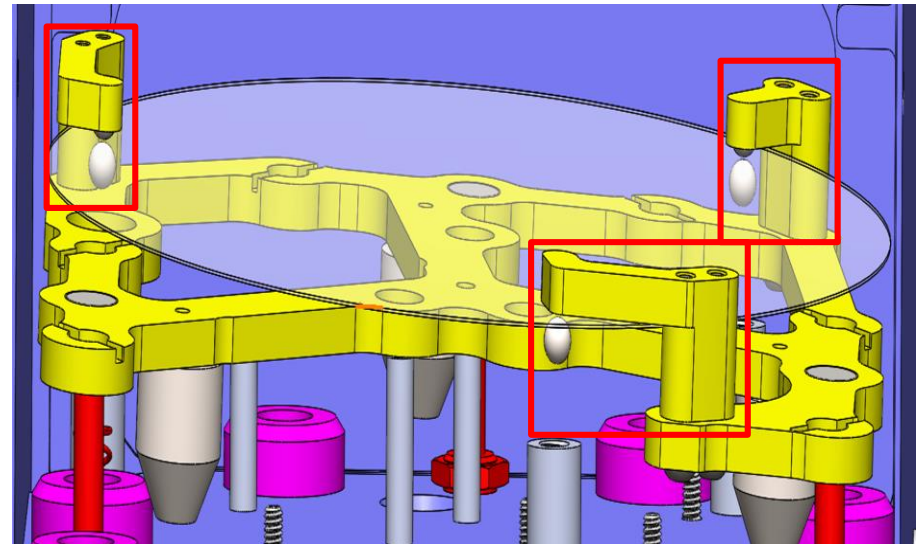
Securing the Mirrors

Rigid



Attached at three raised pads with epoxy

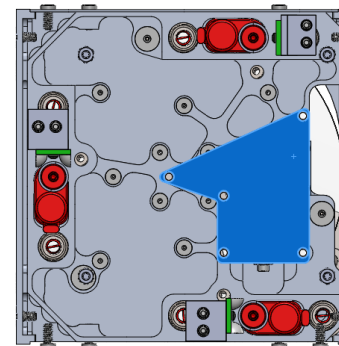
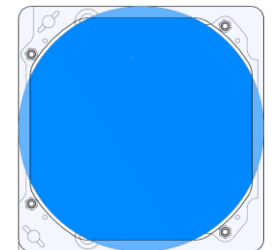
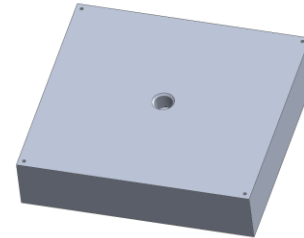
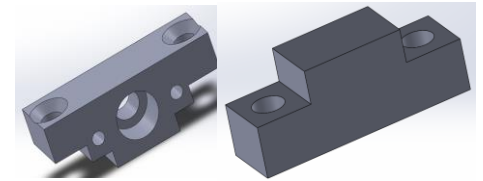
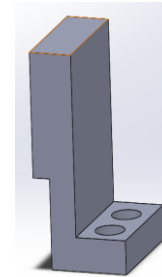
Deformable



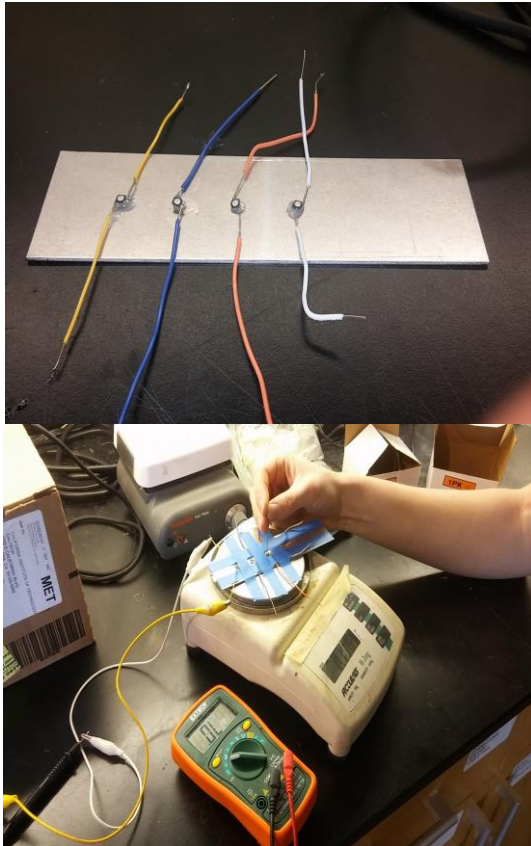
Attached to mounting posts with magnet & ball bearing pinches

Designed and Manufactured Components

- Optical Encoder Bracket
 - Picomotor optical encoder
- Shaft & Clamp Inserts
 - Launch restraint & separation devices
- Representative Mirror Mass
 - Vibration testing
- Optical Mirror Mask
 - Rigid mirror alignment
- Separation Device Lid
 - Contain Vectran after deployment



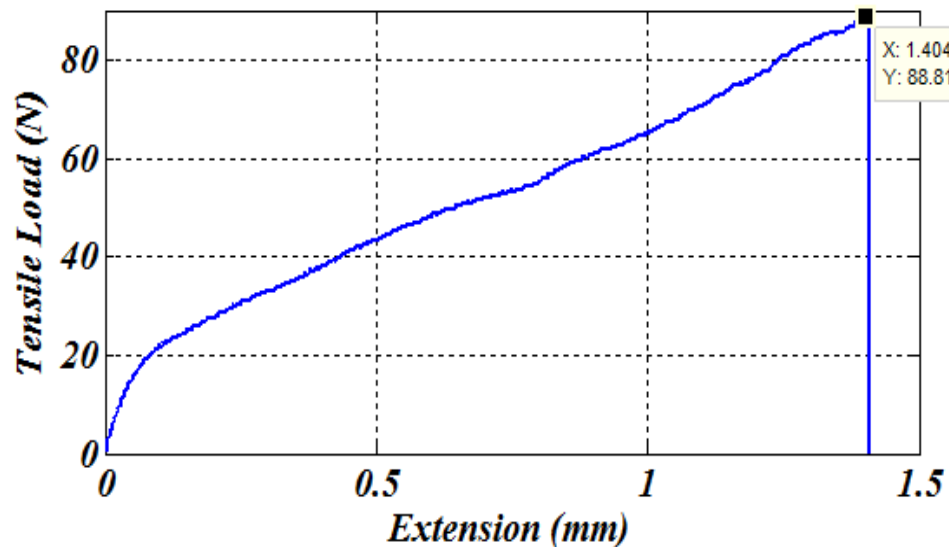
Limit Switch Test



- Picomotors provide **13 N** of force when translating
- Need a fail-safe mechanism to restrain over-actuation
- Nano-miniature Top-Actuated Tact Switch
- Determined force needed to activate switch to ensure they were up to spec
- Mean depression force: **1.02 N**
- Overall Std. Dev: **.09 N**
- The switches were within the force range provided by the manufacturer of **1N +- 25%**

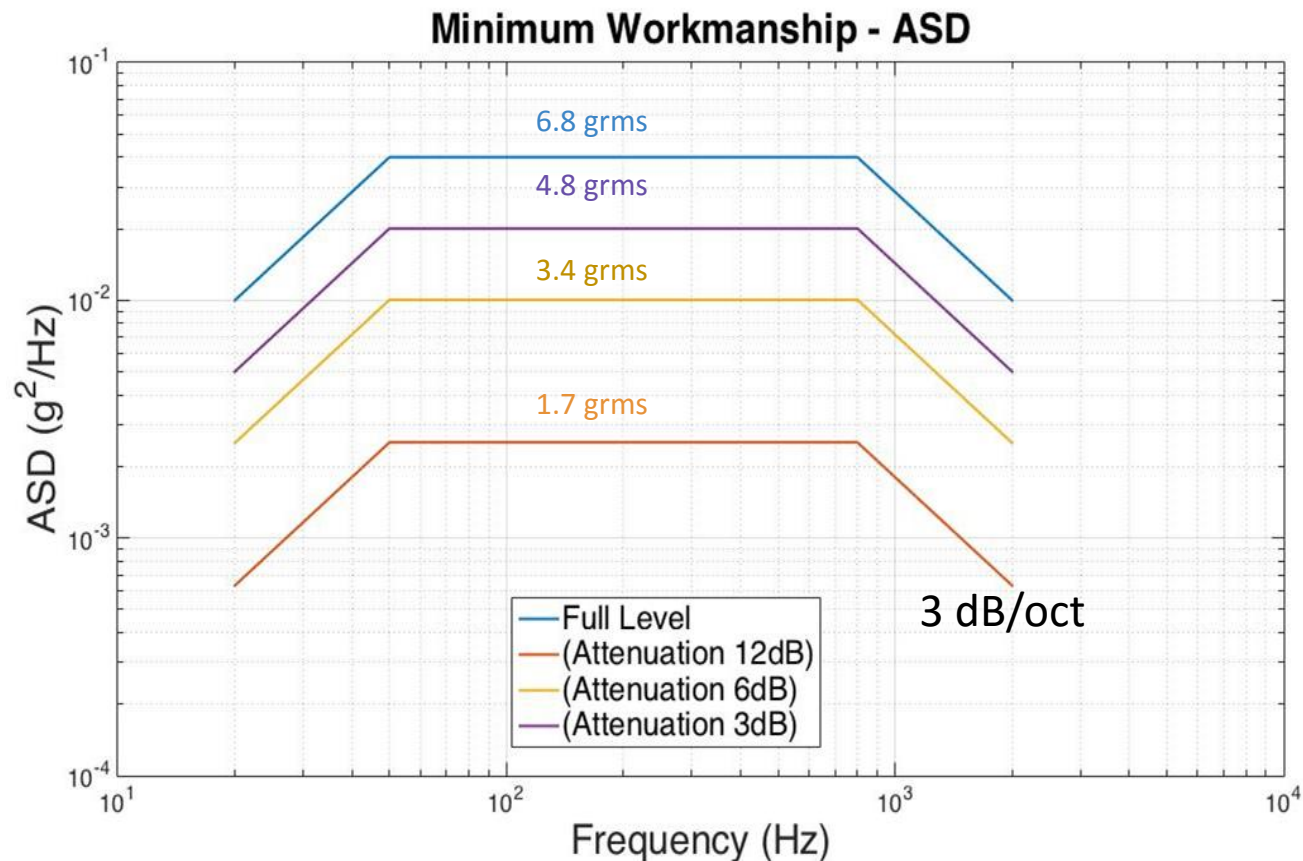
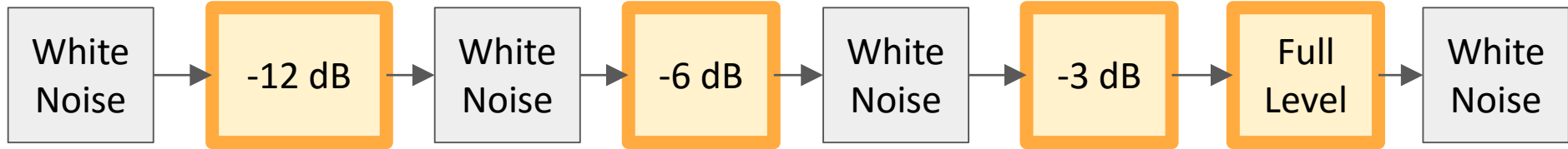
Epoxy Bond Test

- Rigid Mirror Box: Mirror is glued to mirror plate
- Peak Acceptance: 40g -> ~ **42N** on each pad
- Epoxy Name: Loctite EA 9394 AERO
- Tensile test
 - Failure at **88.8N**
 - Debonding from mirror surface



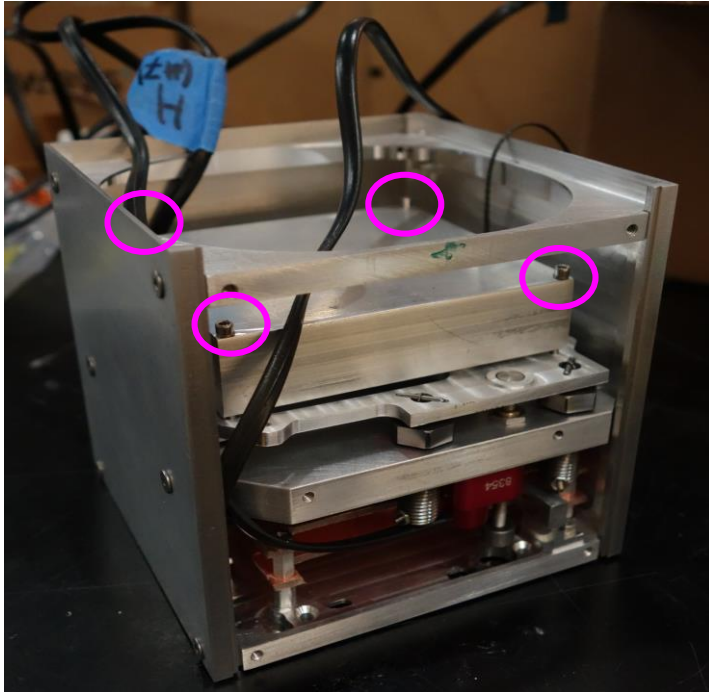
- Limitations: Outgassing properties of 1.5%
- Need to take this strength and compare it with vibration results

Vibration Testing: Test Sequence and Input Profiles



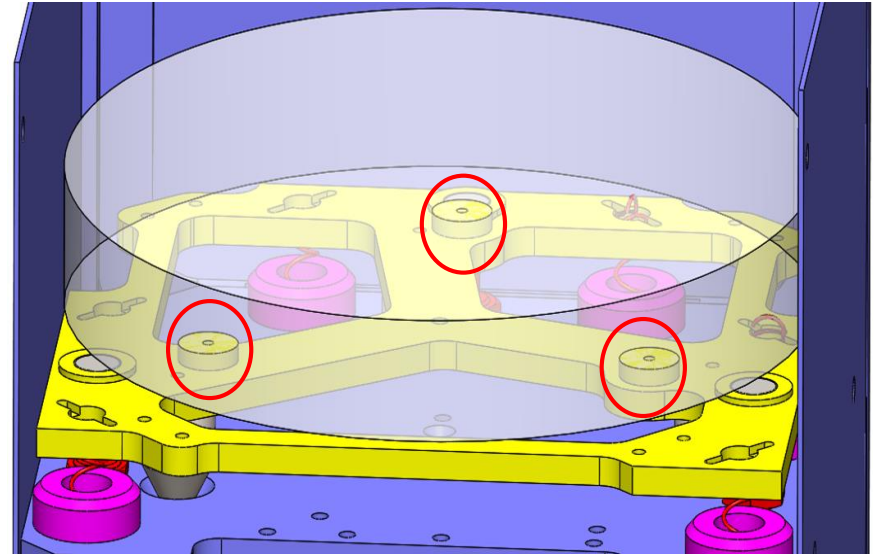
Substituting the Mirror

Vibration Testing



Aluminum Mass Screwed to Mirror Plate

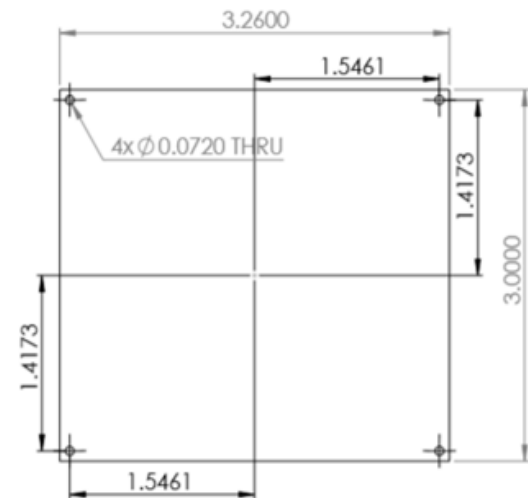
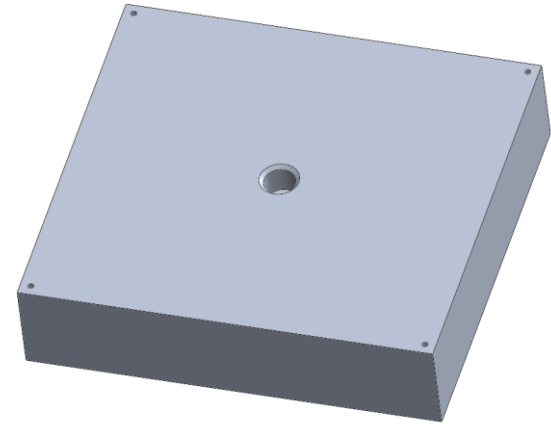
Flight



Rigid Mirror Epoxied to Pads on Mirror Plate

Substitute Mirror Mass Design and Manufacture

- Mass: 323.5g
- Density comparable to Zerodur
- $\frac{3}{4}$ " aluminum rectangular block
- Secured to mirror plate via 2-56 1" long screws
- Dimensions large enough to secure to mirror plate spare holes and small enough to fit within box
- Milled down to size and drilled holes

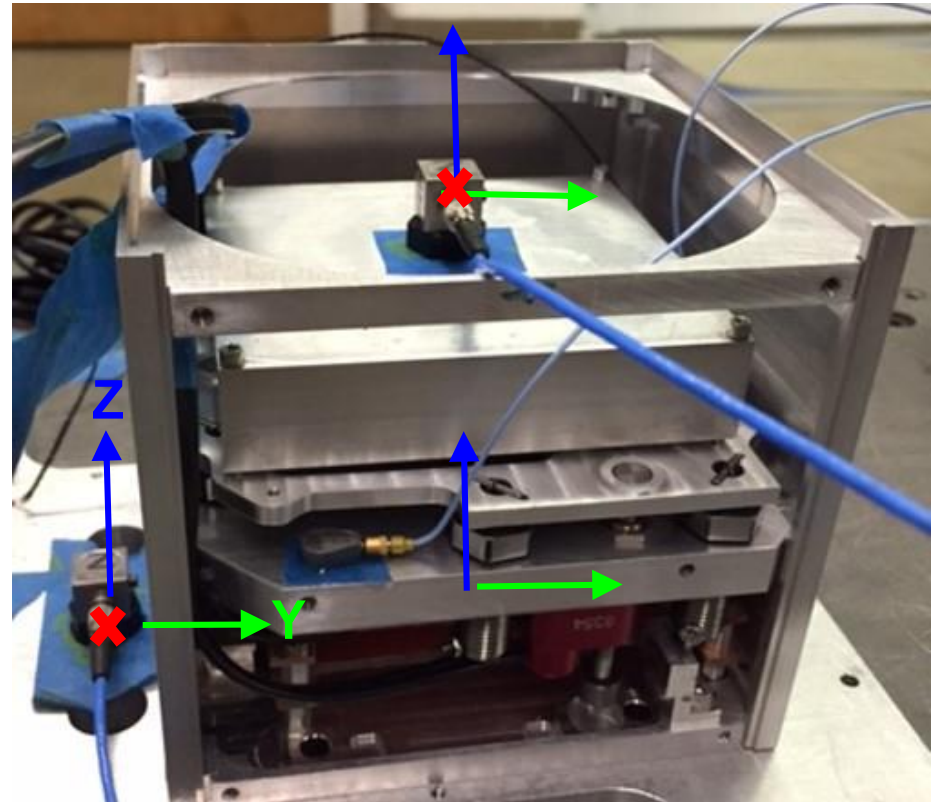


Deviations From Test As You Fly (TAYF)

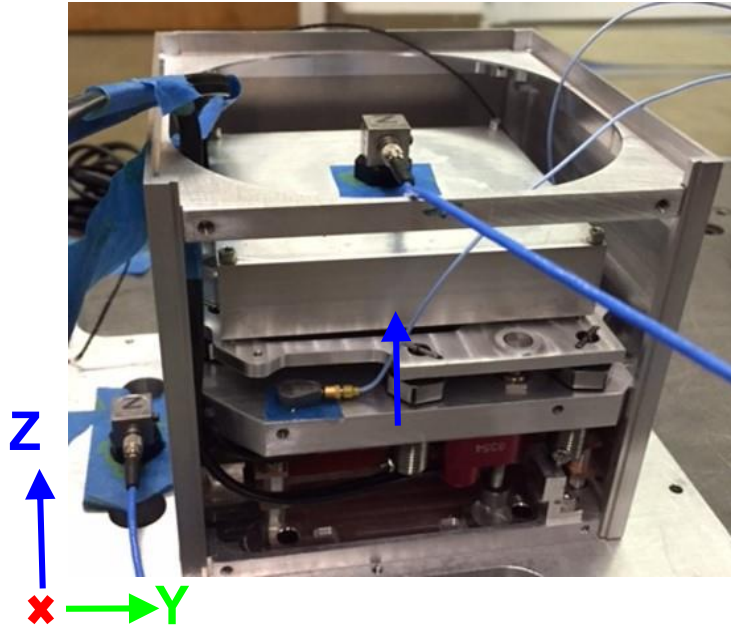
Proto-Flight Boxes	Flight Boxes	Impact
Aluminum Mirror Mass	Actual Rigid Mirror	High
Screws attach rigid mirror to mirror plate	Epoxy bond applied between mirror and mirror plate	High
Picomotors have large RJ45 network wires and are not vacuum-compatible	Picomotors will have encoded Kapton® and will use a vacuum-compatible model	Medium
No additional sensing equipment	Temperature Sensors with wiring	Medium
Manually Cut Glass Fiber Boards	Electronics PCBs	Low
Optical Encoder Brackets	Optical Encoder Brackets with PCB and Encoder	Low

Accelerometer Placement

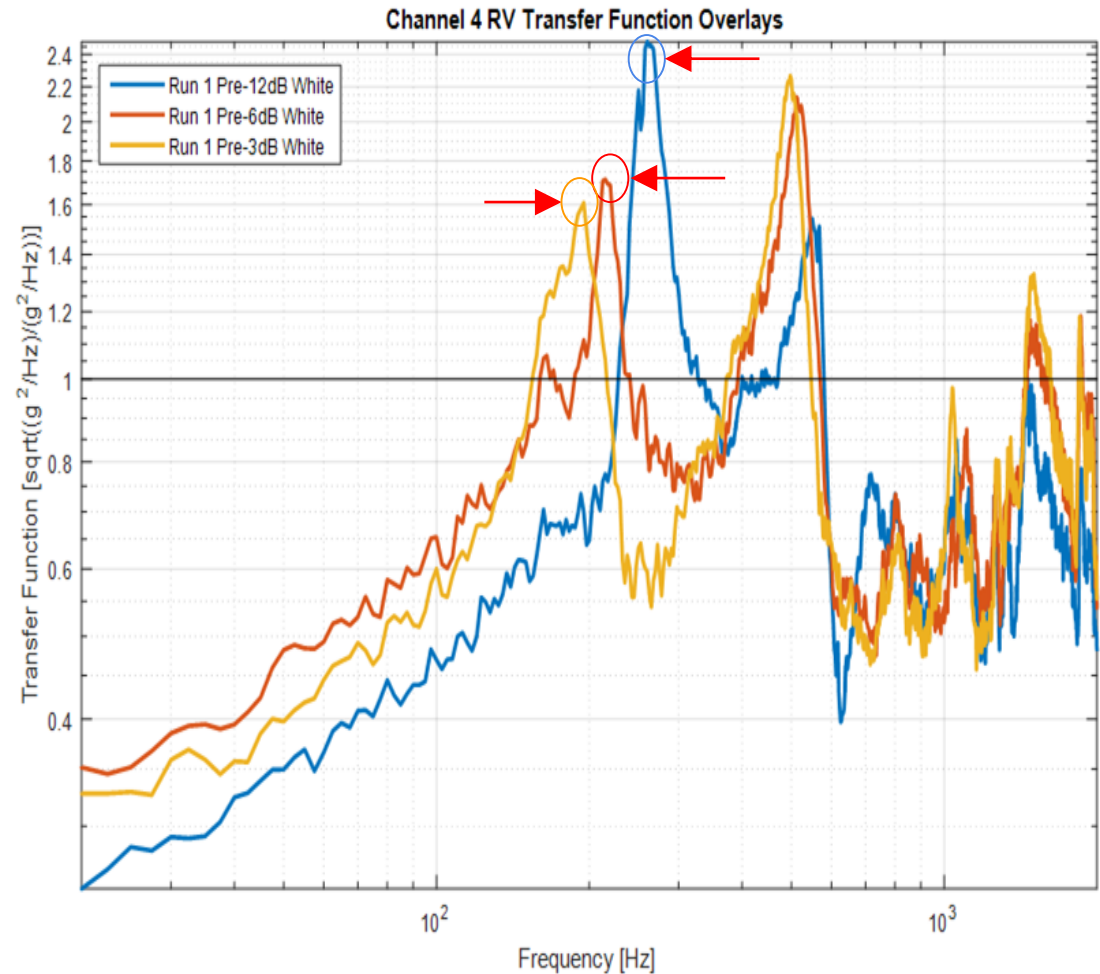
- The signal was input in the **Y direction**
- Accelerometers recorded:
 - All 3 axial responses of the mirror mass
 - All 3 axial responses of interface plate (control)
 - vertical **Z axis** of reference plate
 - input **Y axis** of the reference plate
- Accelerometer locations chosen to identify accelerational load particular to mirror mass from that of entire system



Ch4: Reference Plate Z-Axis White Noise Test 1 Results

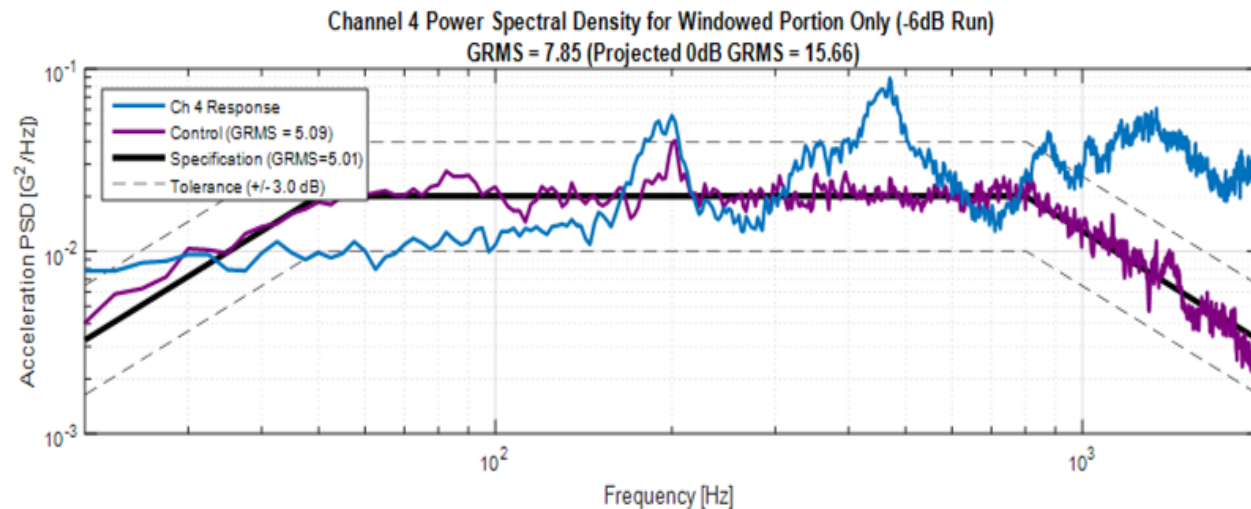
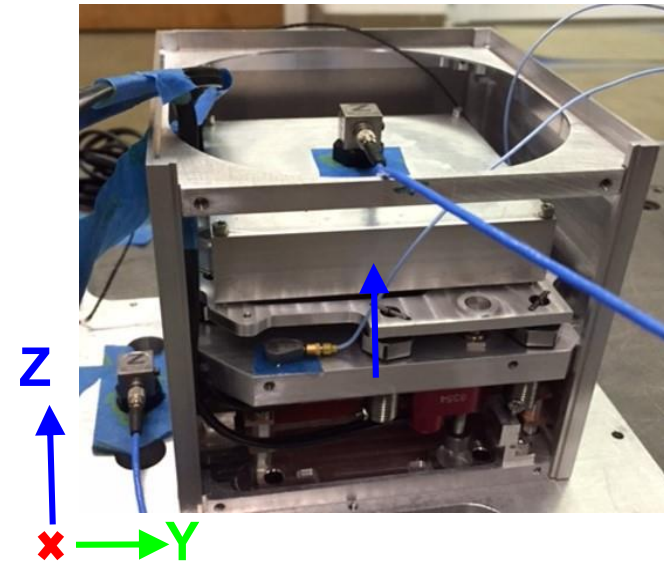


- **20% shift** in resonance frequency after the -12dB test
- These shifts continued after -6dB, signalling **structural changes in the test article**
- Inspected the time history and PSDs for more information

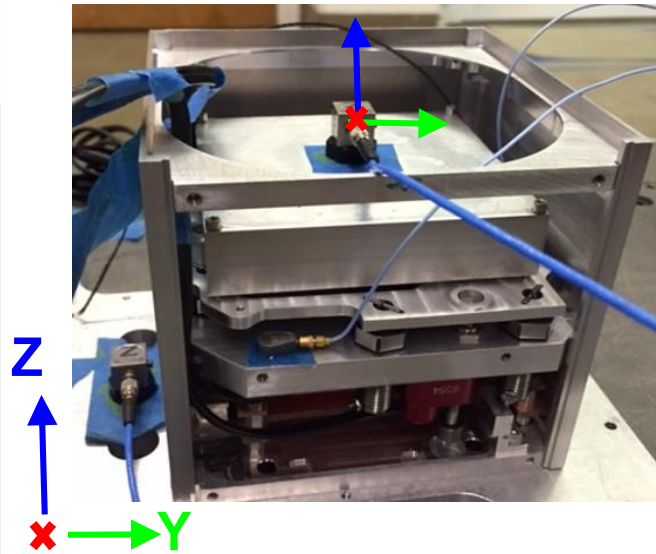


Ch4: Reference Plate Z -6 dB Test 1 Results

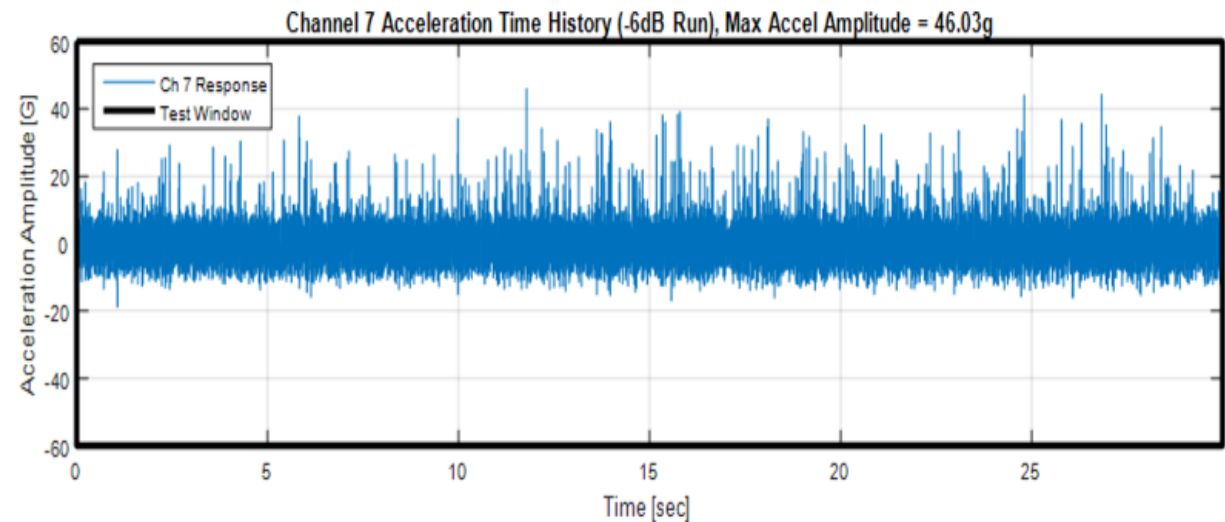
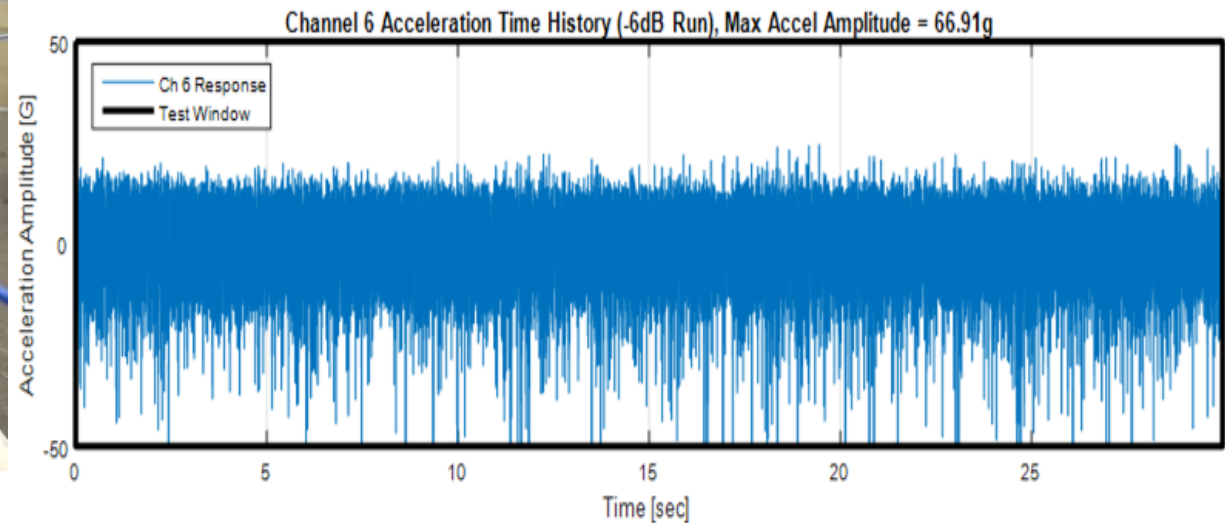
- The vertical axis of the reference plate experienced unexpectedly large amplification
 - Max acceleration: **122.67 g**
 - GRMS: **7.85**
- Cross-Coupled Response
- First Mode of a Thin Plate
- Continued the search for answers with the mirror mass...



Ch6 & Ch7: Mirror Mass Y & Z-Axis -6 dB Test 1 Results

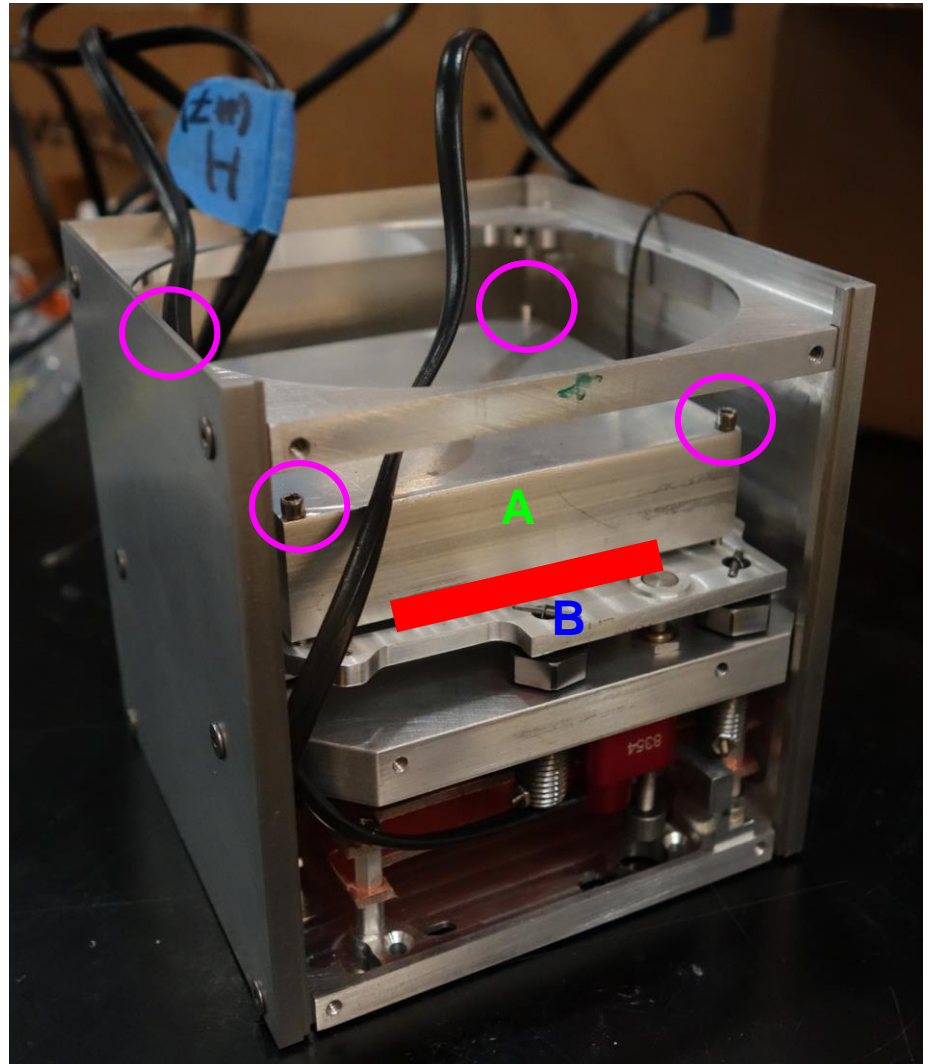


- Mirror Mass vertical and input axes responses were one-sided
 - Upon visual inspection, the mirror mass was loose, and was slapping the reference plate and walls/wires

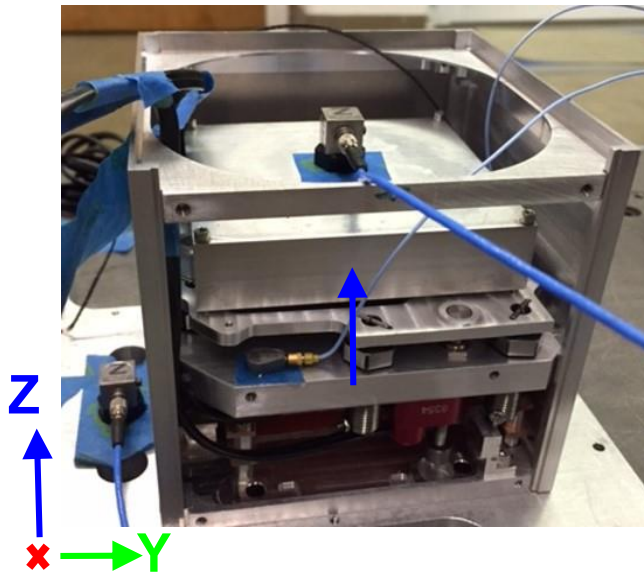


What does a “loose mirror mass” mean, and how do we fix it?

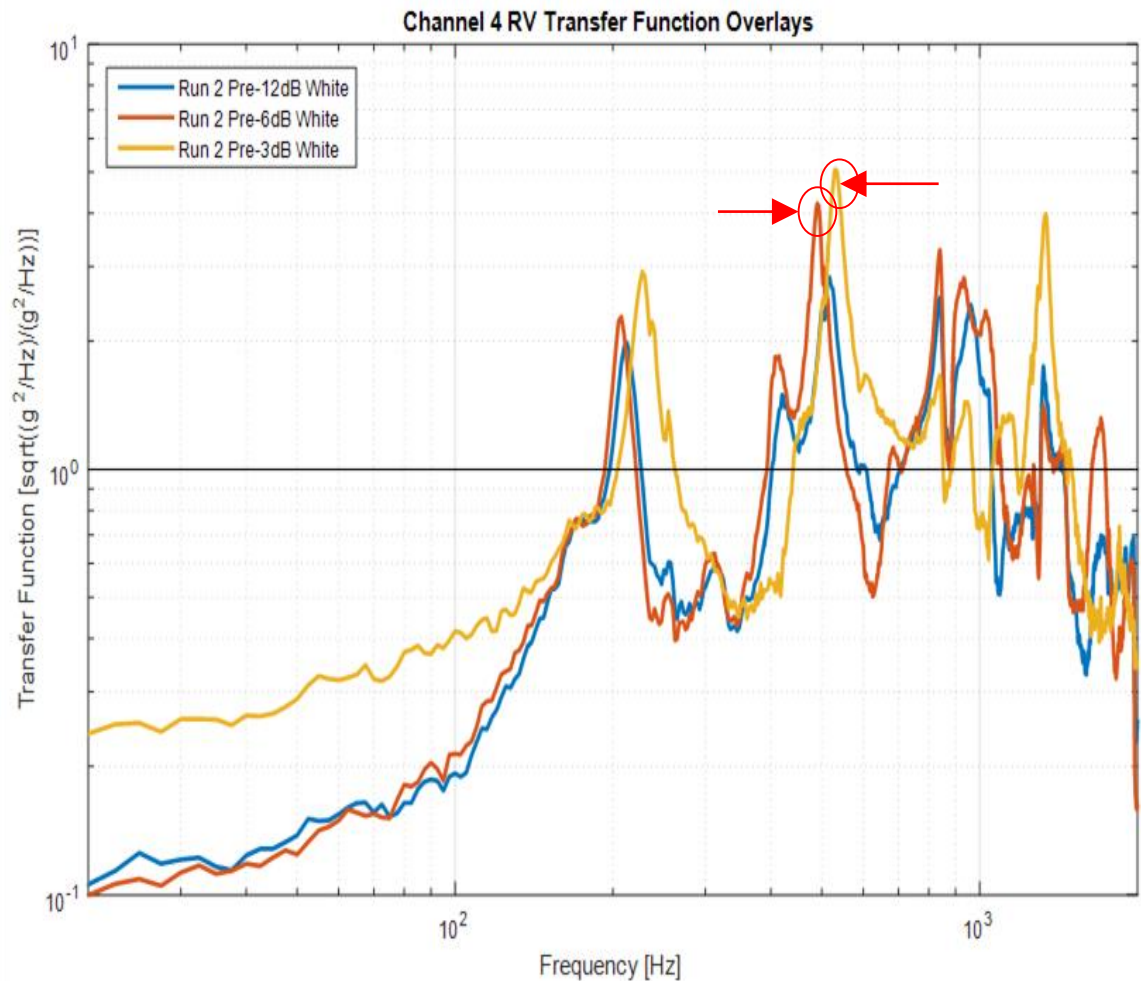
- The Rigid Mirror will be attached to the Mirror Plate using epoxy
- For vibration testing purposes, the **Mirror Mass** is attached to the **Mirror plate** using **screws**
- Improper securement of the mass appeared a likely cause of the unexpected test results
- To eliminate the excess spacing between the Mirror Plate and Mirror Mass, washers were added to the corner screws, along with **foam** between the two pieces



Ch4: Reference Plate Z-Axis White Noise Test 2 Results

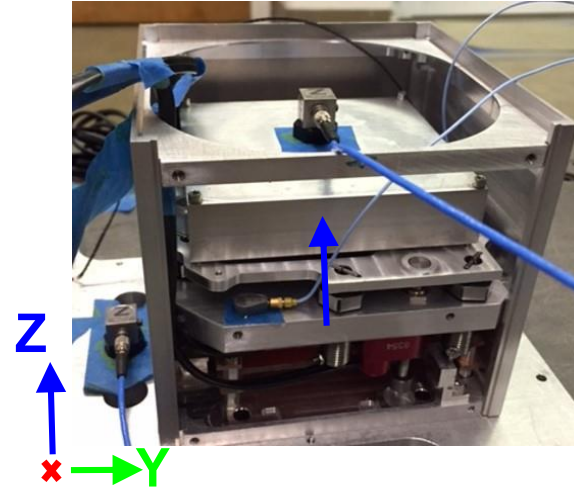


- All screws were confirmed secure with a torque wrench
- After properly securing the mirror mass, the reference plate had acceptable, smaller frequency shifts

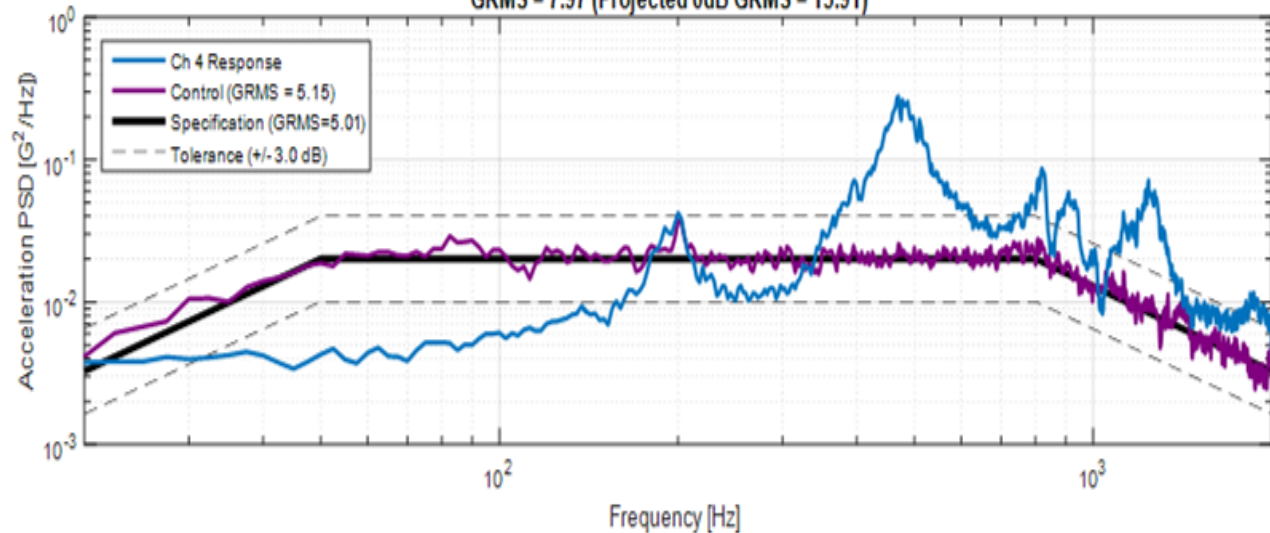


Ch4: Reference Plate Z -6 dB Test 2 Results

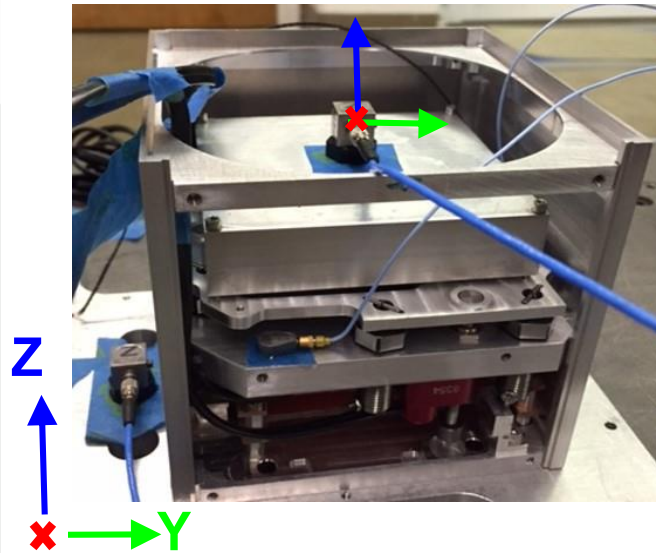
- After securing the reference plate, the amplification was lessened
 - Max acceleration: 84.46g (122.67g)
 - GRMS: 7.97 (7.85)
- Preliminary projections from this data raise possible **concerns about the epoxy bond strength**
- Solutions include increasing pad size for larger bond area



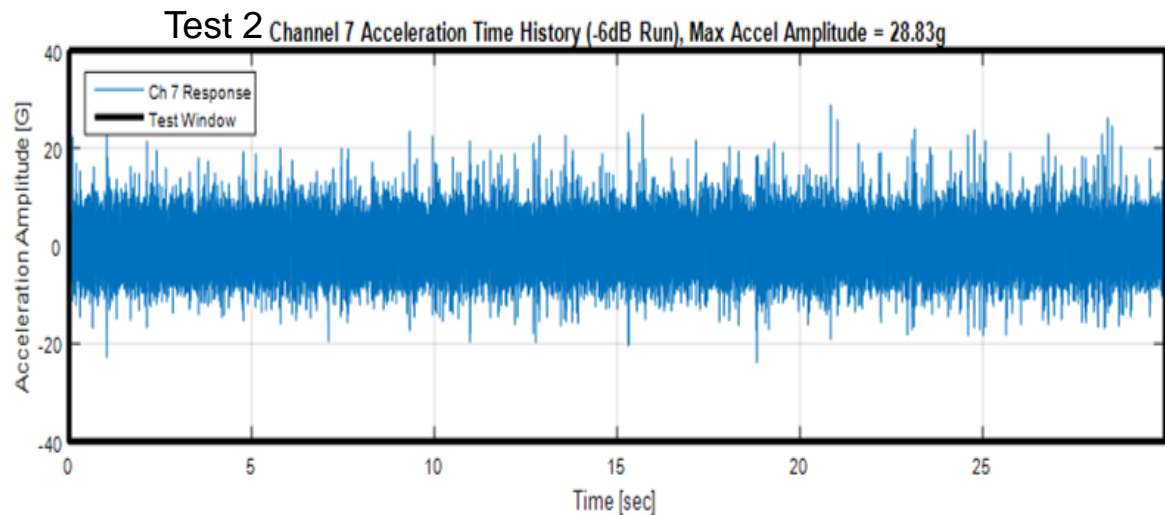
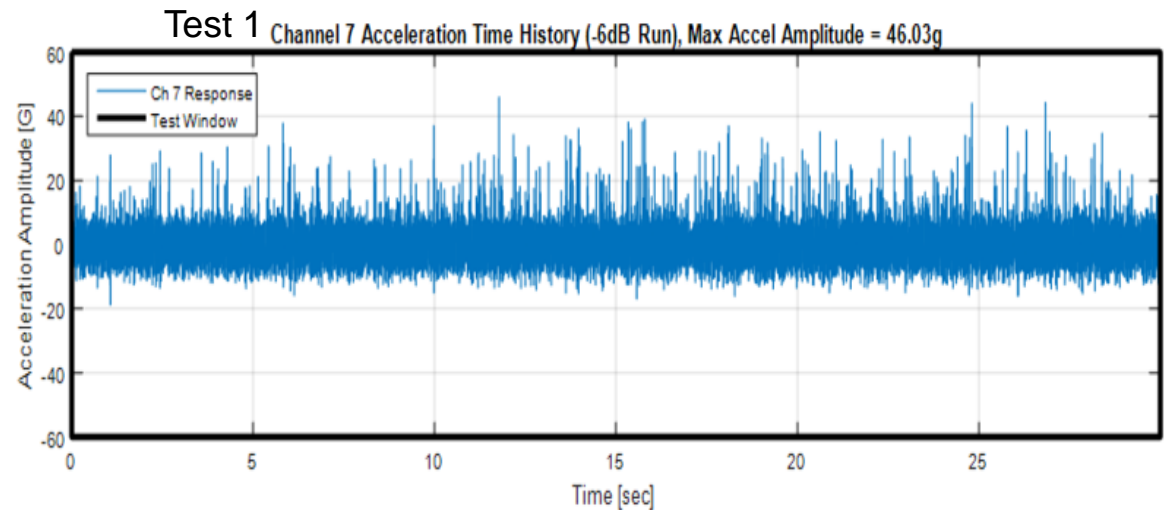
Channel 4 Power Spectral Density for Windowed Portion Only (-6dB Run)
GRMS = 7.97 (Projected 0dB GRMS = 15.91)



Ch6 & Ch7: Mirror Mass Y & Z-Axis -6 dB Test 2 Results



- Mirror Mass Response now displayed expected two-sided peaking
- Upon visual inspection, box displayed no signs of structural failure

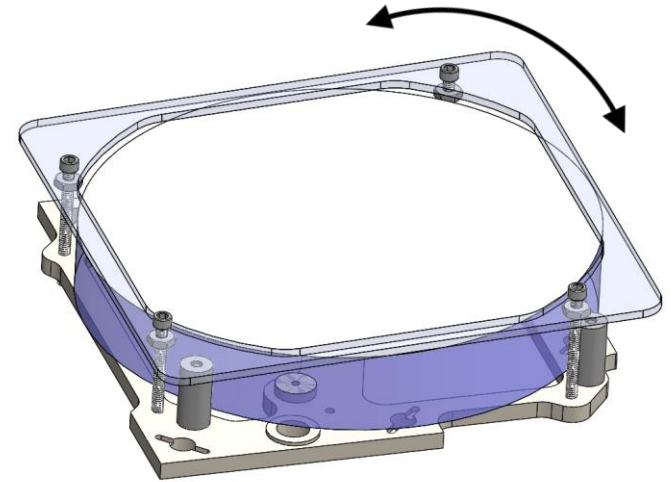


Vibration Testing Conclusions

- Potential to exceed bonding strength at full level loading
- Box structure withstands very high peak loading
- Shaker table needs to be fixed so Y and Z axis can be accurately assessed

Rigid Mirror Mask Design and Manufacture

- After Vibration Testing, need to optically align the mirror for a “true assembly”
- Need to maintain mirror position during optical alignment
 - Box is rotated to apply epoxy to underside of mirror
- Designed and manufactured a mask to secure the mirror during optical testing and assembly



Summary of Tasks

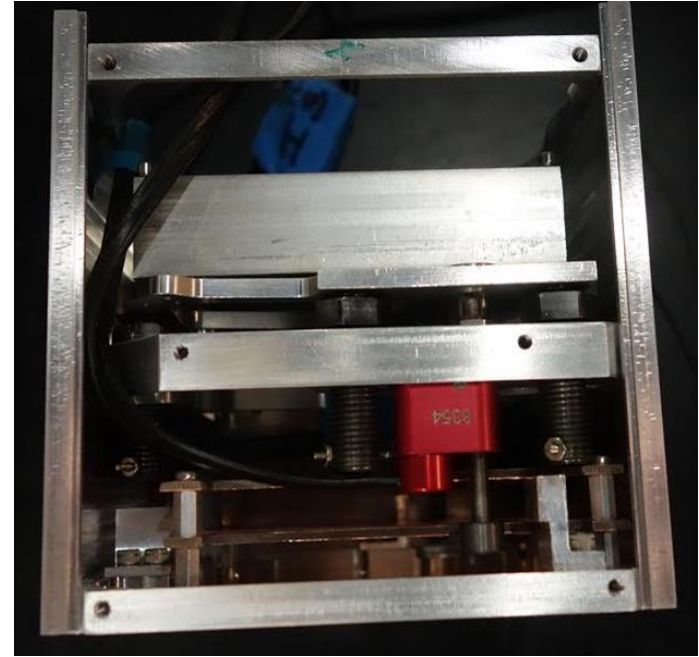
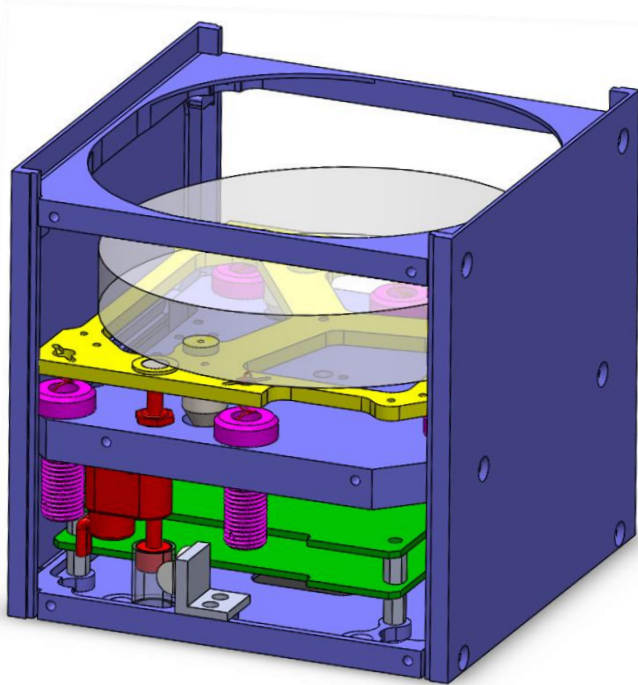
Completed Work

- Designed and manufactured components
- Limit switch and Epoxy Bond Test
- Assembly of both boxes
- Assembly documents
- Rigid box vibration testing in y
- Rigid box optical testing preparation

Future Work

- Vibration testing of rigid mirror in x and z
- Vibration testing of deformable mirror box
- Complete assemblies with real mirrors
- Optical testing and alignment verification
- Separation device mechanism test

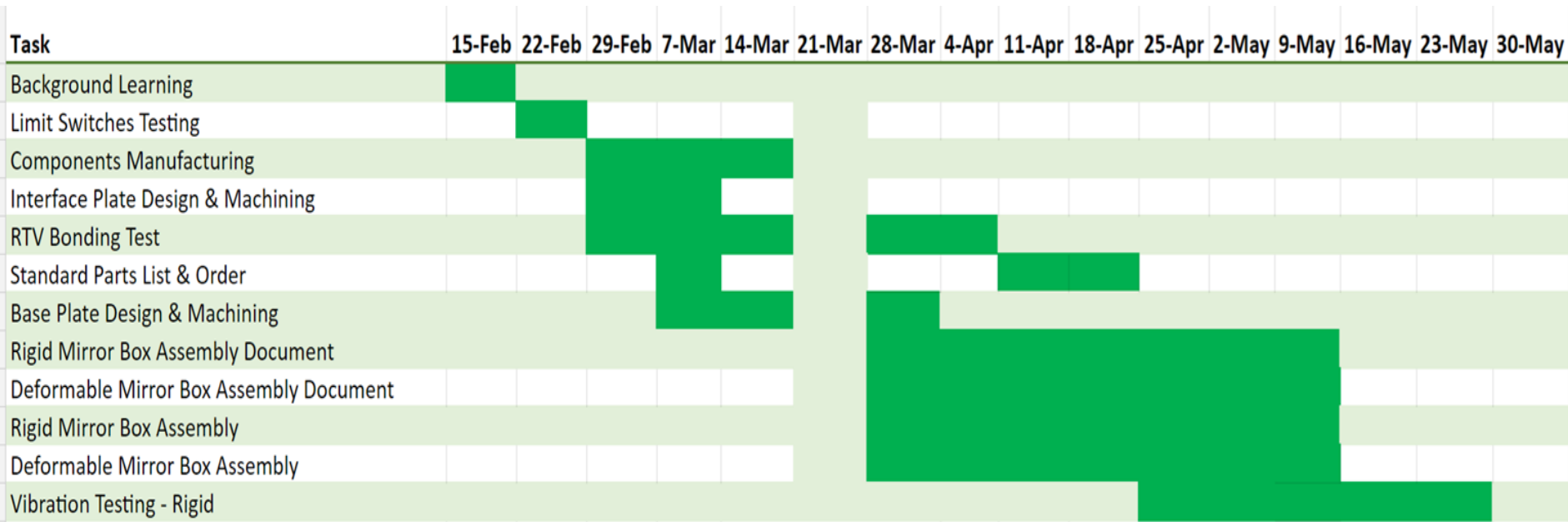
Concluding Remarks



The Mirror Boxes have progressed from CAD models to real, assembled equipment and undergone a first round of vibration testing

Backup Slides

Schedule



Assembly Documents

I.	Materials Required
A.	Principle Materials
B.	Shims for Pillars
II.	Summary Instructions
III.	Assembly
A.	Mirror Plate
1.	Epoxy of vees and springs
2.	Mounting mirror
B.	Reference Plate
1.	Shims
2.	Separation Device
3.	Picomotors
C.	Electronics Plate
D.	Integration
1.	Vectran Cable
2.	Attaching Walls
3.	Optical Encoders

AAReST Deformable MirrorBox Assembly Document

Serena Ferraro

Project Supervisor, California Institute of Technology

Jake Larson and Catherine Pavlov

Rigid MirrorBox Members, California Institute of Technology

These instructions detail the recommended assembly method for the Deformable MirrorBox for the AAReST project. This includes assembling the base electronics plate, assembling the reference plate, and assembling the mirror plate. For the MirrorBox containing the rigid mirrors, please see the Rigid MirrorBox Assembly Document.

AAReST Rigid MirrorBox Assembly Document

Serena Ferraro

Project Supervisor, California Institute of Technology

Anand Kumar, Sheila Murthy, and Tyler Okamoto

Rigid MirrorBox Members, California Institute of Technology

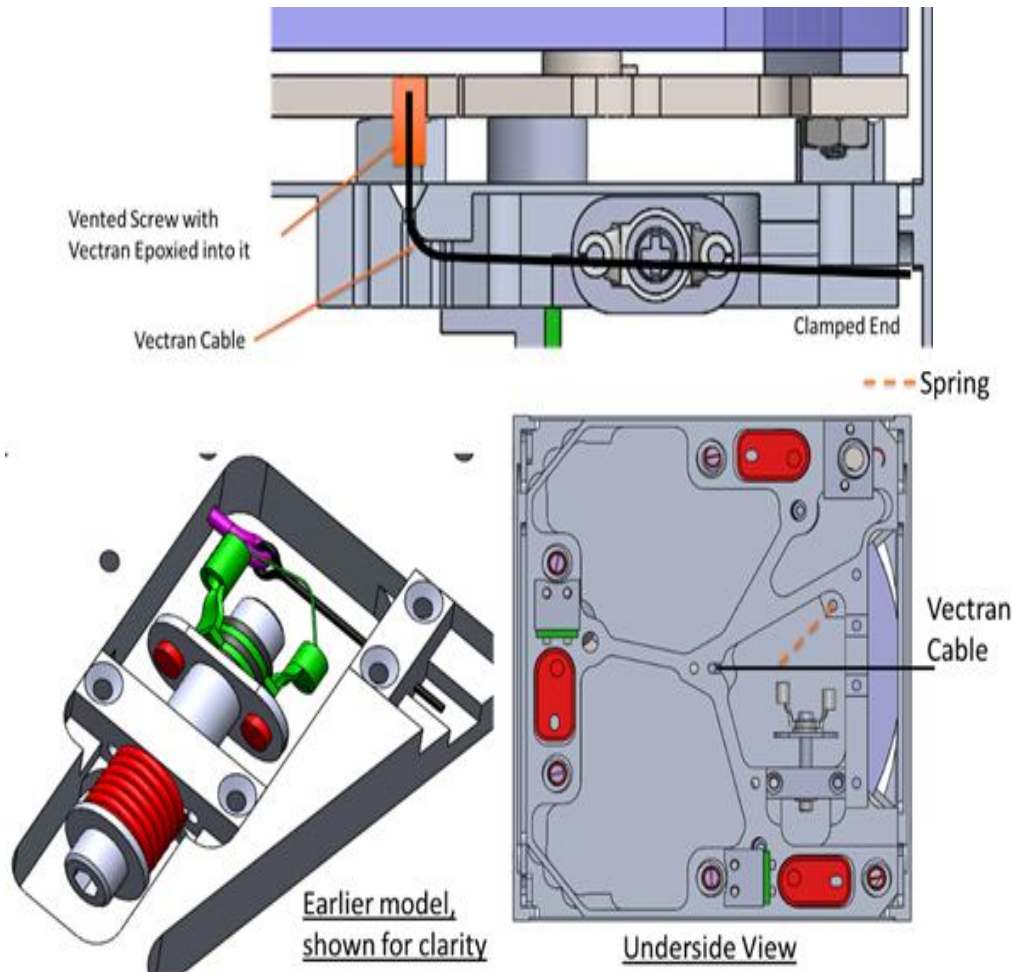
These instructions detail the recommended assembly method for the Rigid MirrorBox for the AAReST project. This includes assembling the base electronics plate, assembling the reference plate, and assembling the mirror plate. Special steps are required in order to mount and calibrate the optical assembly before the RTV silicone can be applied. For the MirrorBox containing the deformable mirrors, please see the Deformable MirrorBox Assembly Document.

Reference Plate Subsystem

- Need to limit axial excitation of Deformable Mirror
- Soft silicone pads are epoxied to the pillars
- Shims are placed below the pillars to ensure equal compression of the material at all locations,

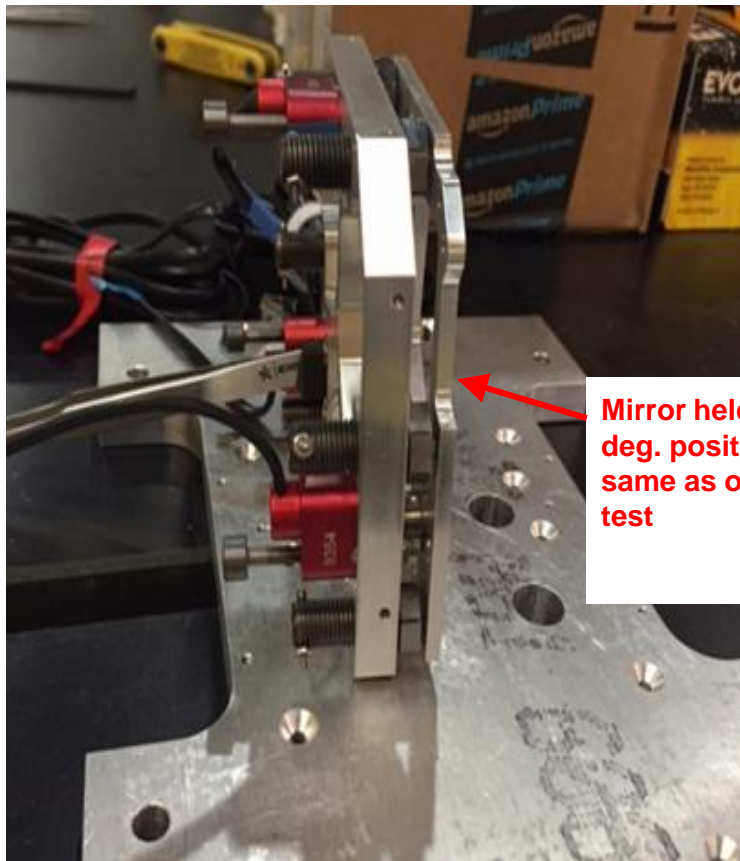


Tensioning the Vectran for Assembly

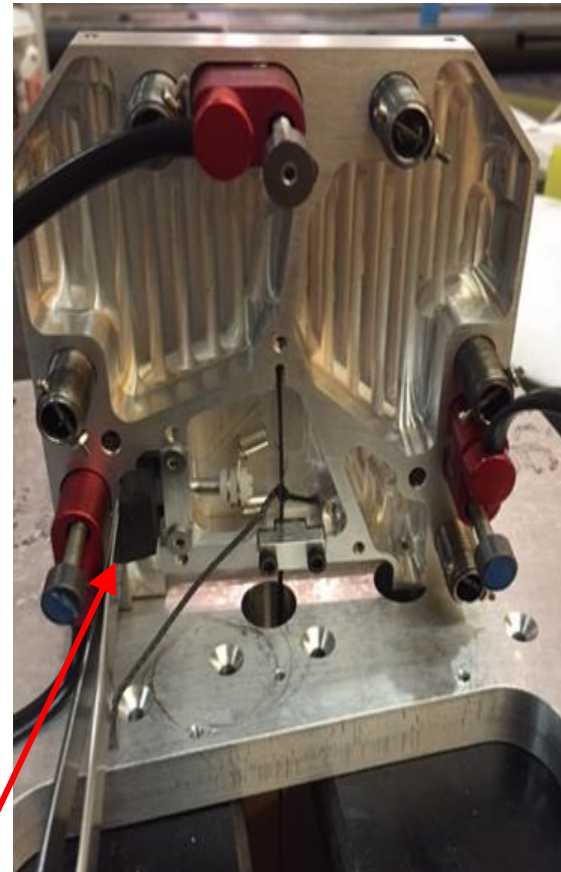


- The Launch Restraint and Separation devices secure and release the mirror during and after launch
- The mirror is secured with Vectran Cable, tensioned to 200N
- The mirror is released by activation if a NiChrome wire severing mechanism, burning and cutting the cable

Tensioning the Vectran for Assembly

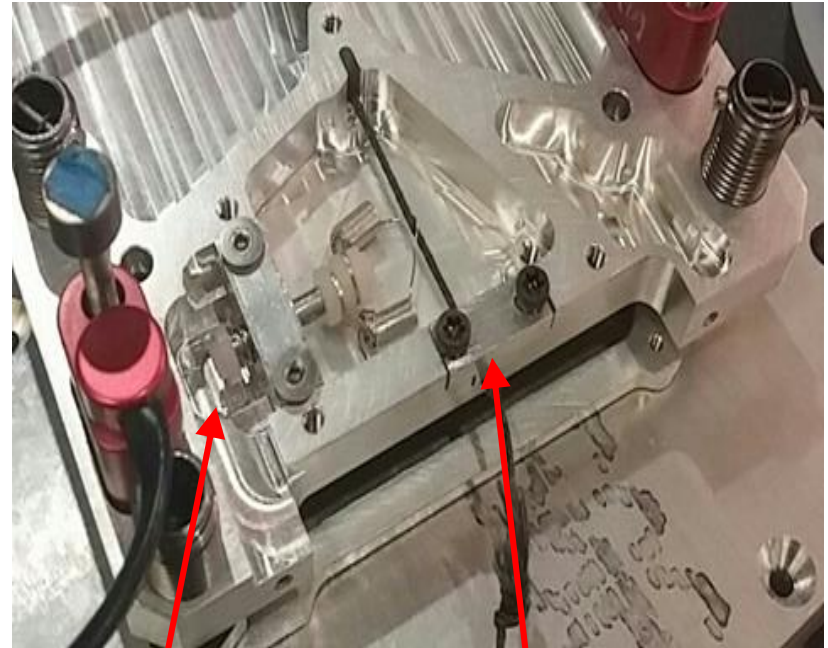


Mirror held in 90 deg. position, same as optical test



Stopper

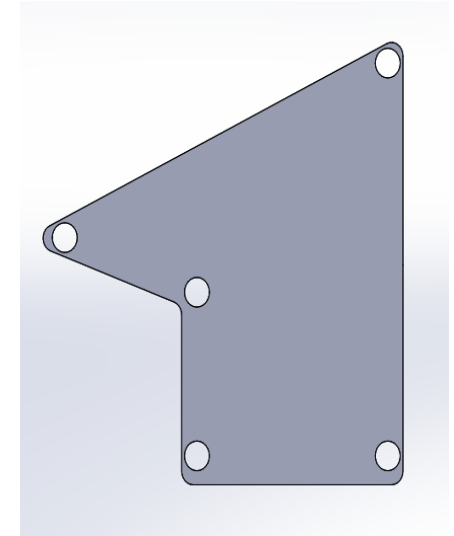
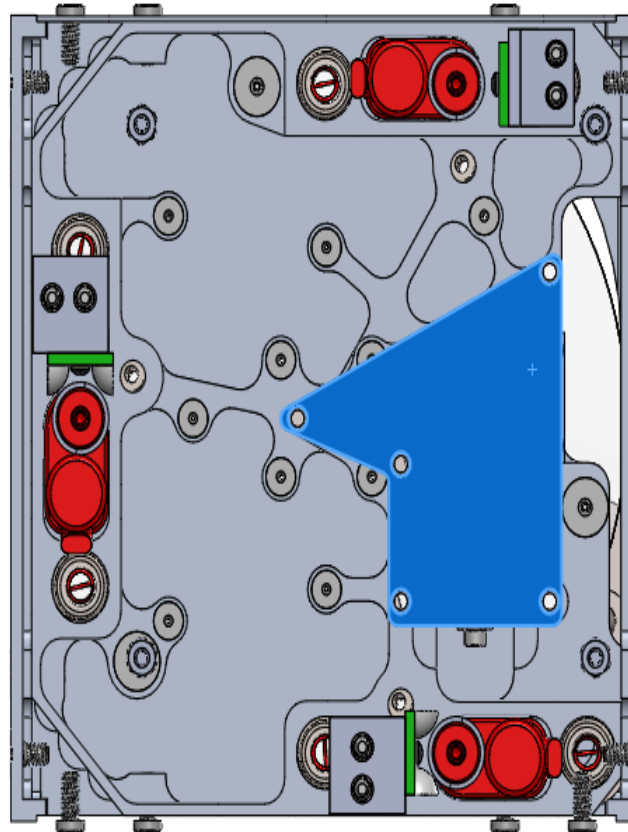
Tensioning Vectran for Assembly



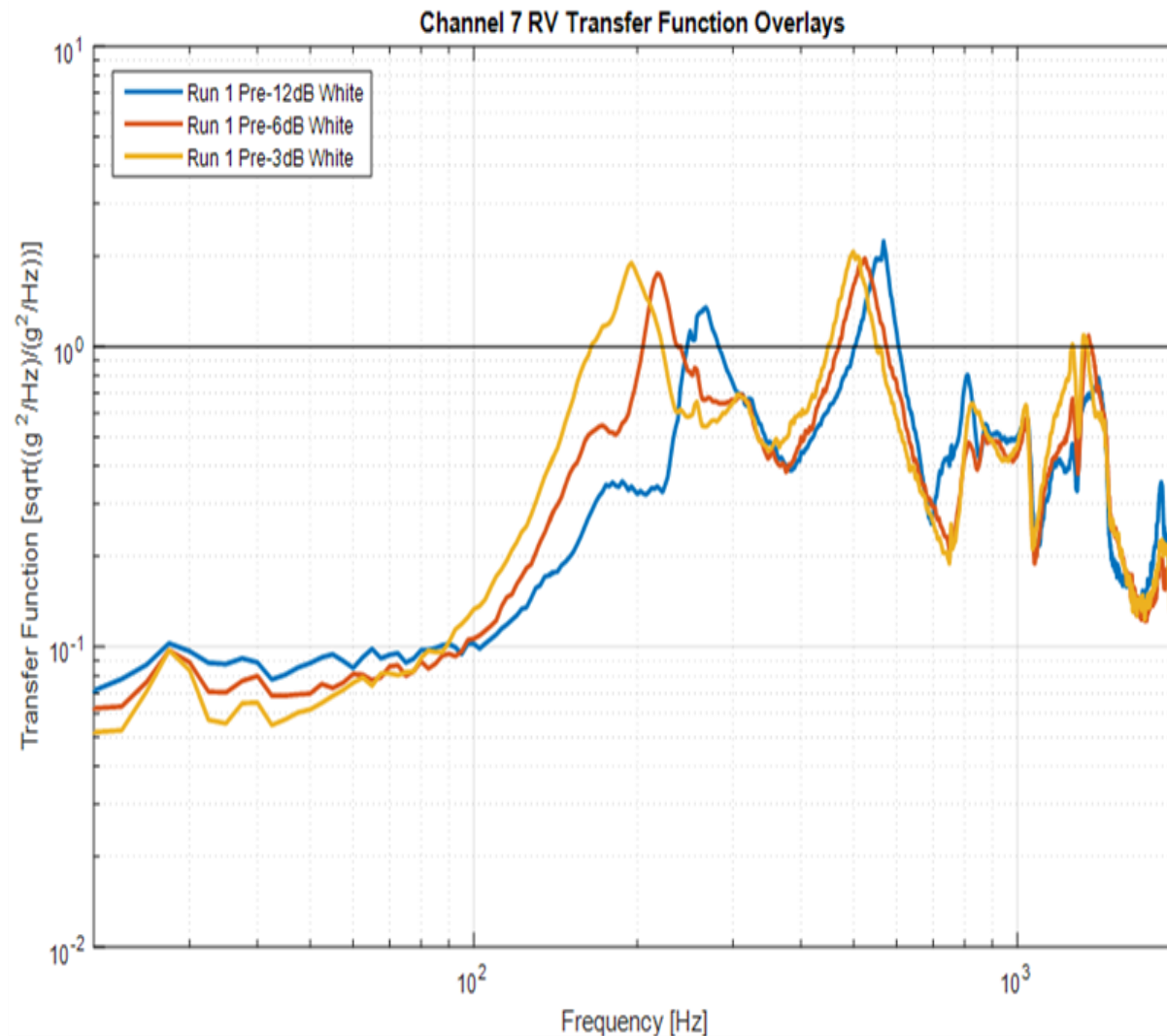
2. Fix Clamp

Reference Plate Lid

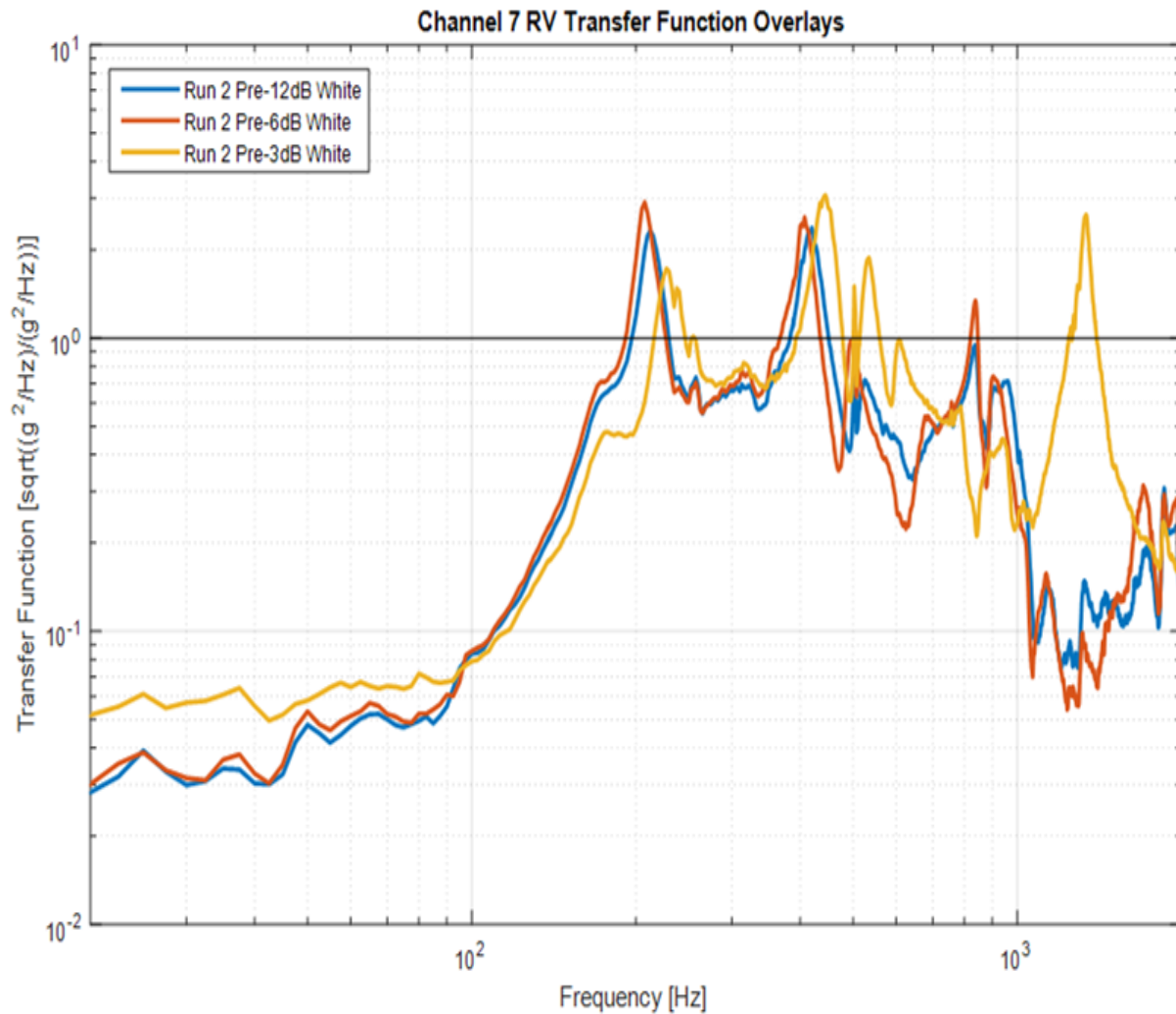
- After vectran is cut, there will be loose vectran cable
- Lid designed to keep vectran pieces contained after mirror deployment, as well as protect surroundings from heat and current in burnwire



Transfer Function for Mirror Mass Z Axis Run 1

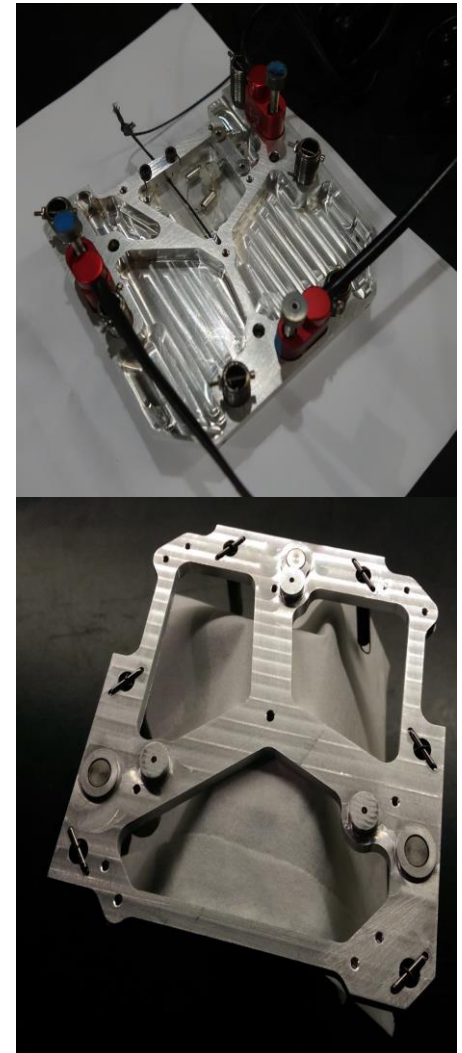
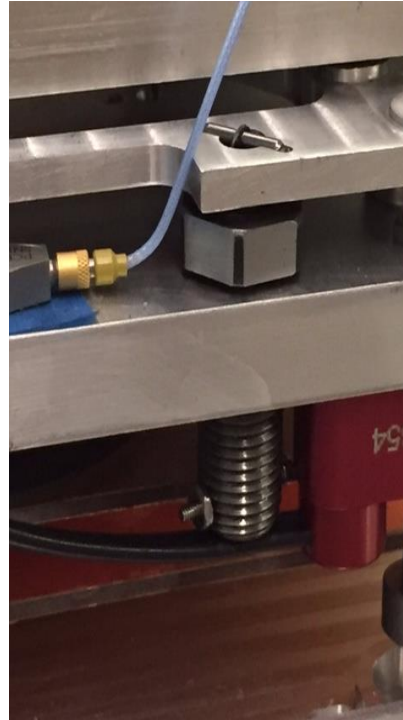


Transfer Function for Mirror Mass Z Axis Run 2



Second Set of Rigid Box Vibration Test Results

- -12 dB test had normal accelerations (right?)
- Assembly flaw identified during -6 dB test
 - Rattling noise in box: a picomotor is too close to adjacent spring tube pin
 - Spring tube couldn't fully tighten to reference plate
 - **Solution**: either shorten pin insert or change position



Outline

2:00 pm: Introduction & Welcome

2:15 pm: Camera

2:45 pm: Boom

3:15 pm: Mirror Boxes

3:45 pm: On-board Software

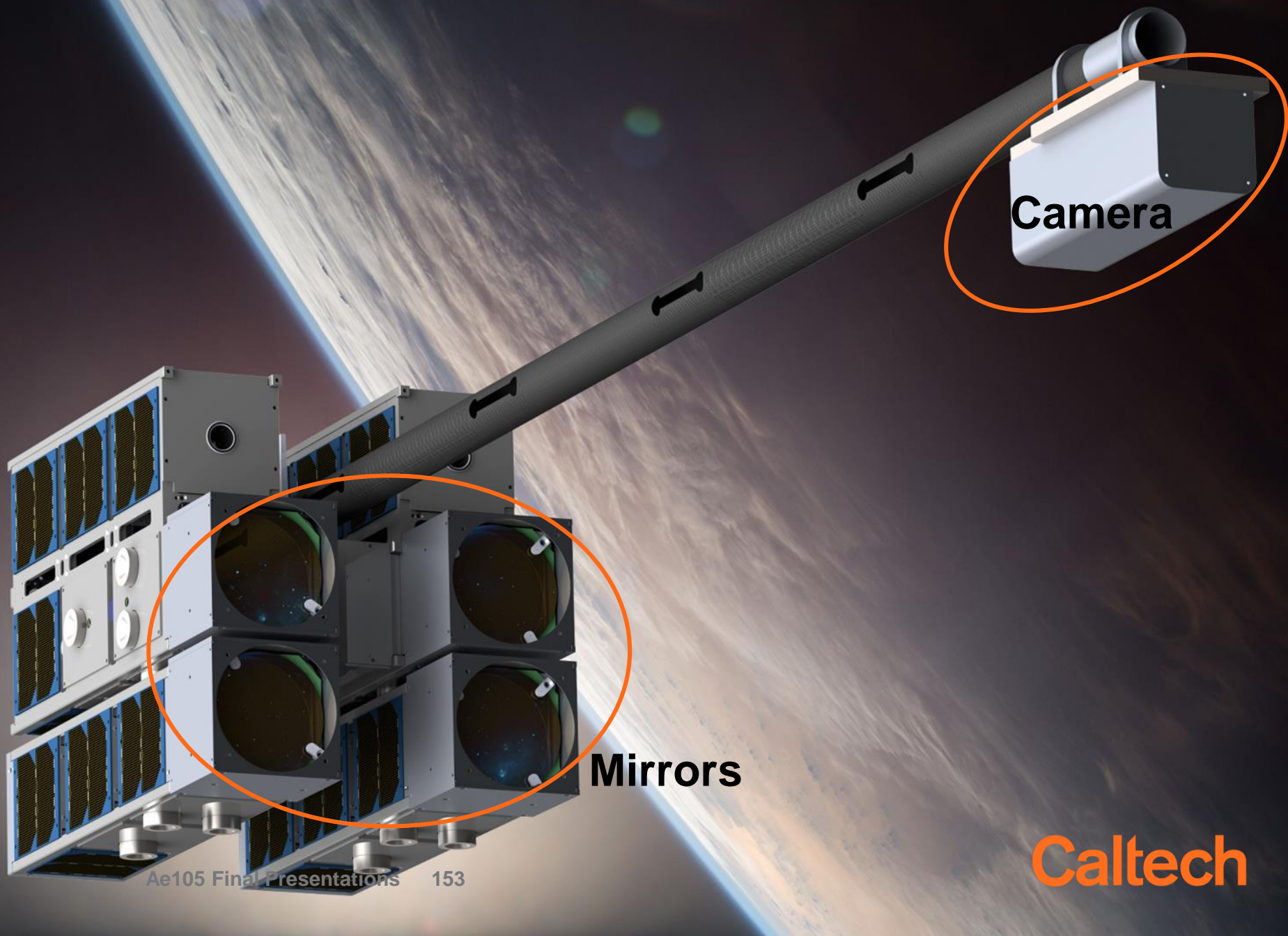
4:15 pm: Electronics

AAReST

Onboard Software (OBSW)

Gautham Sholingar
Abbas Tutcuoglu
Arjun Sadanand
Daniel Pastor
Juliana Kew

Mentors:
Thibaud Talon
Yuchen Wei



Camera

Mirrors

Caltech

High-Level Overview

Main Objectives

- 1x focused image from Deformable Mirror (DM)
- ≥ 2 images of other sources

Camera

- Capture image and perform analysis
- Control **mirror alignment**

Mirror

- **Reflects/focuses** light onto camera via 2 Rigid & 2 Deformable Mirrors
- Receives command from camera to **adjust mirrors**

Agenda – Mirror OBSW

1. High Level Overview
2. Mirror Positioning
3. Communications
4. Results and Future Work

Project Tasks - Mirror

Task I : Software

- Implement algorithm to **minimize Root Mean Square (RMS)** error of mirror position (<40 nm)
- Test implementation using **Google Testing Framework**

Task II: Comm. Protocols

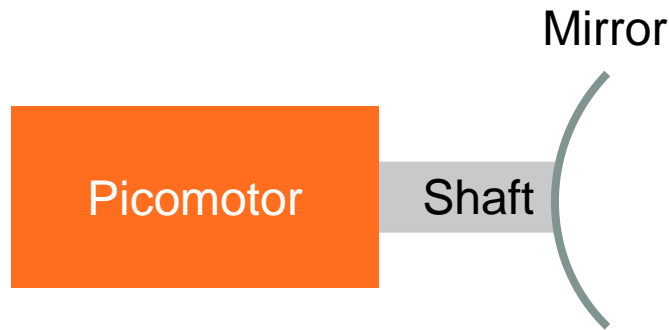
- **Implement wireless communication protocol** between mirrors and camera
- Monitor device health using thermal sensors

Task III: Hardware

- Manufacture **reliable encoder**

Mirror Actuation

- Each mirror controlled by **3 picomotors**
- Each DM additionally controlled by **41 electrodes**
- Use **picomotors** to enable **tip, tilt and piston motion** for the rigid and deformable mirrors



Forward Step

$$\Delta z = 28\text{nm} \pm 6\text{nm}$$

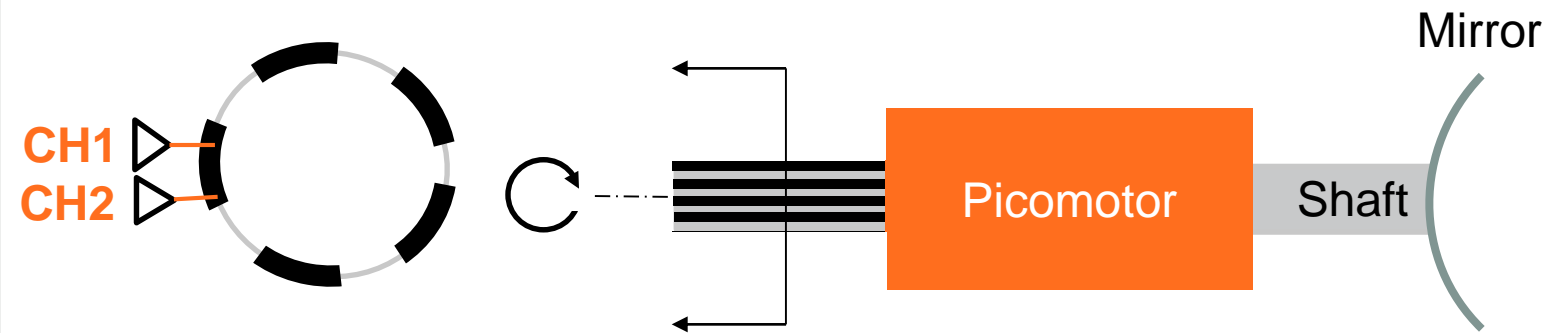
Backward Step

$$\Delta z = -40\text{nm} \pm 8\text{nm}$$

- Picomotor behavior is a **stochastic process**.
- How to **estimate** shaft head location?

Need for Encoders

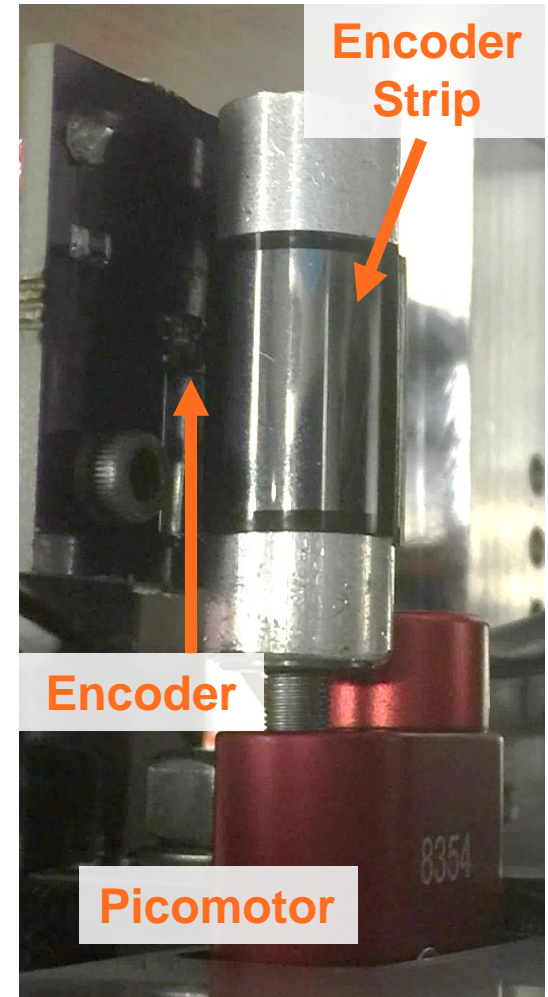
Encoders help estimate mirror position within an interval



Challenges with Encoder

Encoder Strip

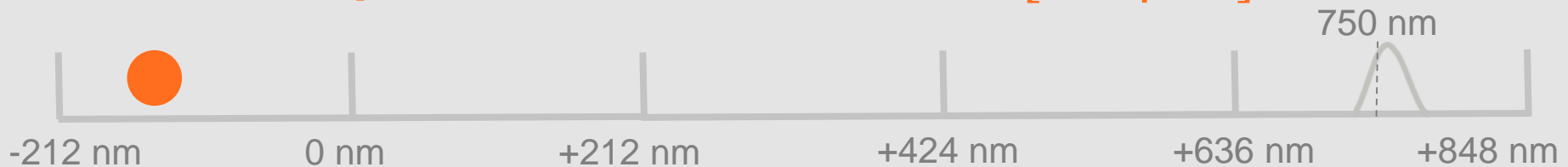
- Encoder strip (right) tailored to use on **flat surfaces**
- Consisting of **3 layers** → glossy top layer **delaminates** upon curving
- **Previous solution:** Tested position estimation algorithms in a **simulator** using Google Testing Framework
- **Permanent solution:** Achieved curvature at **elevated temperatures**



Final Result

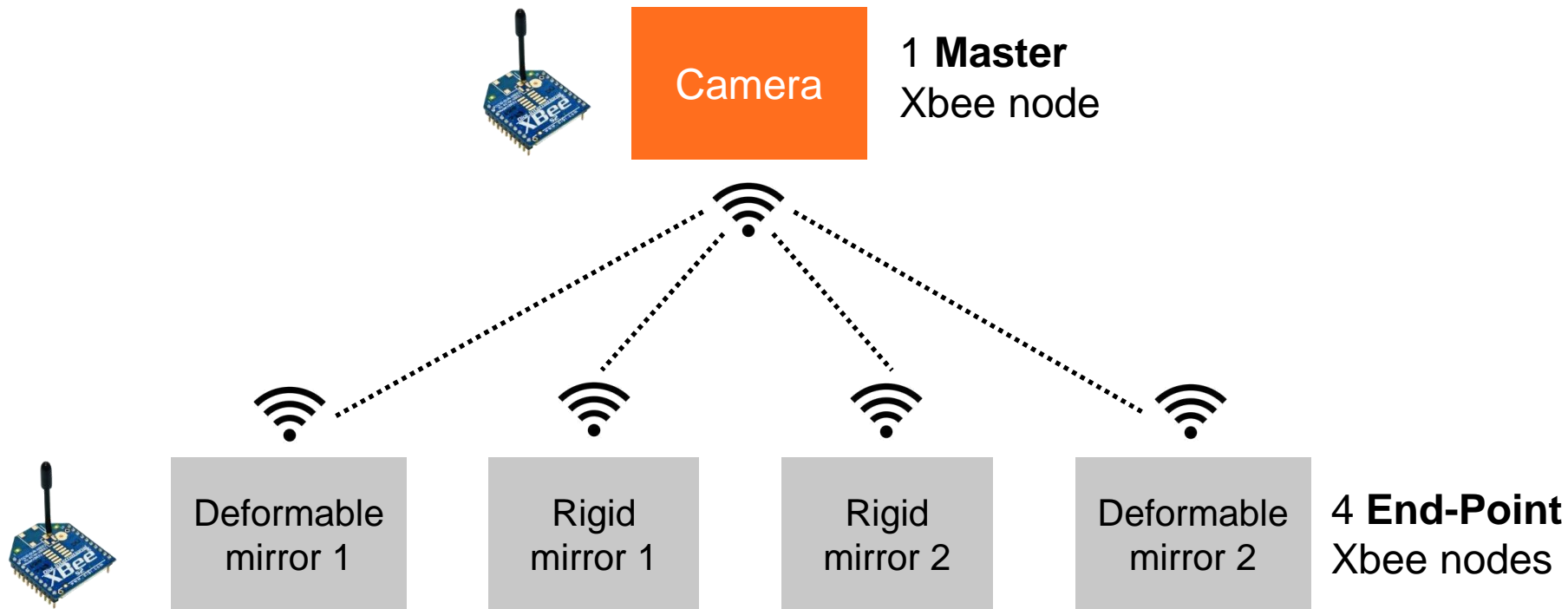
- **Step 1:** Exact position unknown → **Calibrate** encoder
- **Step 2:** Receive **desired location** from camera team
→ calculate how many **interval-jumps** to be made
- **Step 3:** Adjust for stochastic variation to minimize RMS error in a **deterministic way**
→ **calculates** no. of **picomotor steps** needed

Desired Displacement: 750nm **Move** $\lceil \frac{750}{212} \rceil + 3$ **Intervals**

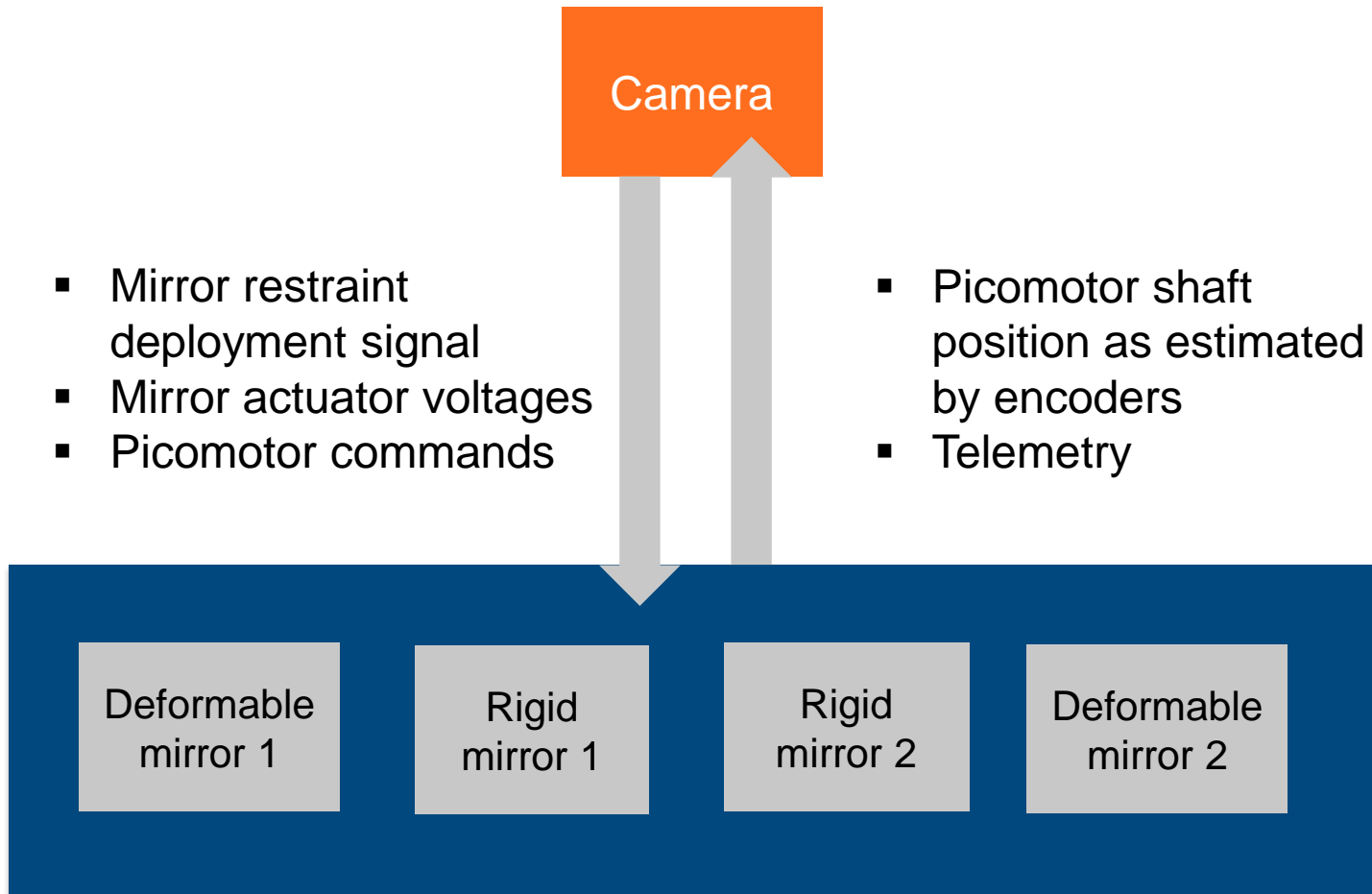


Wireless Communications

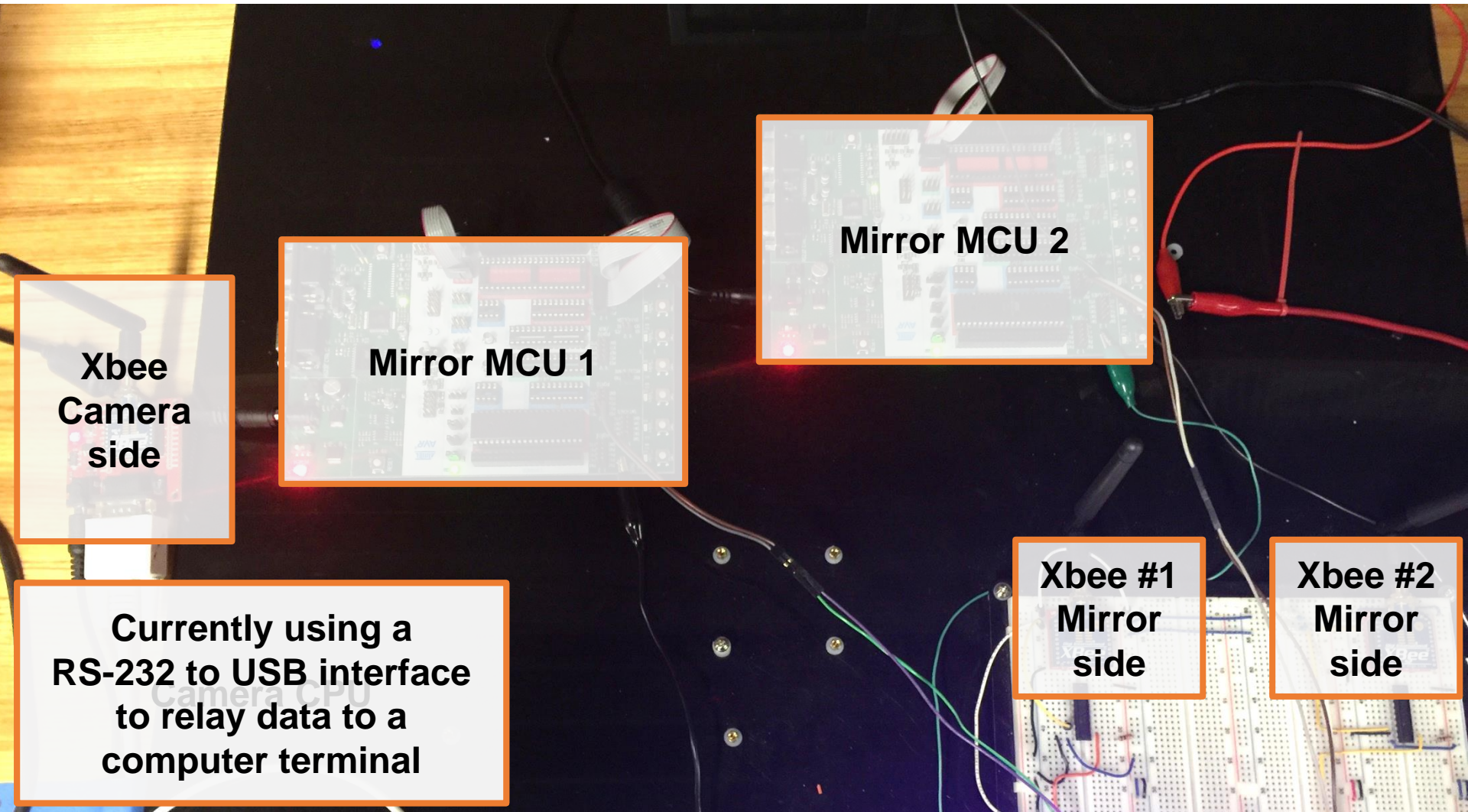
Objective: Establish a robust **Wireless communication** system between the **Mirror MCUs** and **Camera CPU** using **Xbee** wireless radio modules



Xbee Communications



Xbee Communications Testbed



Xbee Communications

- Communication packets:

0x05	0xA7BB01
1 byte address	3 bytes of data

- Application Programming Interface (**API**) mode enables **data verification**, **checksums** and **point-to-point** communication
- Interface Control Document (**ICD**) created to explain message types and protocol
- Current progress:** Two-way communication established between 1 Master Xbee and 2 End-Point Xbee modules

Hardware Monitoring

MCU's connected hardware

- Thermal Sensors
- High Voltage Board

Why read off temperature?

- Hardware could overheat
- Temperature monitoring required for thermal control

Needs **protocol to communicate** with MCU (ATMega 1284):

- Inter-Integrated Circuit (**I2C**)
- Serial-Peripheral Interface Bus (**SPI**)

Caution: protocols require **robust error handling** [e.g. due to other interfering communication processes]

Thermal Sensor Testing

Two thermal sensors [I2C]

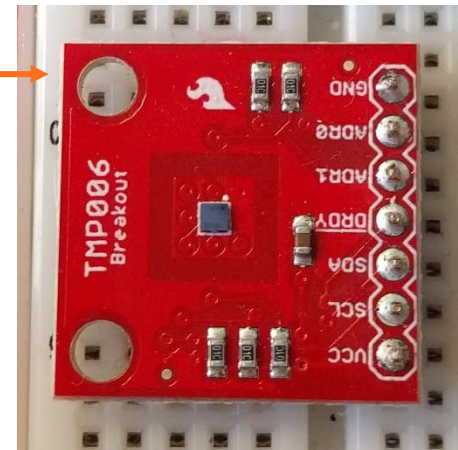
- MCP9801 [Conduction-based]
- TMP006 [Radiation-based]

Testing

- Reliable testing difficult due to environmental conditions

Observations

- Currently require **contact** between thermal sensors and targets
- Need to **calibrate** sensor measurements



Results

Software-Level

- Implemented **algorithm** to lower RMS error under 40nm
- Tested **simulator** using **Google-Testing** framework
- Established **Xbee communication** between 1x master and up to 2x slaves
- Tested health monitoring via I2C with **thermal sensors**

Hardware-Level

- Manufactured a **reliable encoder** via heat treatment
- Tested **wireless picomotor** actuation

Future Work

- Actuate a **combination of 3 picomotors** to achieve **tip, tilt and piston** functionality
- Test **calibration** and position **estimation** using picomotors
- Integrate **4 End-Point Xbee modules** and **implement protocol** for messages
- **Close the loop** to demonstrate camera image correction using picomotor actuation

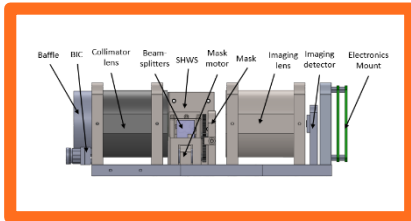
AAReST OBSW: Camera

Outline

1. Background & Motivation
2. Task Overview & Progress
3. Hardware Constraints
4. Future Work

Camera Hardware

Cameras

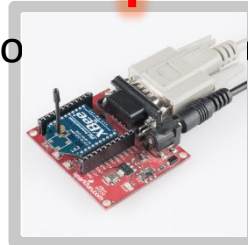


Flight CPU



Gro

Xbee

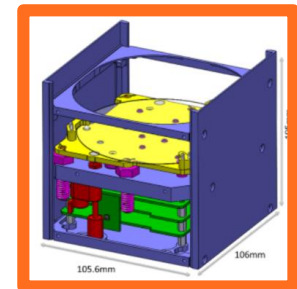


Other electronics
(temperature sensor,
power
management,...)

Eight Test Configuration



Mirror Boxes



Camera Task Overview

Task I

- Implement and improve spot centering algorithm
- Establish bidirectional communication with mirrors
- Test all functionality

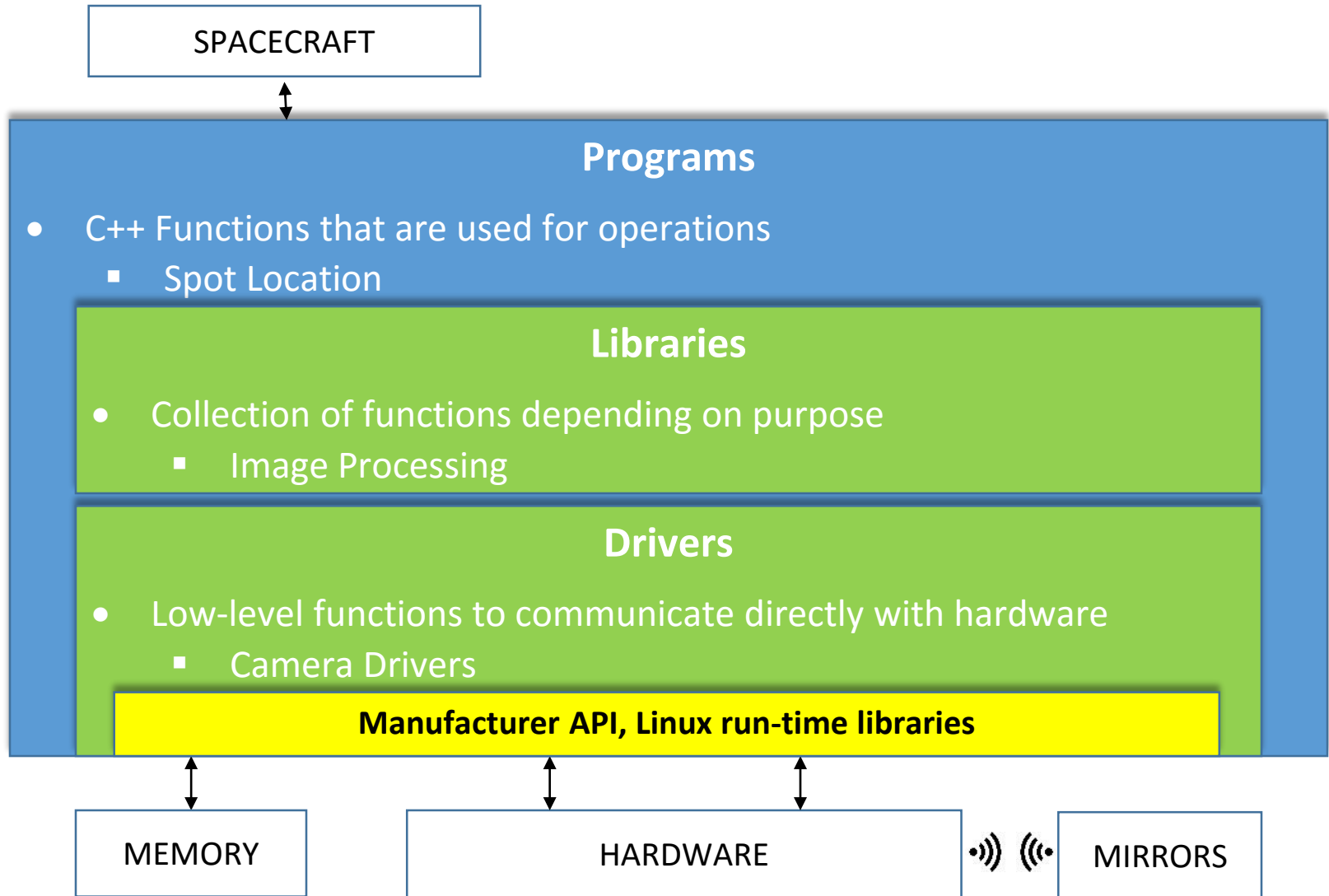
Task II

- Design and test hardware monitor functions

Task III

- Design and test shape correction algorithms

Software Architecture



Testing Environment

OBSW Testing & Verification

- Google Test Framework
 - Overarching testing environment

Test Scripts

- Scripts that test functionality of code
 - Test all possible use cases
 - Use cases derived from Interface Control Documents

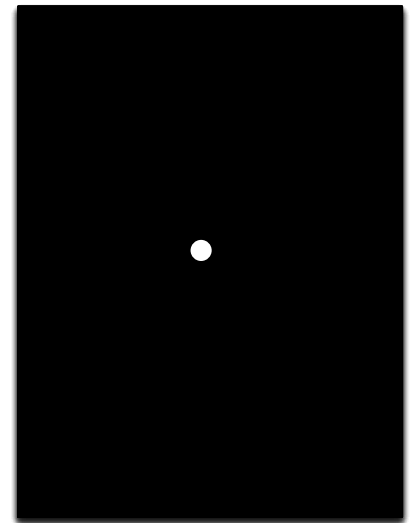
Programs

- List of functions that are used during operations

Task I: Centering Algorithm Introduction

AAReST has four mirrors

- Two rigid, two deformable
- Upon deployment, telescope needs to be aligned
 1. Calibrate picomotor motion via spot displacement
 2. Align optical axes of rigid mirrors
 3. Align optical axes of deformable mirrors
 4. Final iteration



Task I: Centering Algorithm Development

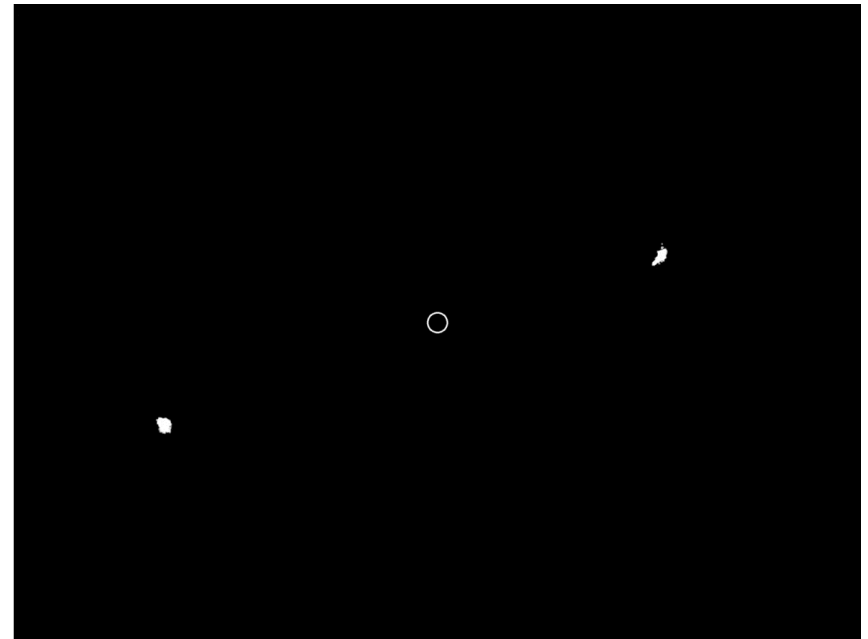
Designed and wrote software to:

- Take images
- Filter images
- Locate and track spots on sensor
- Send actuation commands to the mirrors
- Implement error handling

Generated Interface Control Documents (ICD)

- Clearly defines software interface and functionality

Demonstration in lab

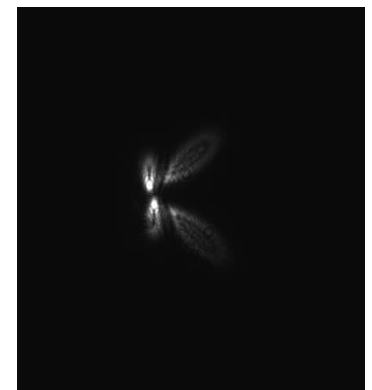
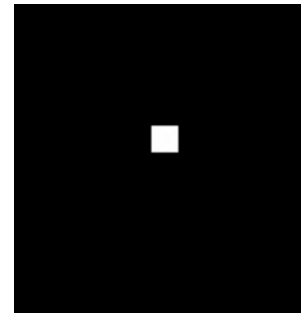


Note: Spots are from saturated laser source. These are much larger than expected in flight.

Task I: Centering Algorithm Testing

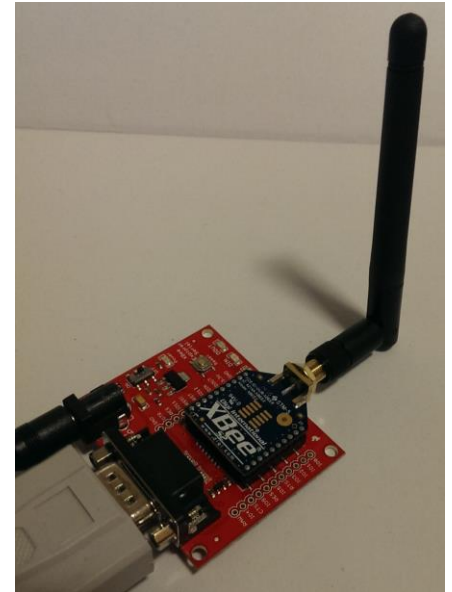
Tested spot location and tracking algorithms:

- Tested expected cases
 - 4 normal spots
 - Square-shaped spot
- Tested fringe cases
 - Spot on the edge
 - Defocused image (expected in space)
- Resolved encountered bugs
 - All tests now passed



Task I: XBee Communications

- Wrote drivers for Xbee communication between flight CPU and mirror MCUs
 - Implemented as C++ class using the open source C library libxbee
- Designed and implemented communication software
 - Used communication protocol set by mirror software team
- Tested and verified wireless communication link with mirror MCU
 - Verified data exchange by C program



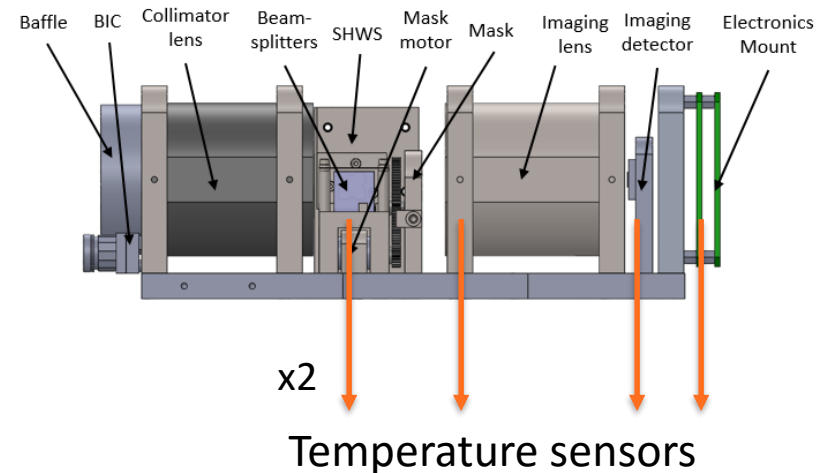
Task II: Hardware Monitoring

Software

Hardware health needs to be monitored

- 5 sites for temperature monitoring
 - External temperature sensors are accessed via I2C
- Implemented status monitoring for imaging camera
 - All parameters are accessed via camera API

Sensor position assigned by camera/electronics team



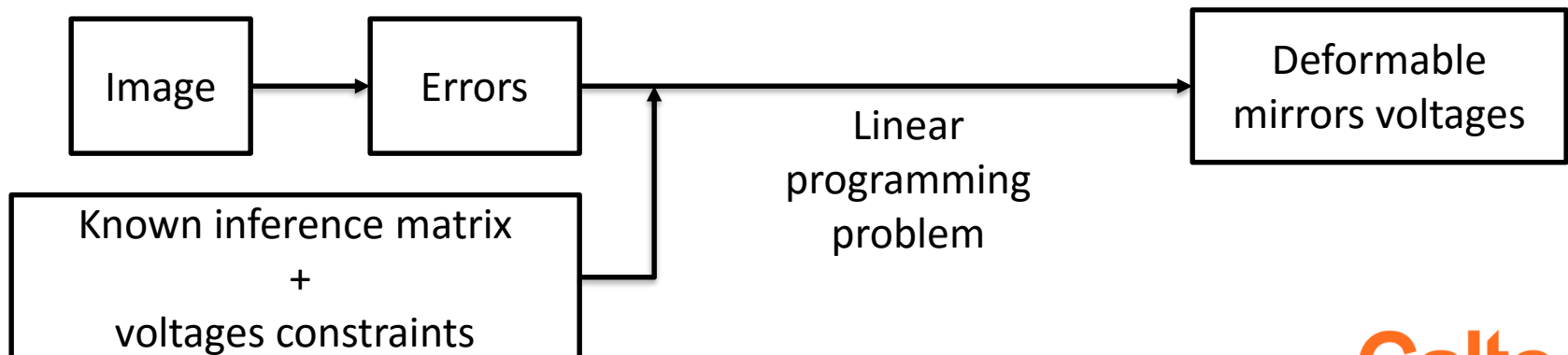
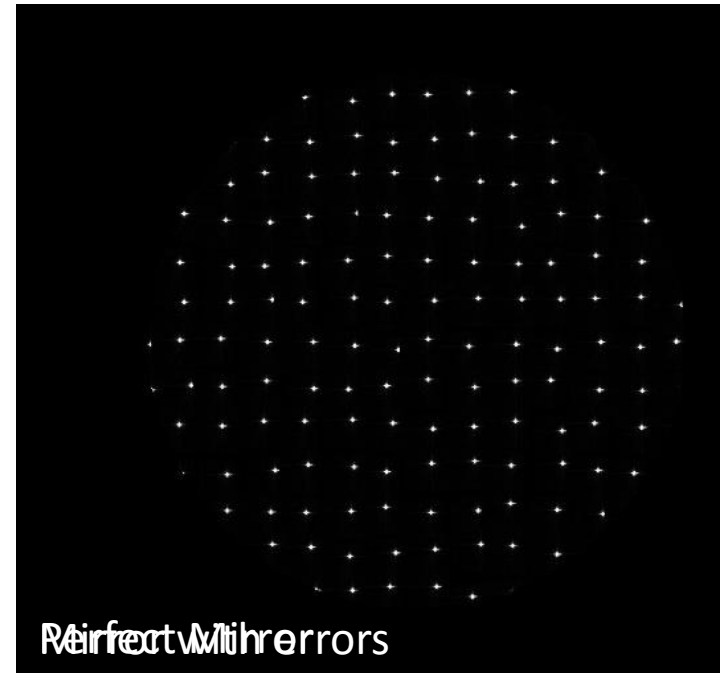
Task II: Hardware Monitoring Software Testing

Hardware error handling

- Ensure break in camera communication is properly handled
- Designed and implemented error handling function
 - Need to test by disconnecting camera during communication

Task III: Shape Correction Algorithm

- Use Shack-Hartmann wavefront sensors (SHWS)
- Given known effect for each deformable mirror + voltage constraint, compute required voltages to minimize voltages



Task III: Shape Correction Progress

- Provided with already written code
 - Get an image
 - Compute the errors
 - Solve the linear programming problem
- Updated to work with current code
- Wrapped into C++ Objects

Hardware Constraints

Shape correction algorithms tested with previously taken images

- Baumer camera unavailable for use
- Software test with SHWS under way

Software not yet tested with all four mirrors

- Lab currently has two rigid mirrors
- Deformable mirror still in development

Future Work

Durability tests

- Run camera for an extended period and ensure proper operation

Verify functionality of final centering algorithm

- Use four mirrors
- Test on flight hardware

Verify functionality of shape correction algorithms

- Perform unit-test with flight hardware



Acknowledgements:

- Thibaud, Yuchen, Kathryn

Questions?

Outline

2:00 pm: Introduction & Welcome

2:15 pm: Camera

2:45 pm: Boom

3:15 pm: Mirror Boxes

3:45 pm: On-board Software

4:15 pm: Electronics

AAReST Electronics Team

Andre Sukernik

Saumya Vij

Mentors

Ashish Goel

Stephen Bongiorno

AAReST Electronics

Camera
Saumya

Mirror Box
Andre

Mirror Box Electronics

Andre Sukernik

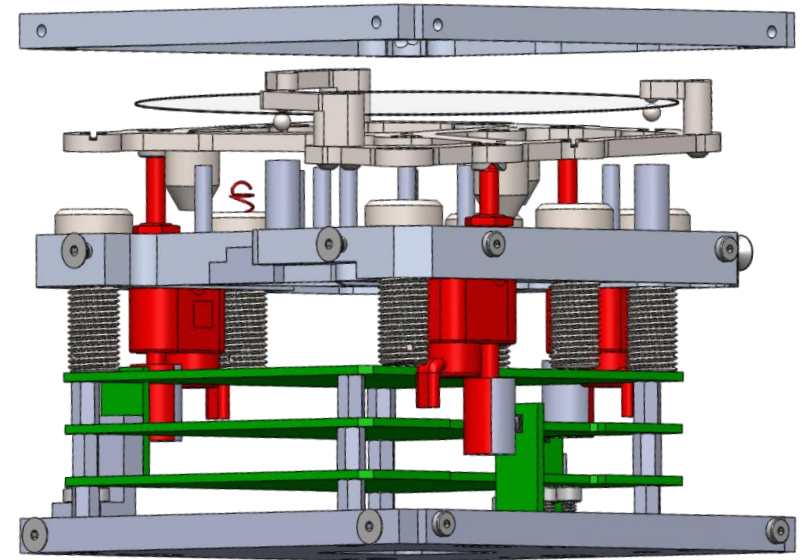
Mentors

Ashish Goel

Stephen Bongiorno

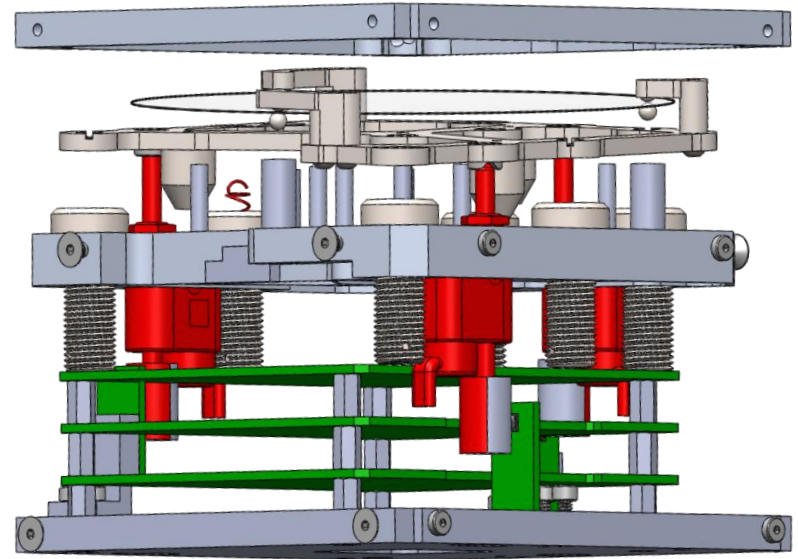
Outline

- System Overview
- Project Objectives
- Design Overview
- Printed Circuit Boards
- Schedule

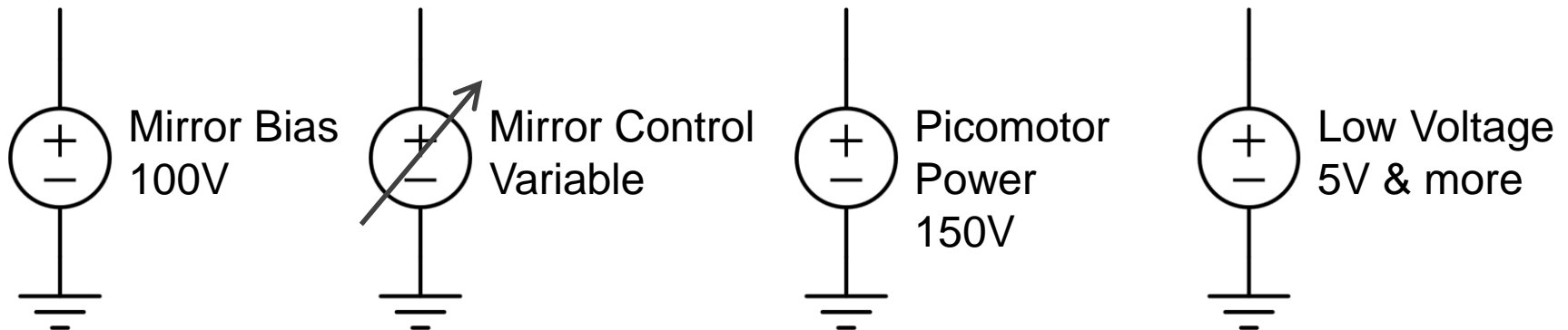


Outline

- ***System Overview***
- Project Objectives
- Design Overview
- Printed Circuit Boards
- Schedule



Mirror System Overview



Deformable Mirror Array Proof of Concept

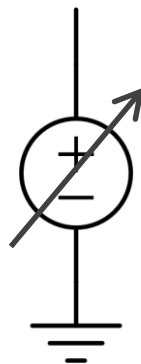
Mirror System Overview

Power
System

Drive
Picomotors



Mirror Bias
100V



Mirror Control
Variable



Picomotor
Power
150V



Low Voltage
5V & more

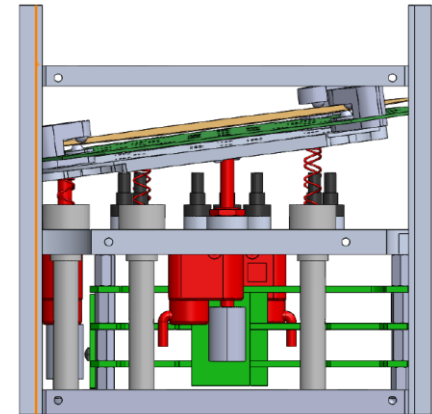
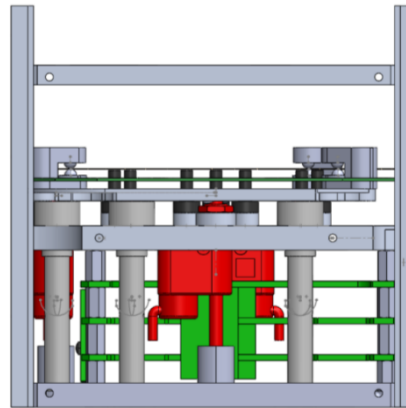
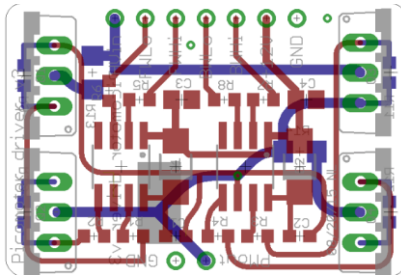
Deformable Mirror Array Proof of Concept

Mirror System Overview

Power
System

Drive
Picomotors

Driver Circuit x3



Deformable Mirror Array Proof of Concept

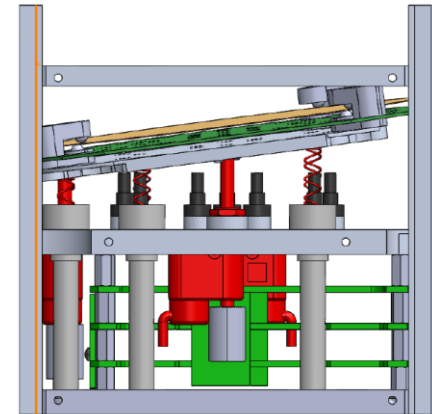
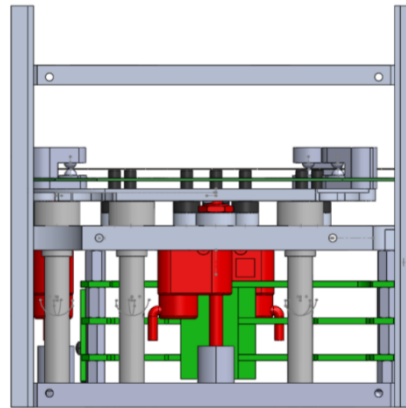
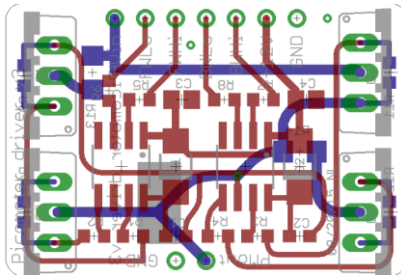
Mirror System Overview

Power
System

Drive
Picomotors

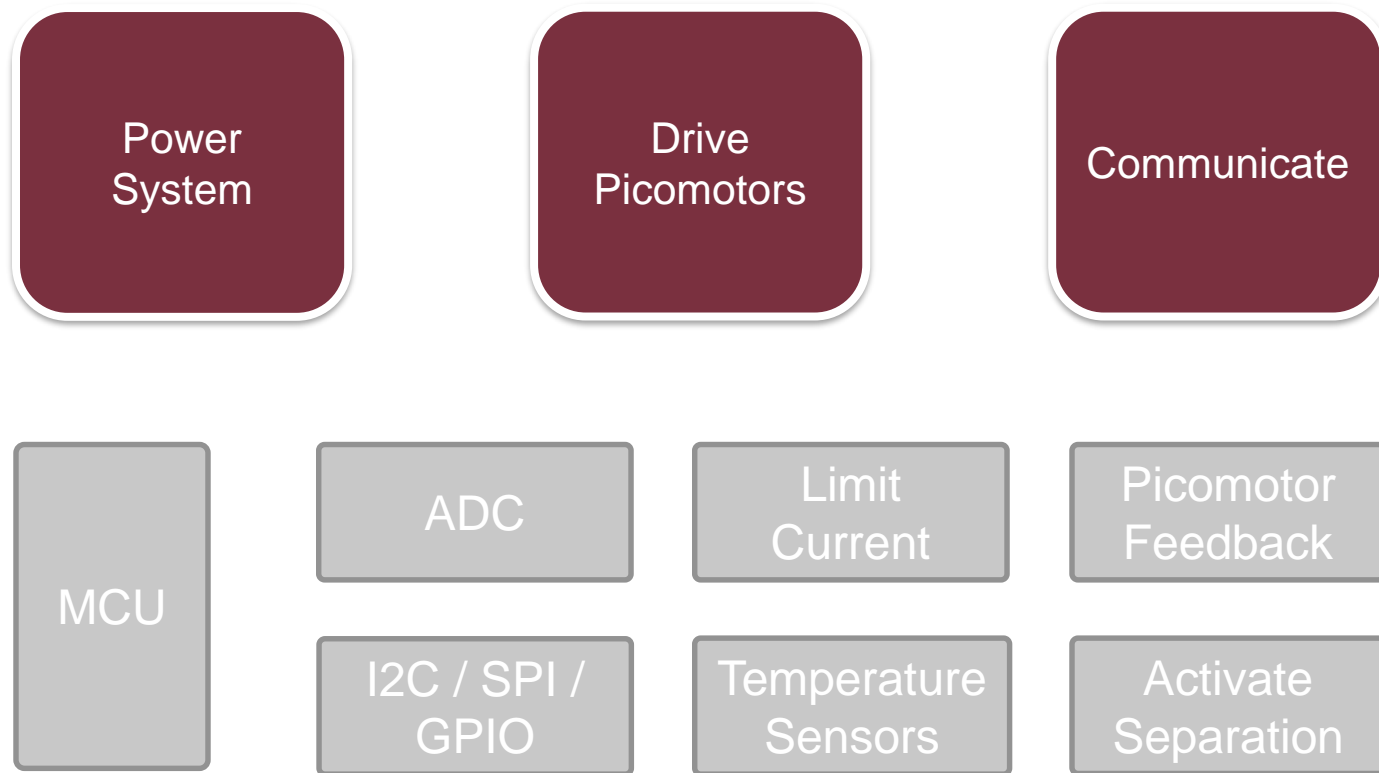
Communicate

Driver Circuit x3



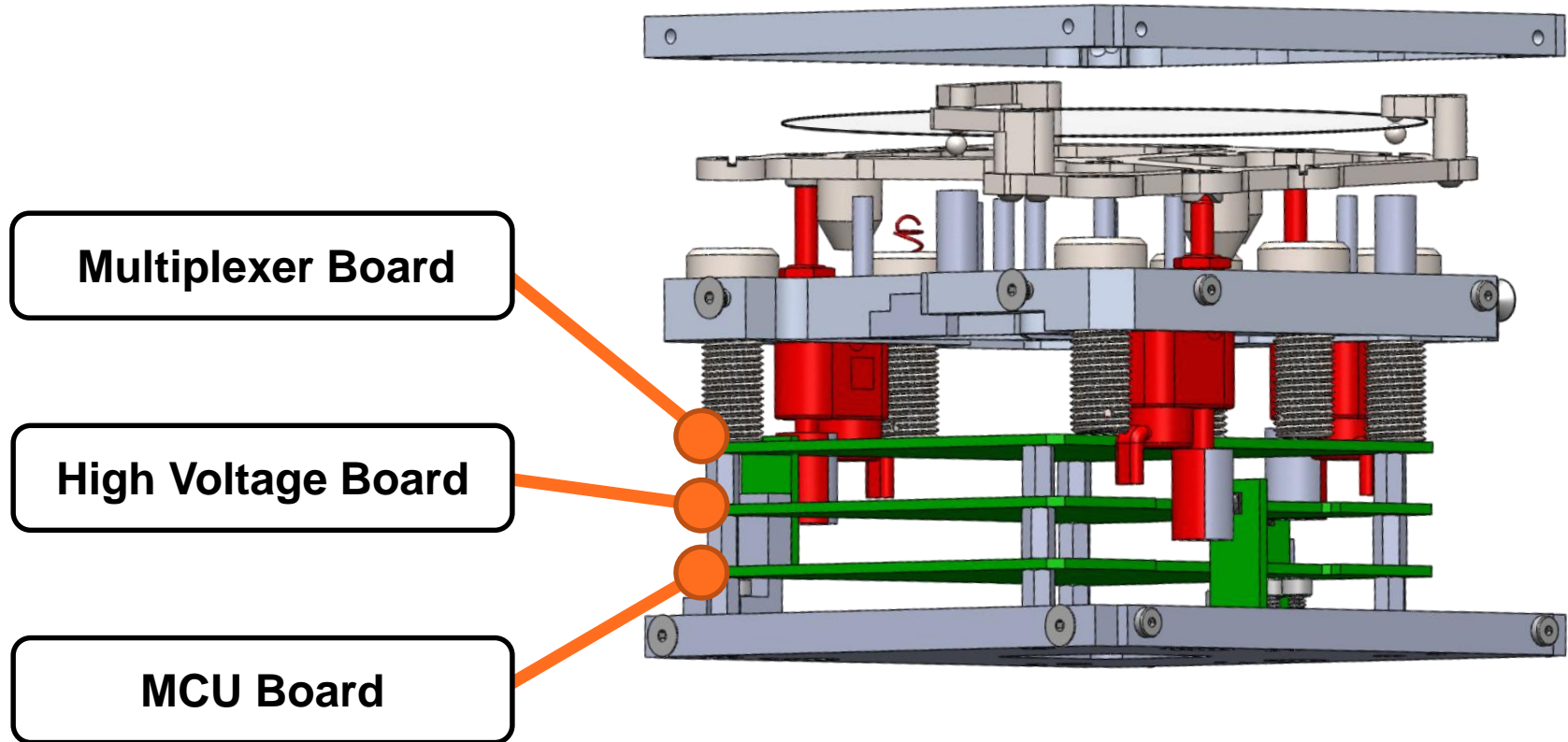
Deformable Mirror Array Proof of Concept

Mirror System Overview



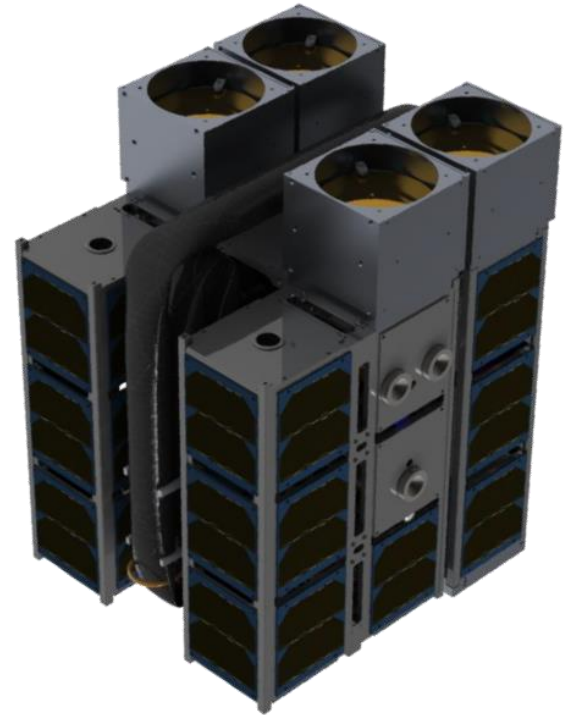
Deformable Mirror Array Proof of Concept

Mirror System Overview



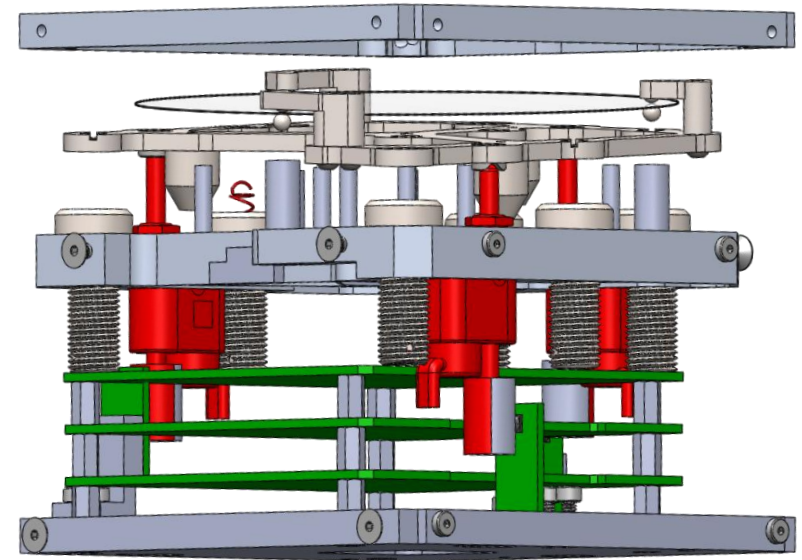
Project Objectives

- Select components
- Convert high level diagrams into detailed schematics
- Layout printed circuit boards
- Focus on 2 boards – High Voltage, MCU



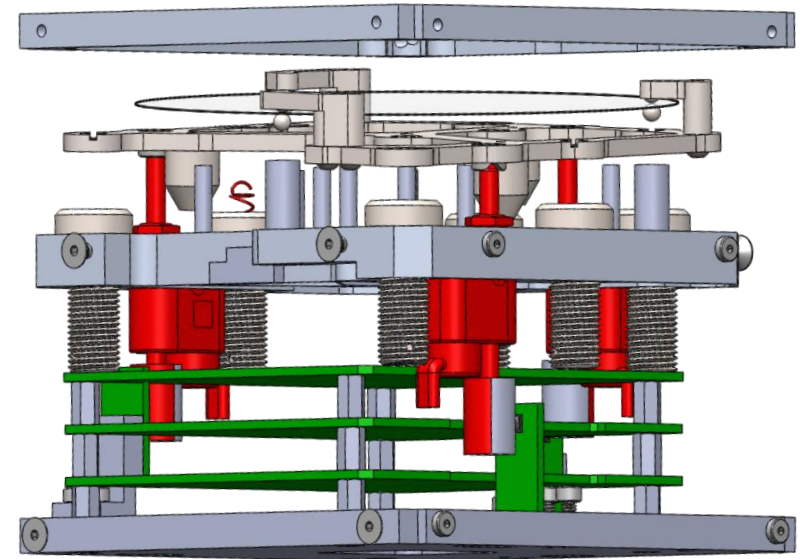
Outline

- System Overview
- ***Project Objectives***
- Design Overview
- Printed Circuit Boards
- Schedule

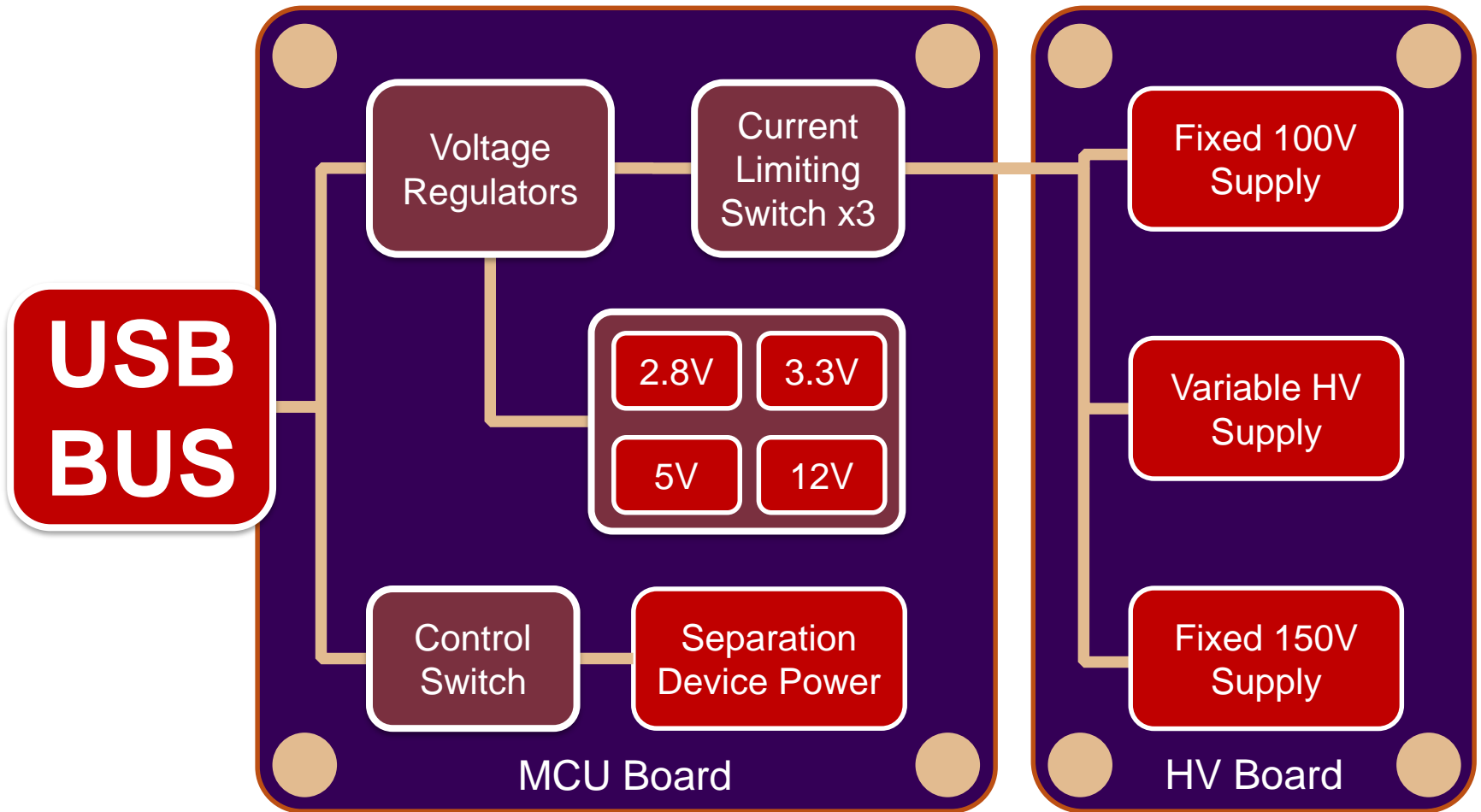


Outline

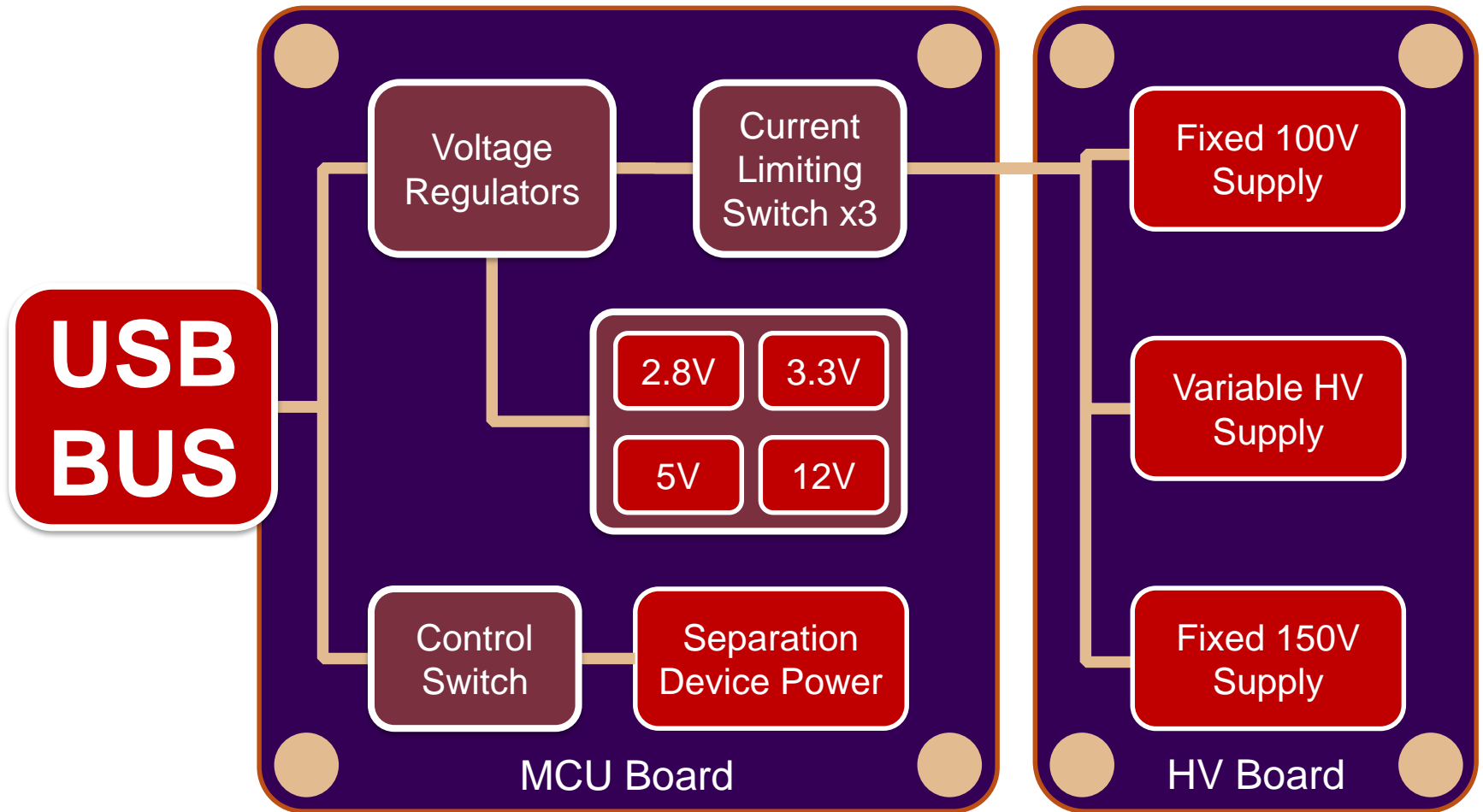
- System Overview
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- ***Design Overview***
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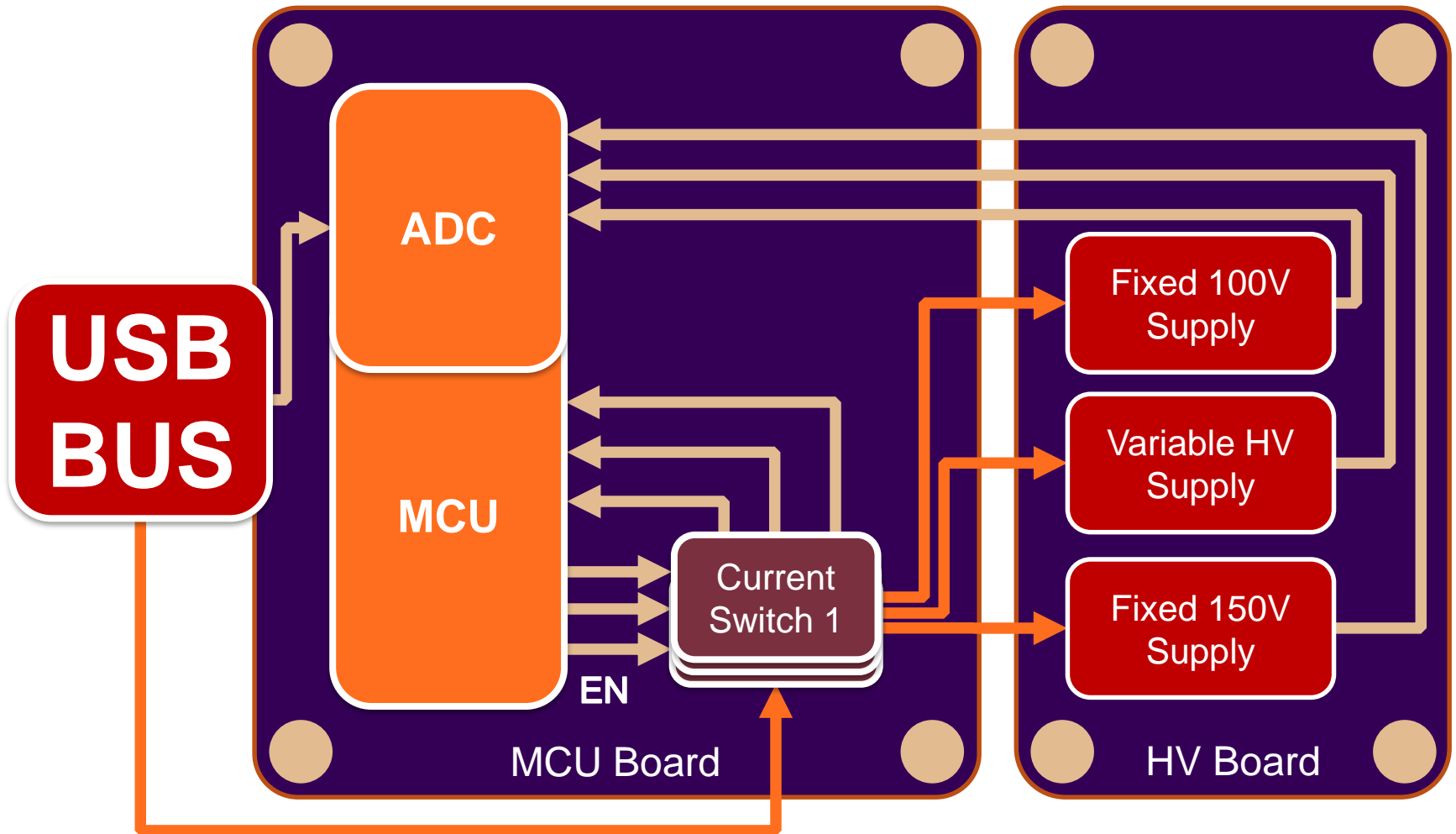
Power Distribution



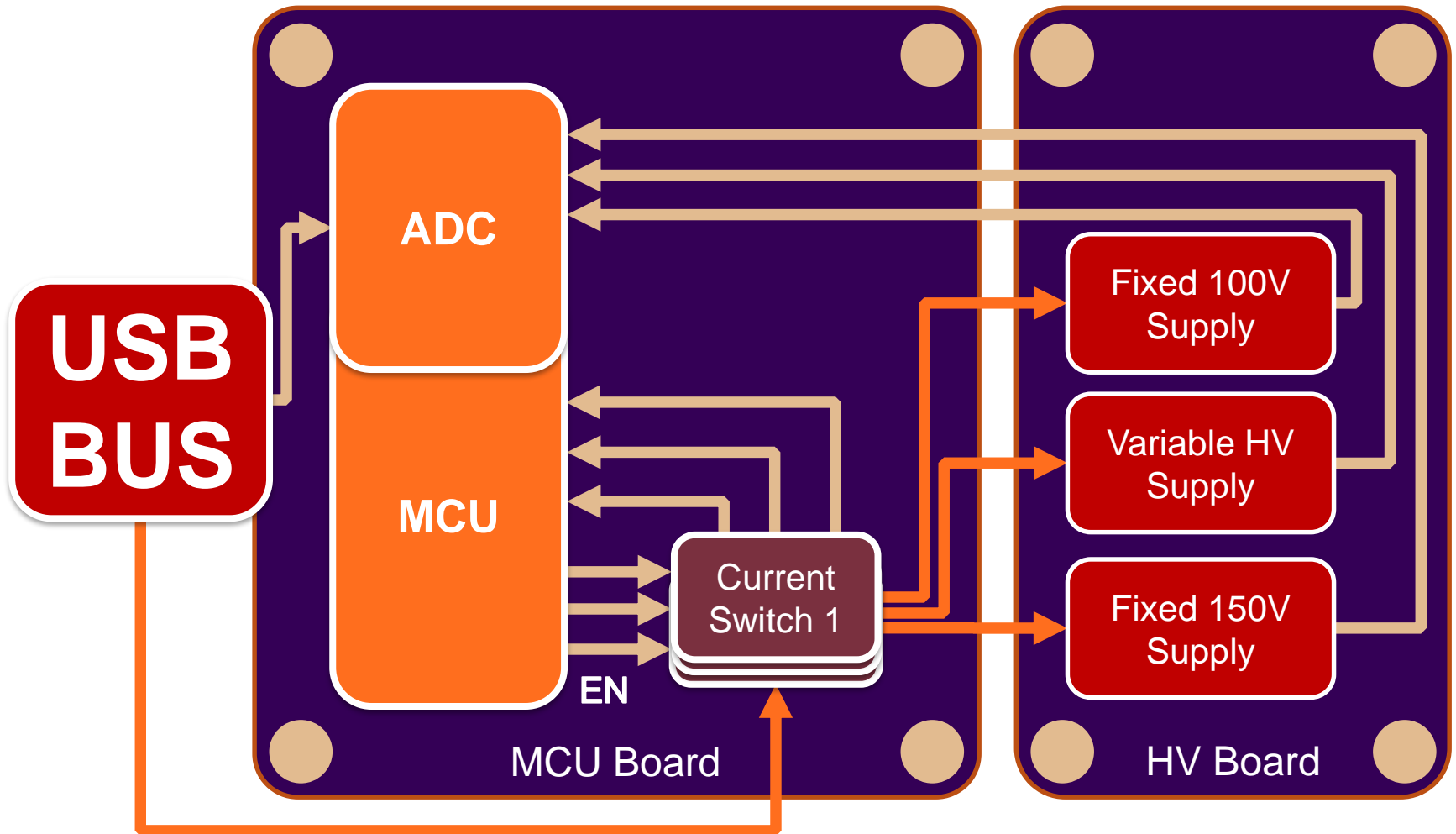
Power Distribution



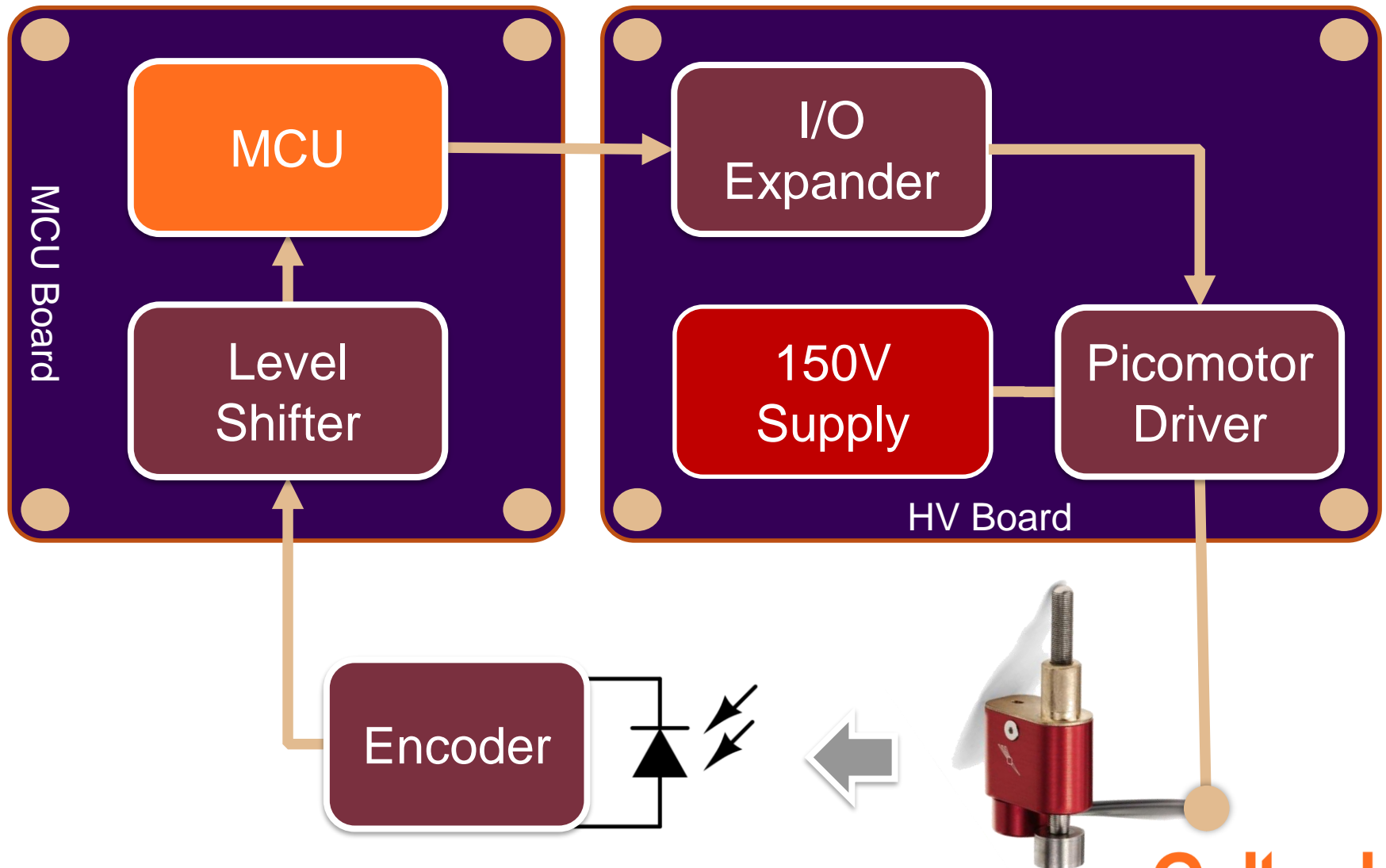
Power Control & Monitoring



Power Control & Monitoring

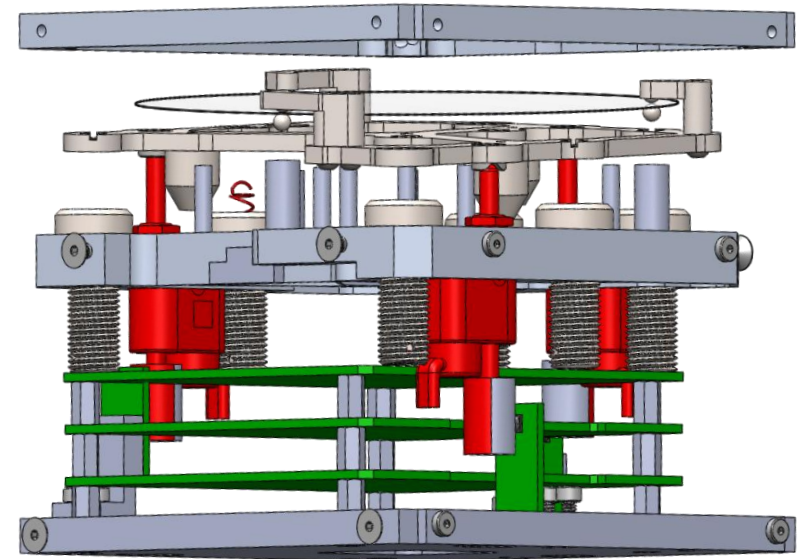


Picomotor Control



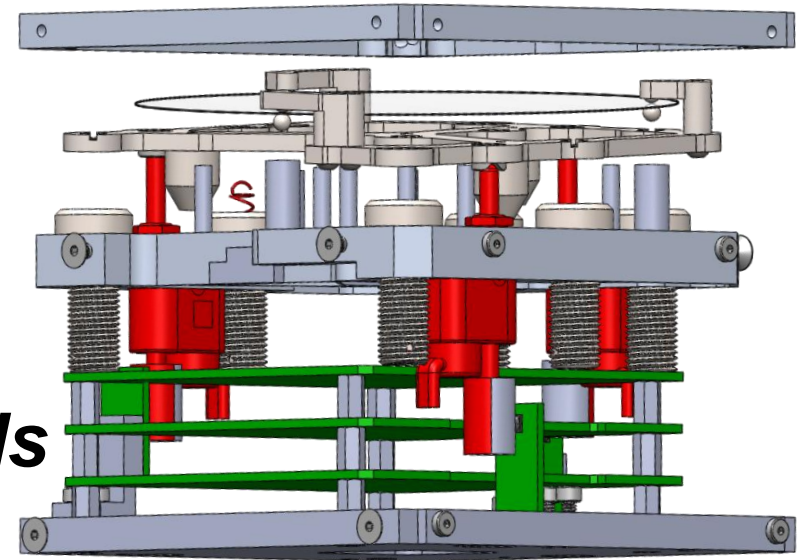
Outline

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- Project Objectives
- ***Design Overview***
- Printed Circuit Boards
- Schedule



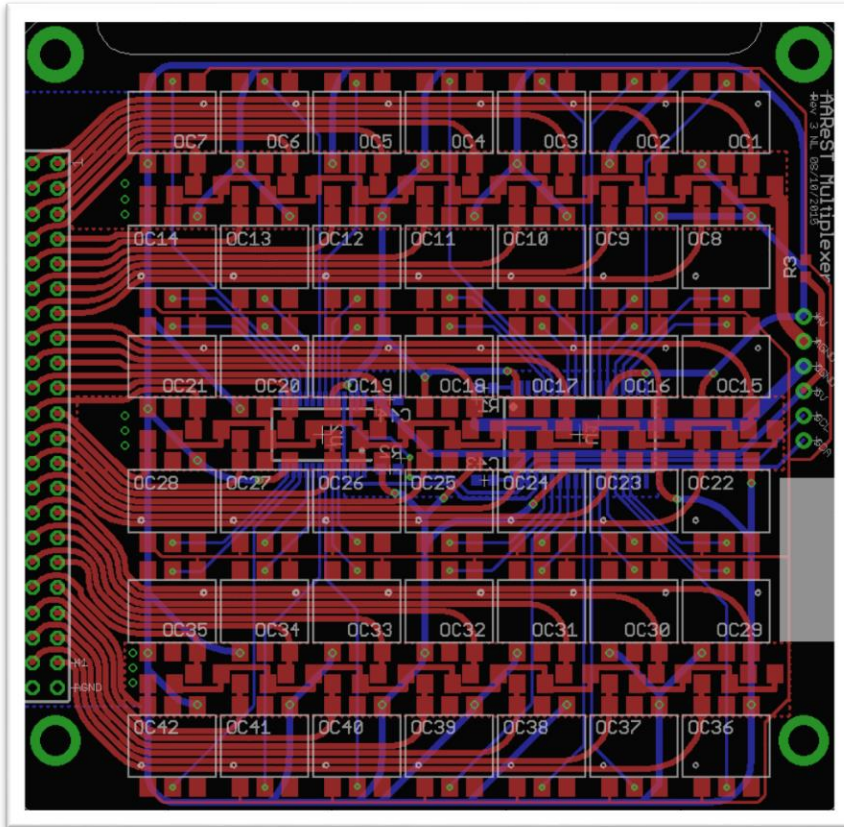
Outline

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- Project Objectives
- Design Overview
- ***Printed Circuit Boards***
- Schedule

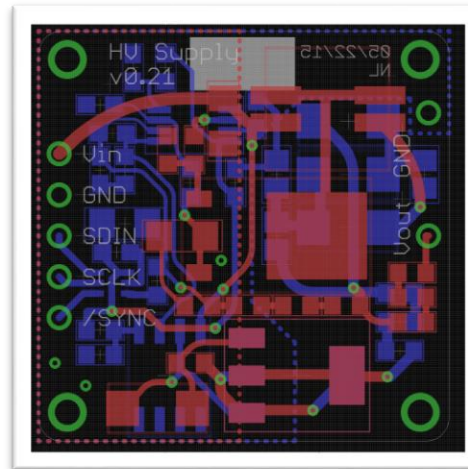


Existing Components

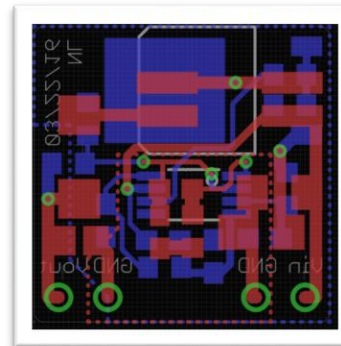
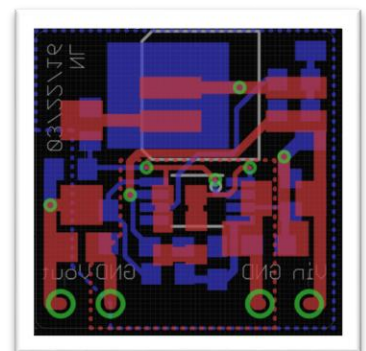
Multiplexer Board



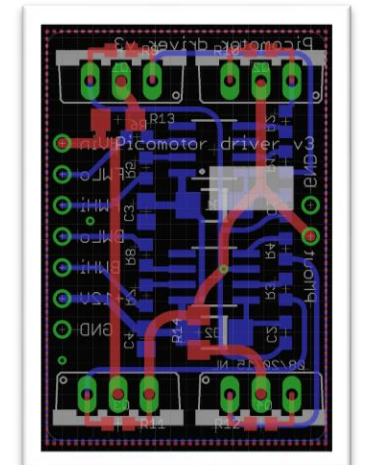
Variable Supply



150V Supply

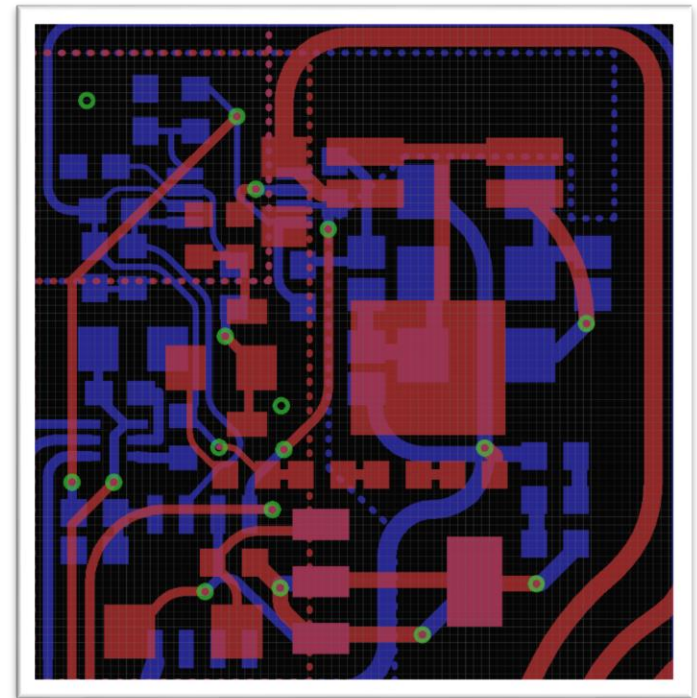
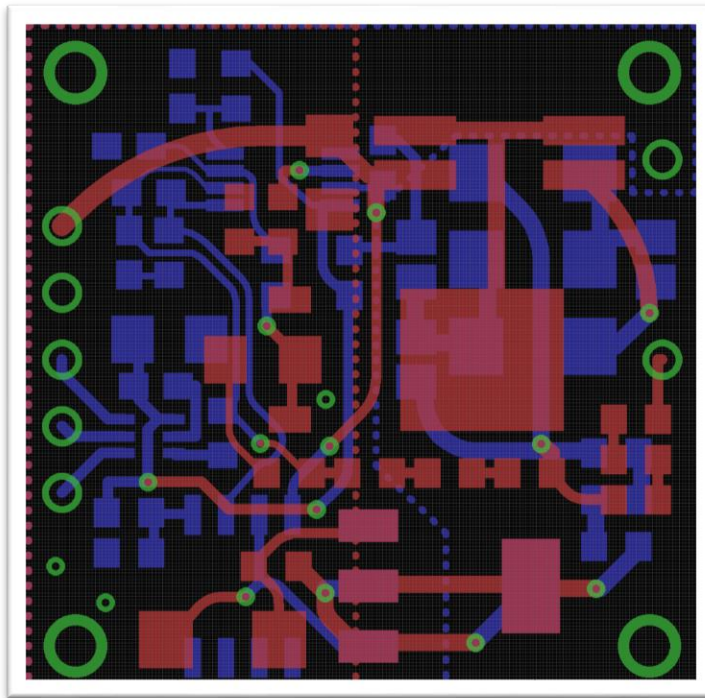


100V Supply



Picomotor Driver

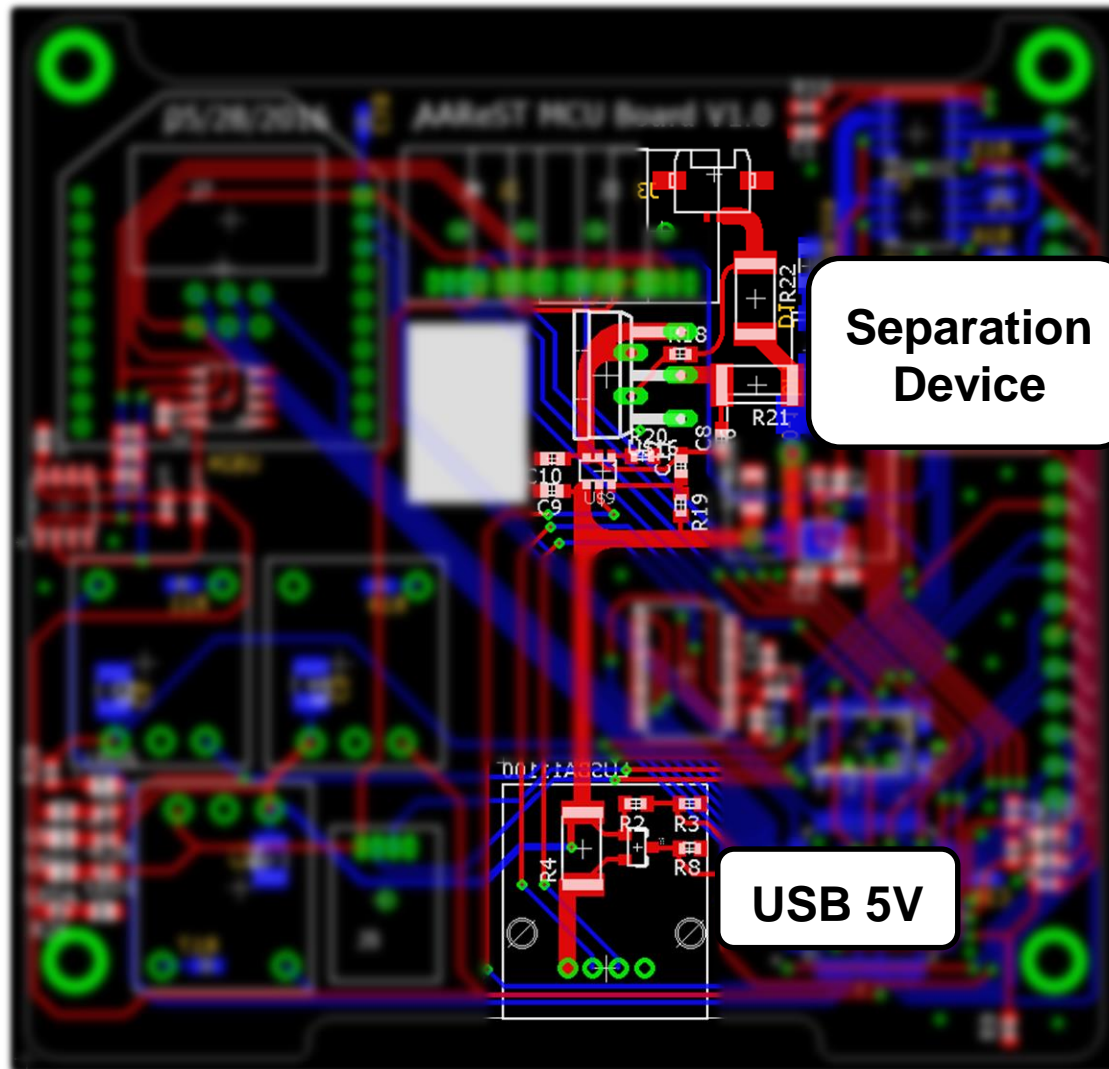
Component Adaptation Example



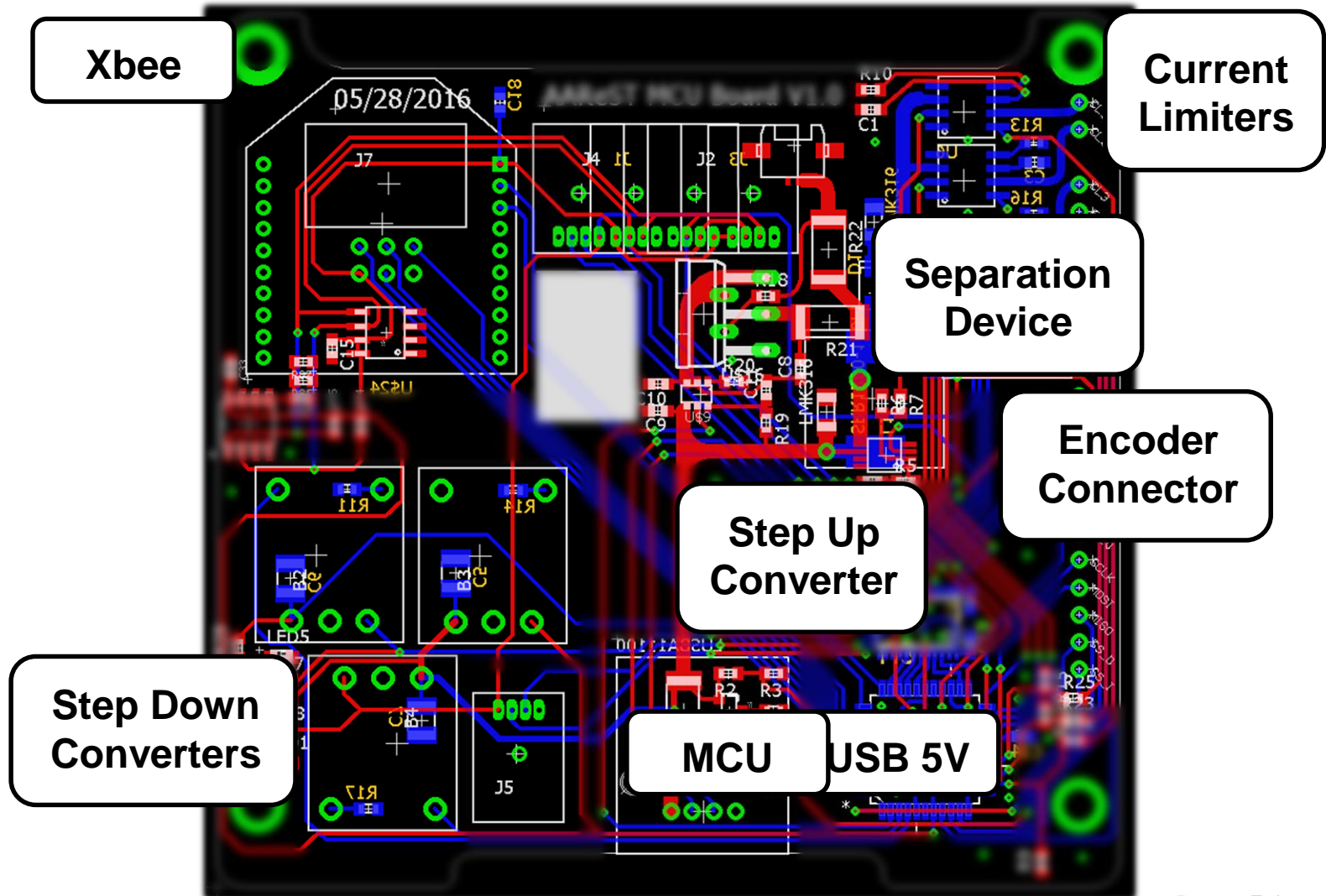
Variable Supply

- Remove mounting holes
- Add monitoring capability
- Minor functional changes

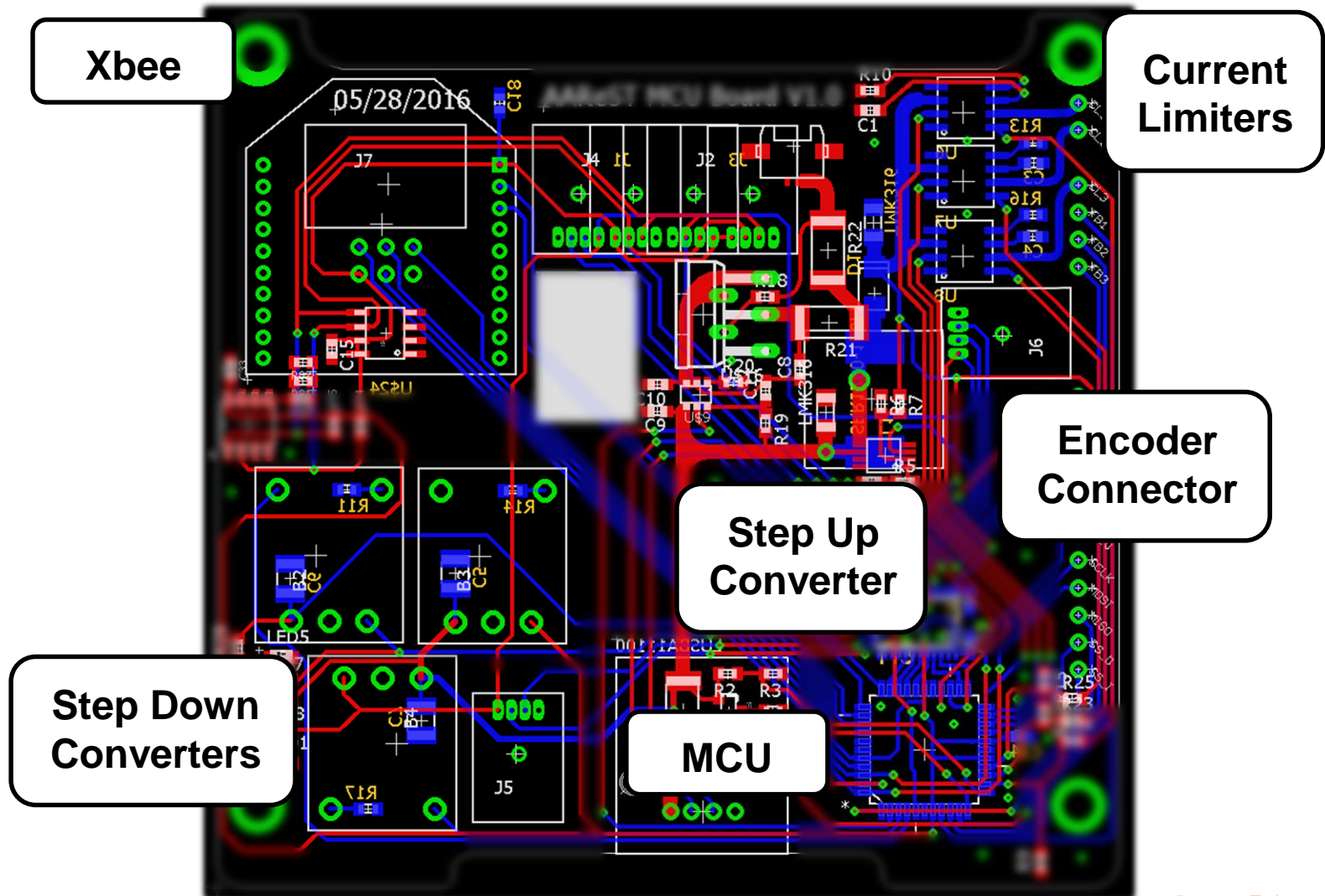
MCU PCB



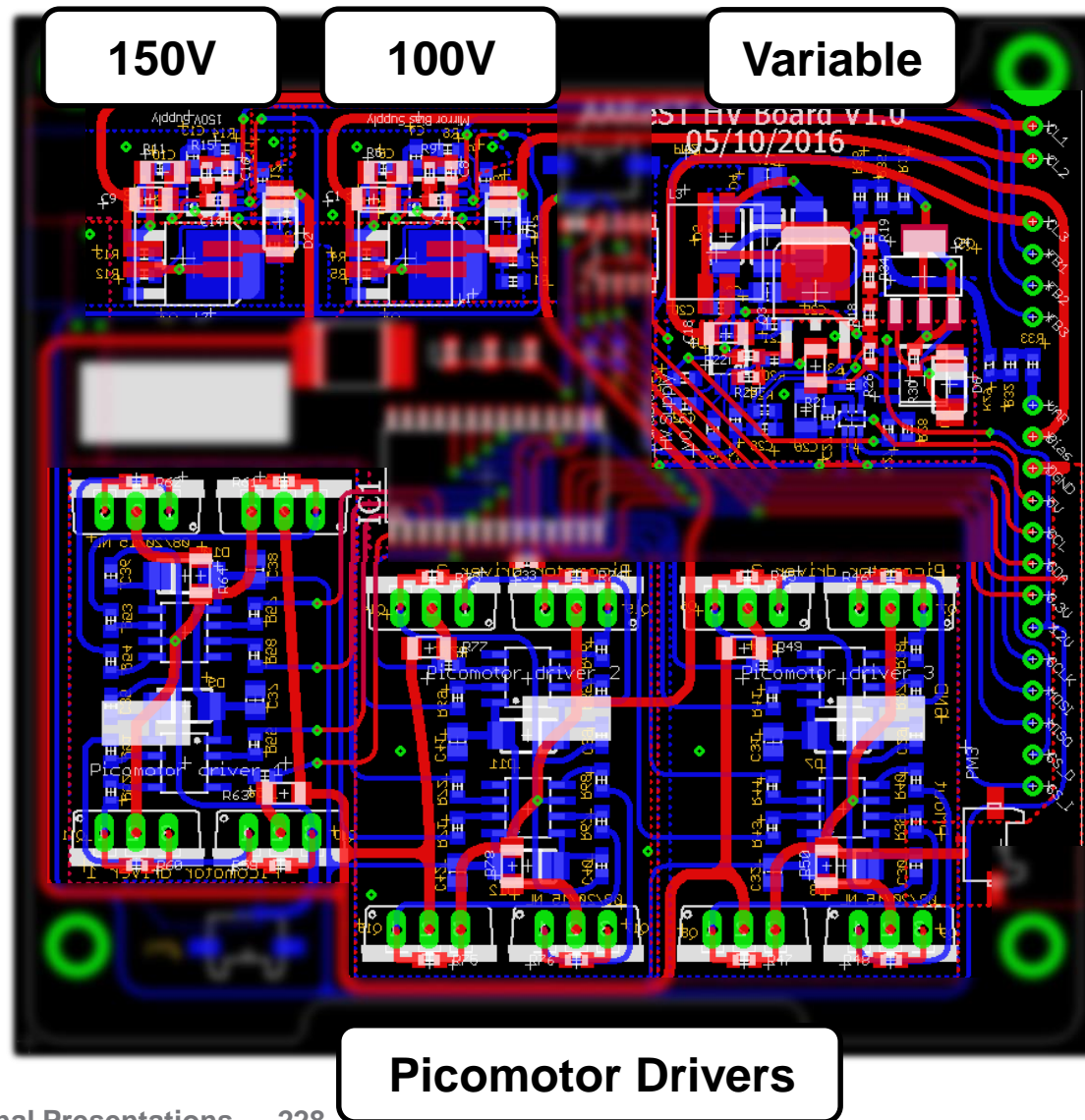
MCU PCB



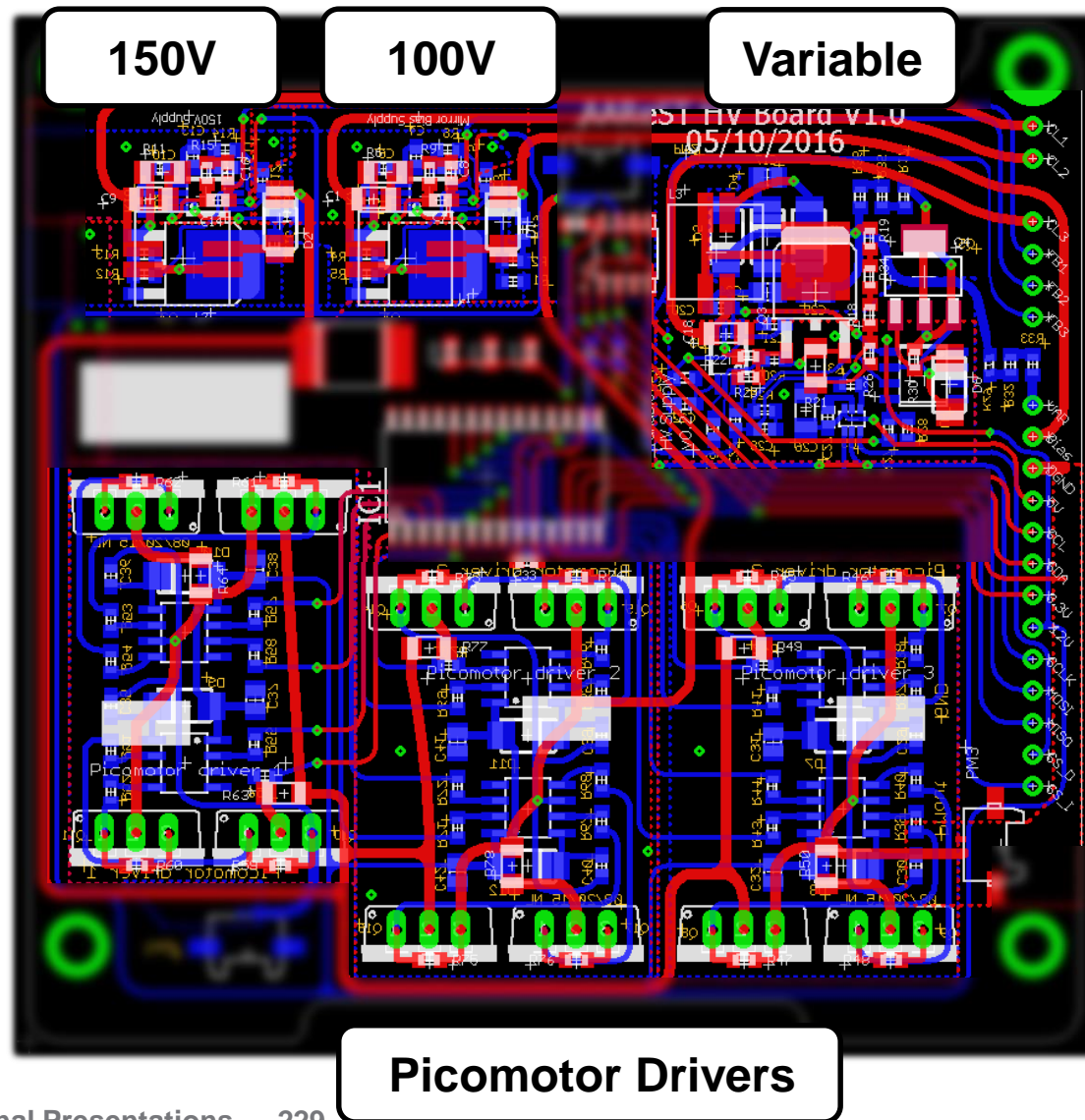
MCU PCB



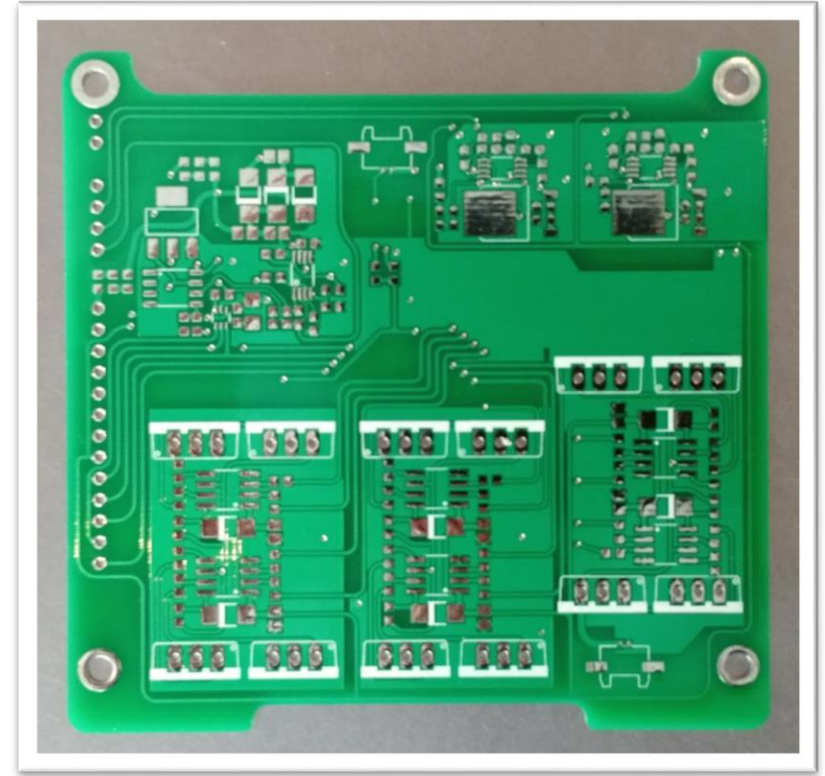
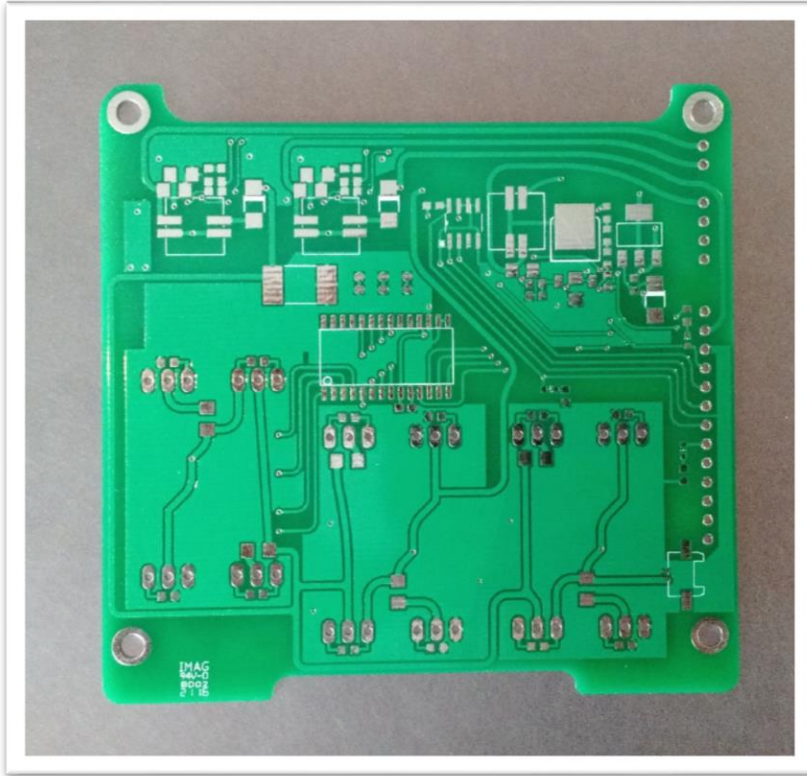
High Voltage PCB



High Voltage PCB

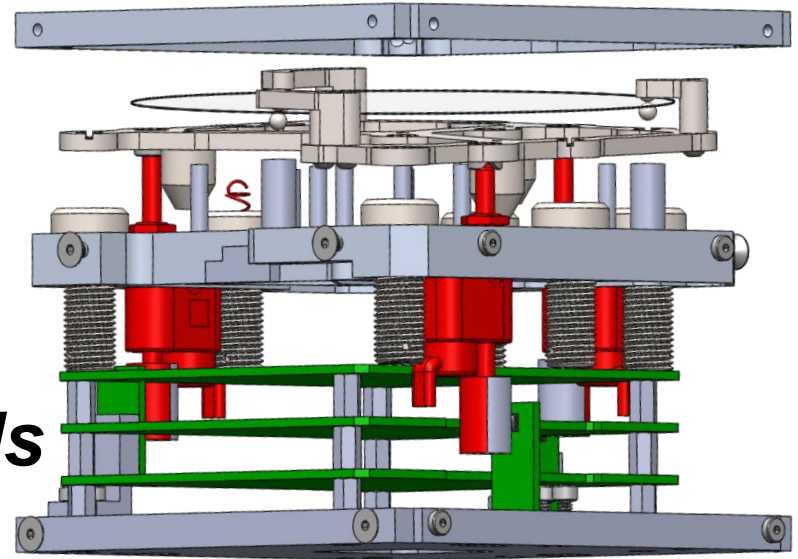


High Voltage PCB



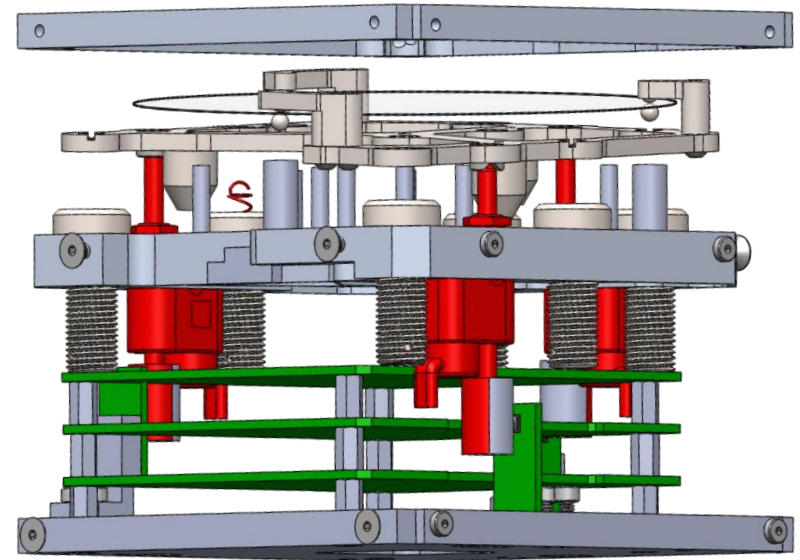
Presentation Outline

- System Overview
- Project Objectives
- Design Overview
- ***Printed Circuit Boards***
- Schedule

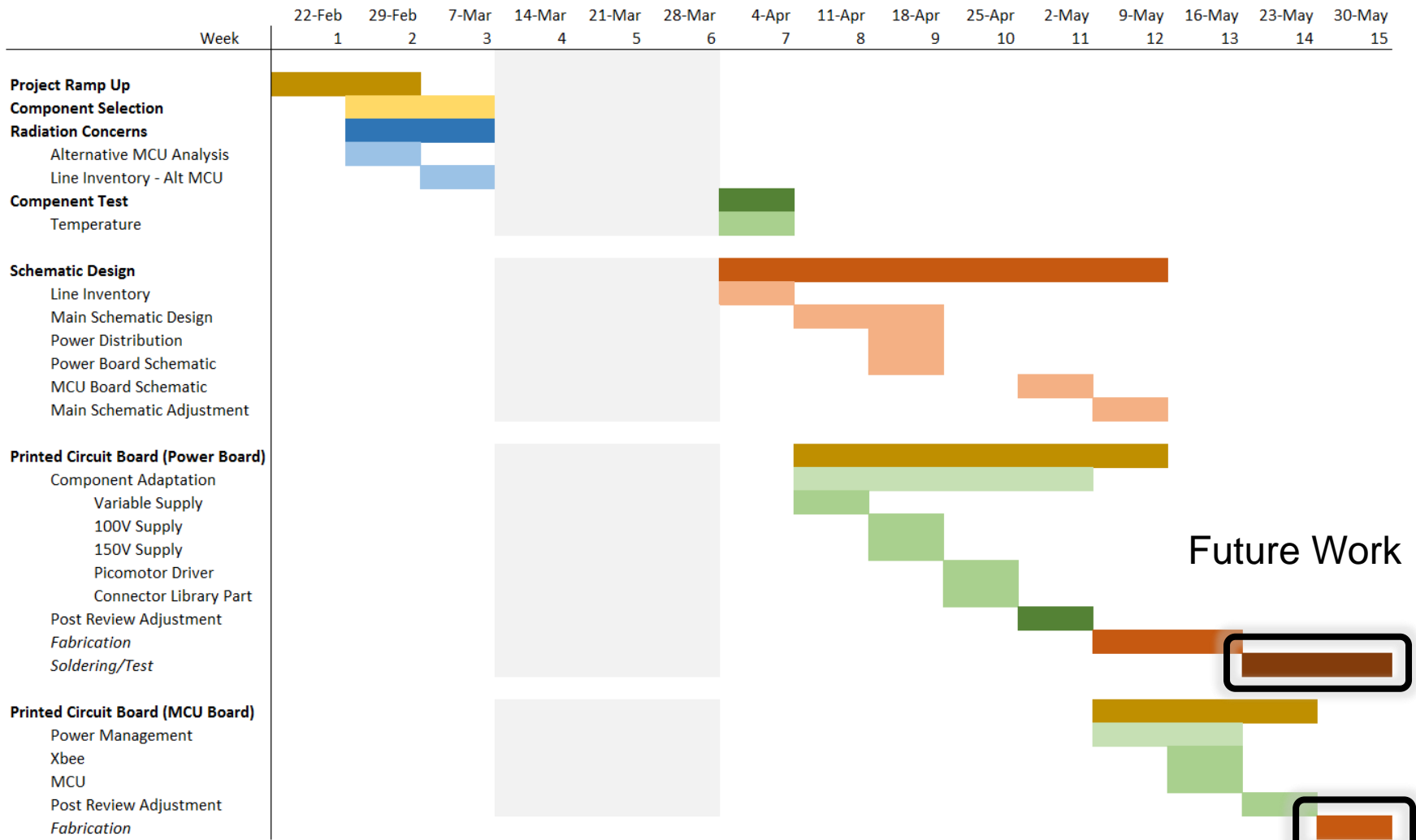


Presentation Outline

- System Overview
- Project Objectives
- Design Overview
- Printed Circuit Boards
- ***Schedule***



Schedule



Future Work

Camera Electronics

Saumya Vij

Mentors:

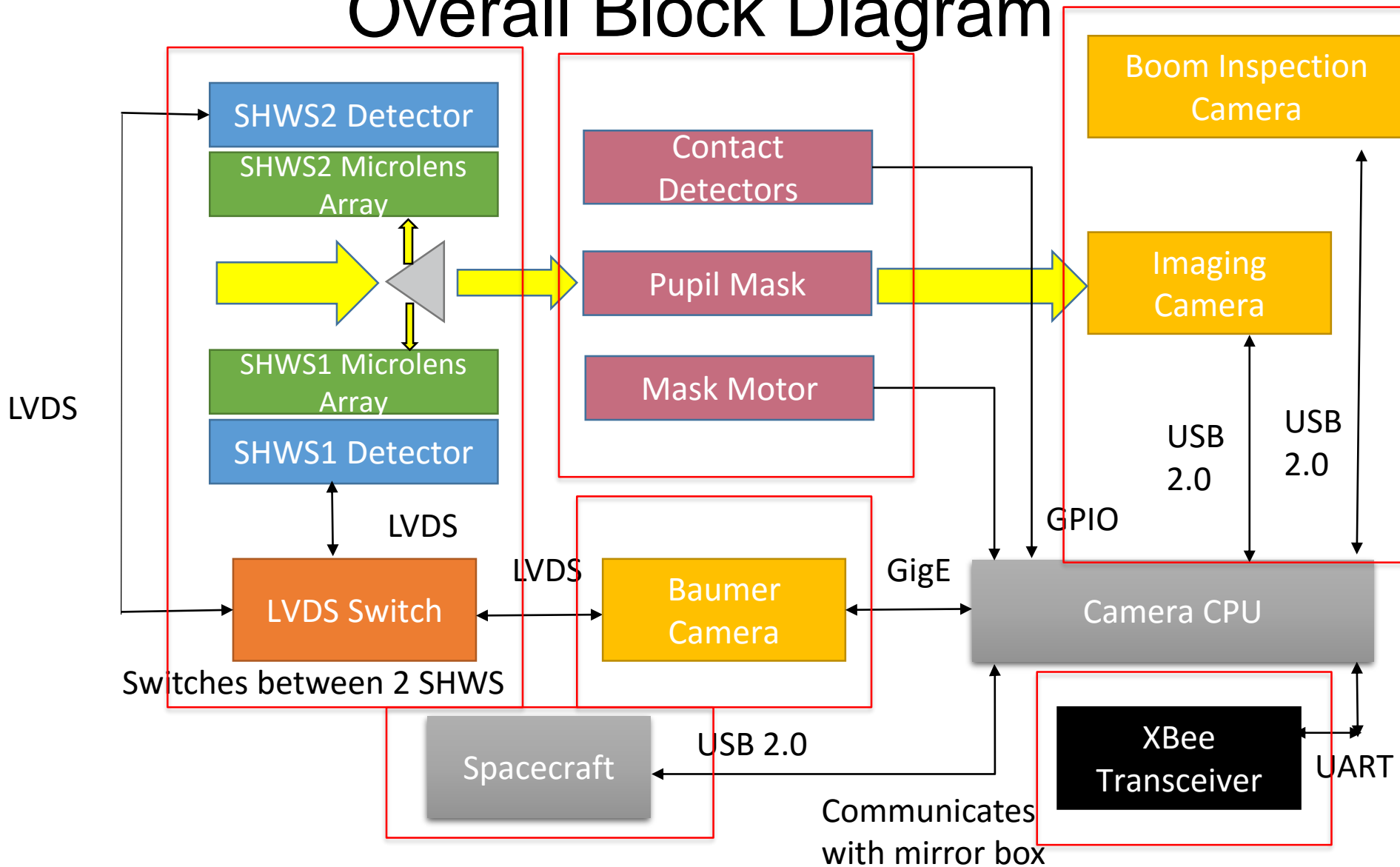
Ashish Goel

Stephen Bongiorno

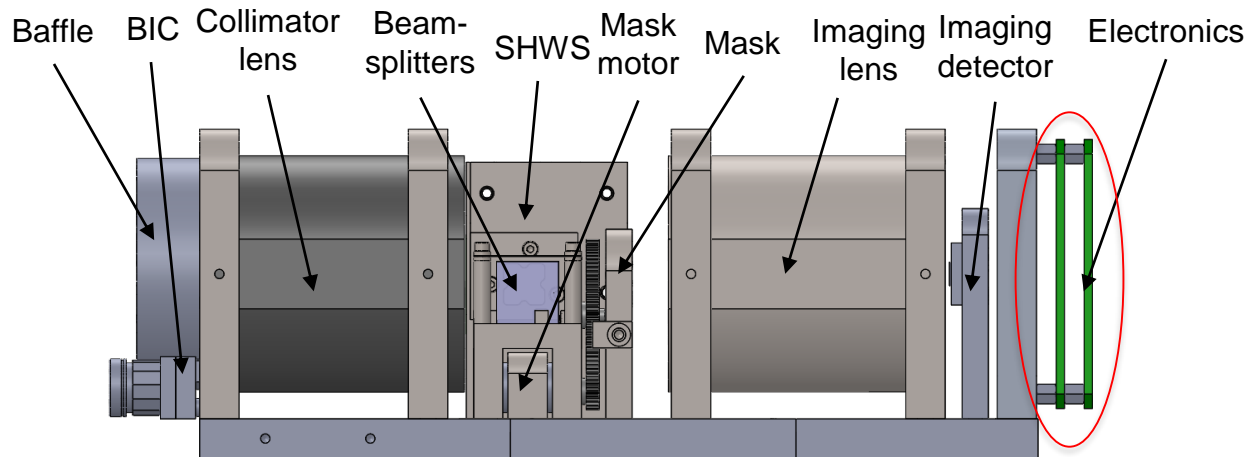
Outline

- Overview of camera electronics
- Task list
- Details of each task completed
- Schedule/Future work

Overall Block Diagram



Camera CAD Model



3 circuit boards in the camera

- **Support board for baumer camera**
- **SHWS (Shack-Hartmann Wavefront Sensor) board**
 - LVDS (Low Voltage Differential Signal) switch
 - Mask motor driver
- **Motherboard**
 - Telescope CPU daughter board
 - XBee daughter board
 - Connectors for peripherals

Task List

- Ramp up on camera, previous work done & EAGLE tool for PCB layout
- LVDS (Low Voltage Differential Signal) switch selection, ordering & testing
- PCB design & layout
 - Motherboard
 - SHWS module board
- PCB fabrication
- PCB testing

Task List

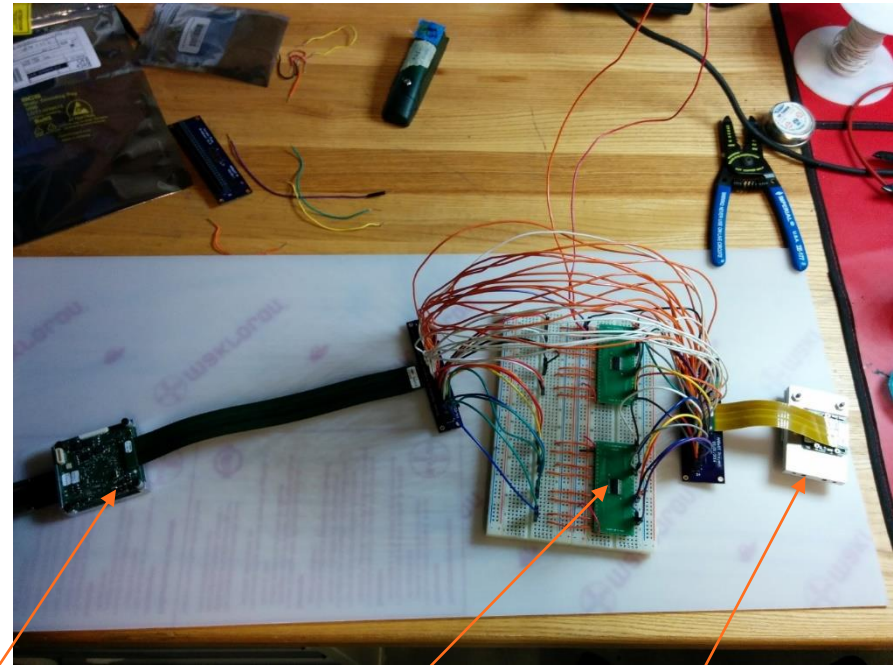
- Ramp up on camera, previous work done & EAGLE tool for PCB layout
- **LVDS (Low Voltage Differential Signal) switch selection, ordering & testing**
- PCB design & layout
 - Motherboard
 - SHWS module board
- PCB fabrication
- PCB testing

LVDS Switch Testing

- ✓ Phase 1: Direct testing
- ✓ Phase 2: Crosstalk characterization
- ✓ Phase 3: Testing with 1 SHWS and Baumer camera
- Phase 4: Testing with 2 SHWS and Baumer camera
 - 2nd SHWS damaged during testing
 - Testing be completed after we receive the 2nd SHWS back from repair

Results

- Positive - meets requirements
- Very low cross-talk noise
- Successfully switches at required rate (@ 2 Hz) between ON & OFF state of 1 SHWS



Baumer
Camera

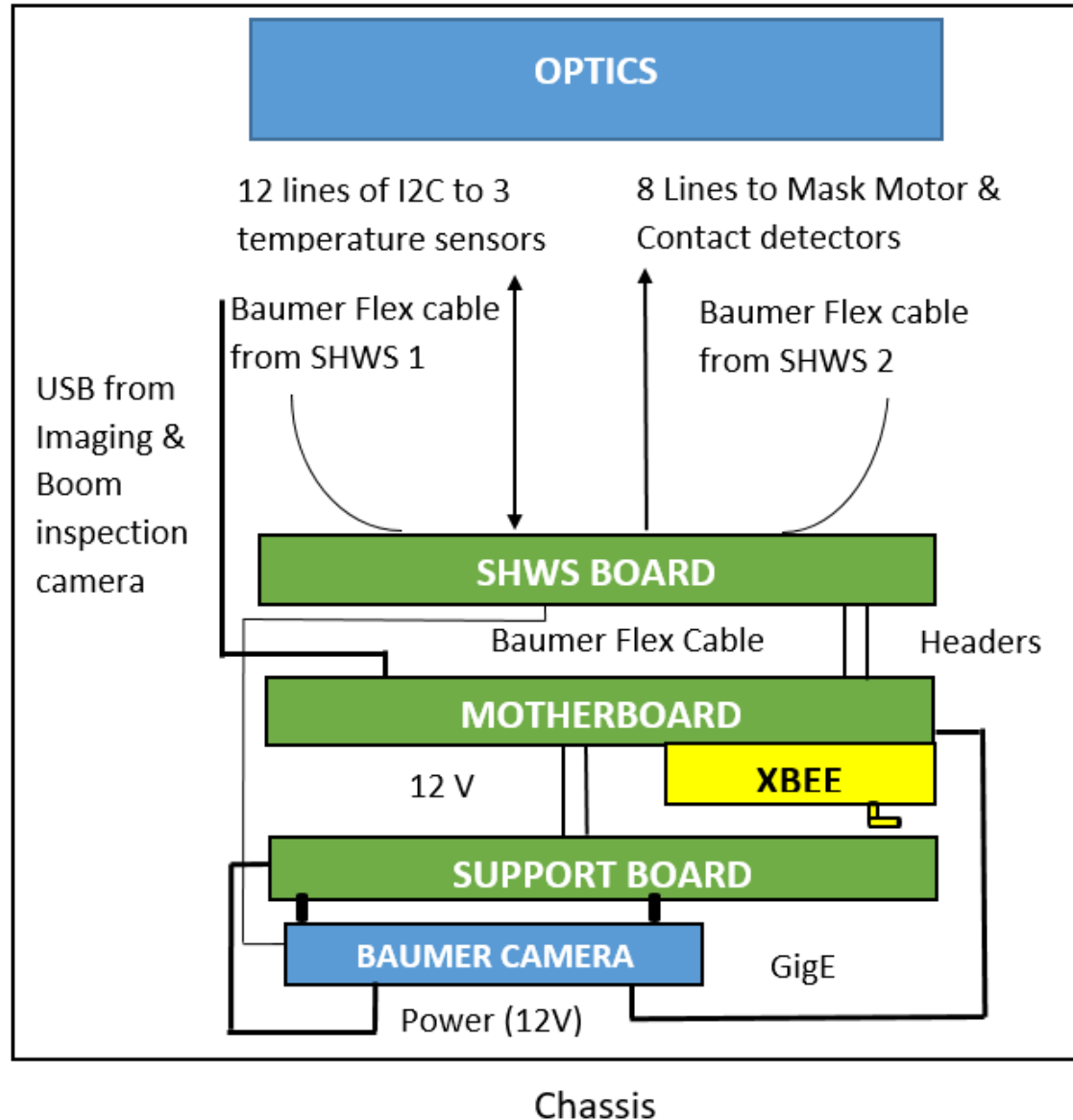
LVDS
Switches

SHWS

Task List

- Ramp up on camera, previous work done & EAGLE tool for PCB layout
- LVDS (Low Voltage Differential Signal) switch selection, ordering & testing
- **PCB design & layout**
 - Motherboard
 - SHWS module board
- PCB fabrication
- PCB testing

On Flight Placement of Boards



Connectors

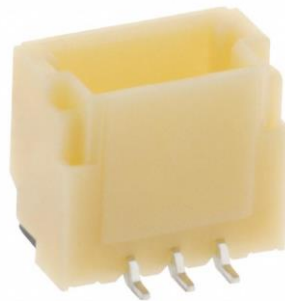
- Need to have a mechanical locking feature for vibration resilient connection
- Insulating material should be low-outgassing



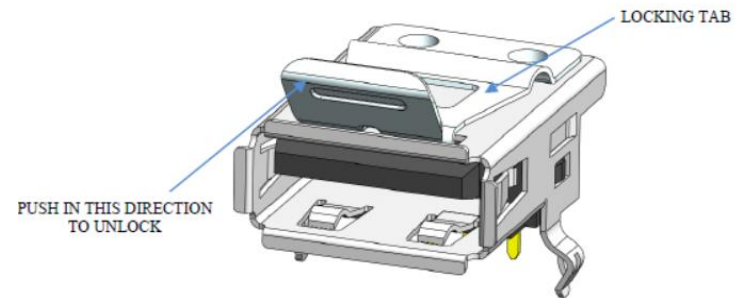
GigE - Pulse Jack



ITT Cannon MDM Series
for I2C and Mask Motor
driver



JST BM03B SRSS
For Baumer camera
connection

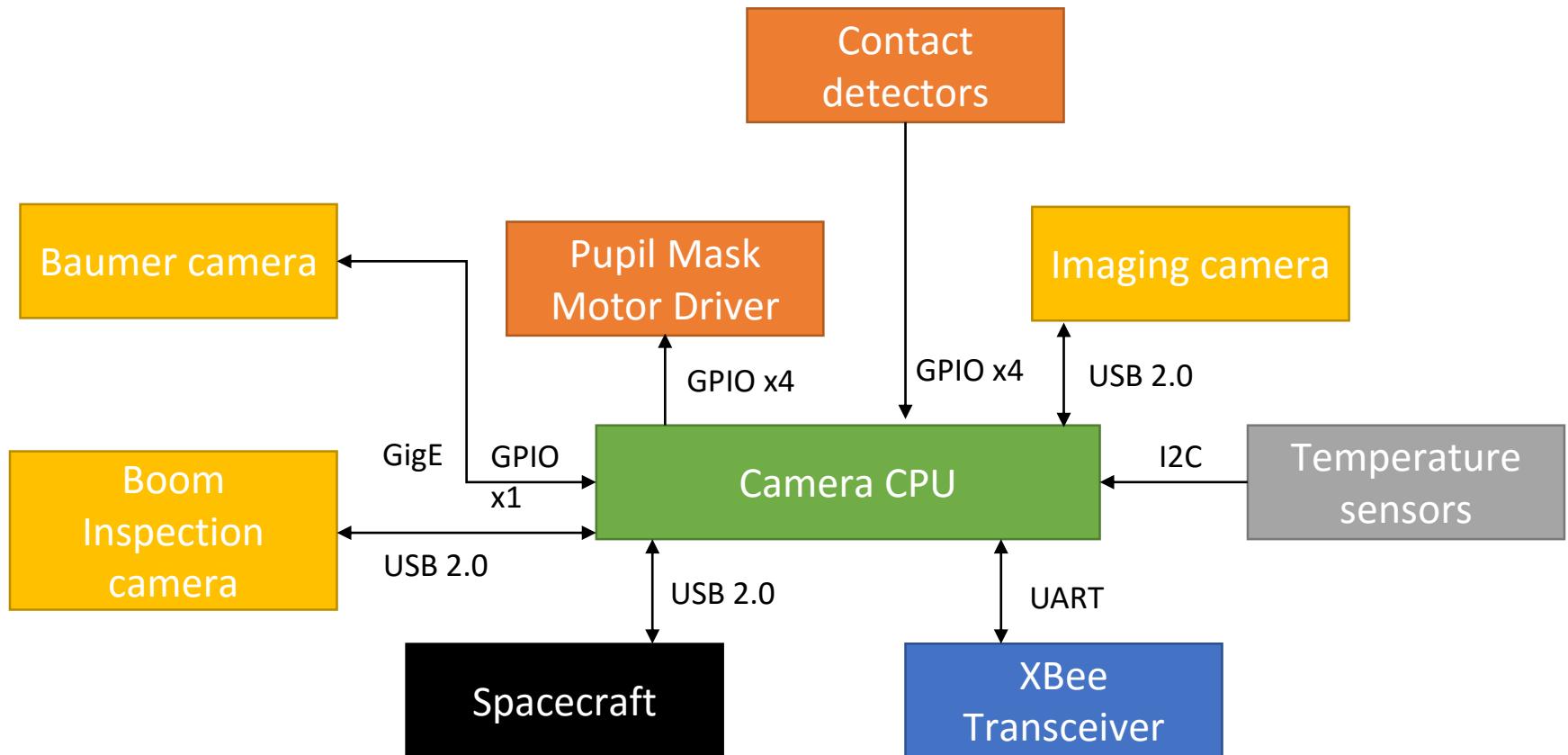


LUSBA11100 for all USB connections –
Like a regular USB type A connector
but with locking

Task List

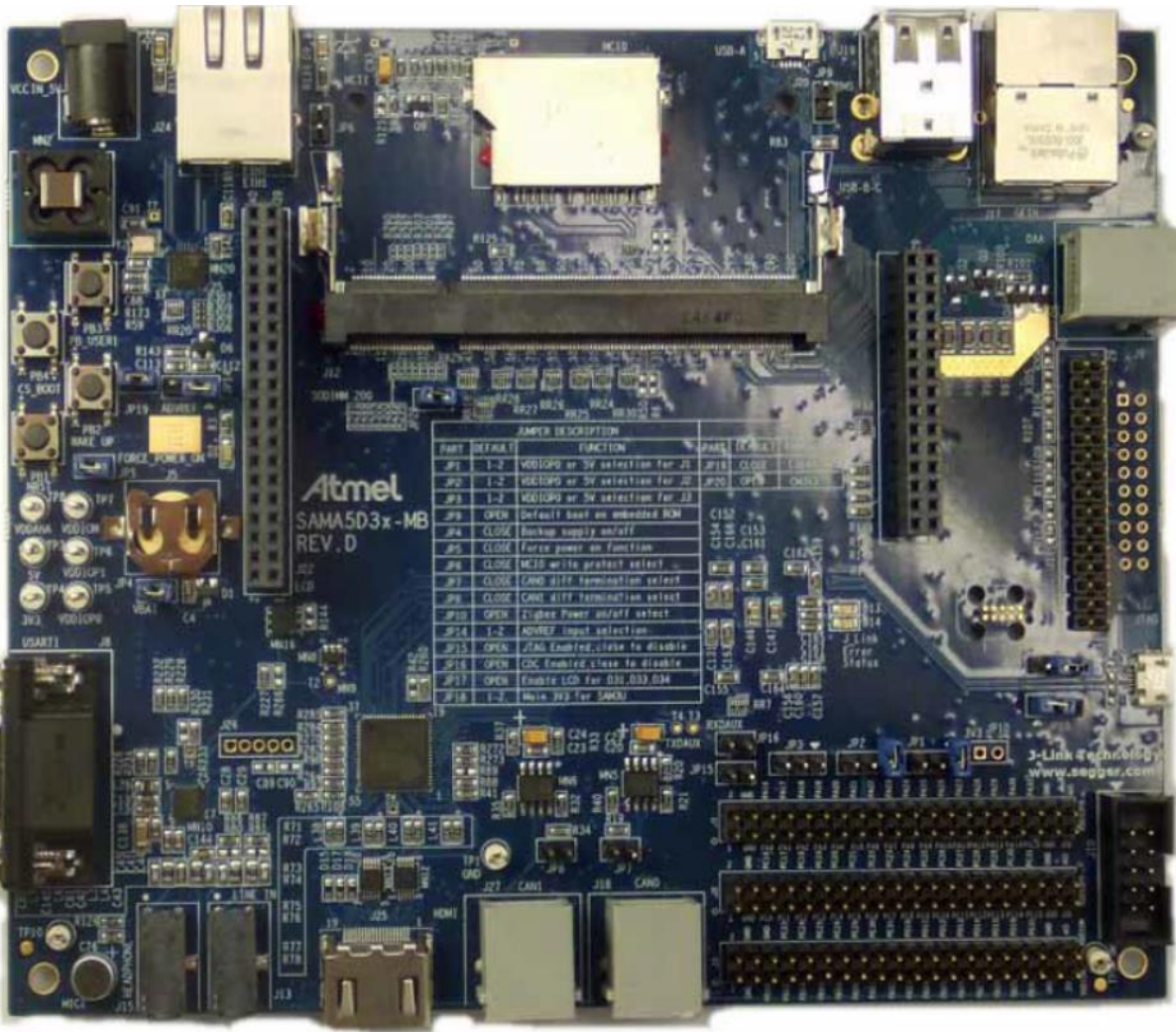
- Ramp up on camera, previous work done & EAGLE tool for PCB layout
- LVDS (Low Voltage Differential Signal) switch selection, ordering & testing
- **PCB design & layout**
 - **Motherboard**
 - SHWS module board
- PCB fabrication
- PCB testing

Motherboard Block Diagram



Motherboard Design

165 mm



Actual Dev board size

135 mm



75 mm

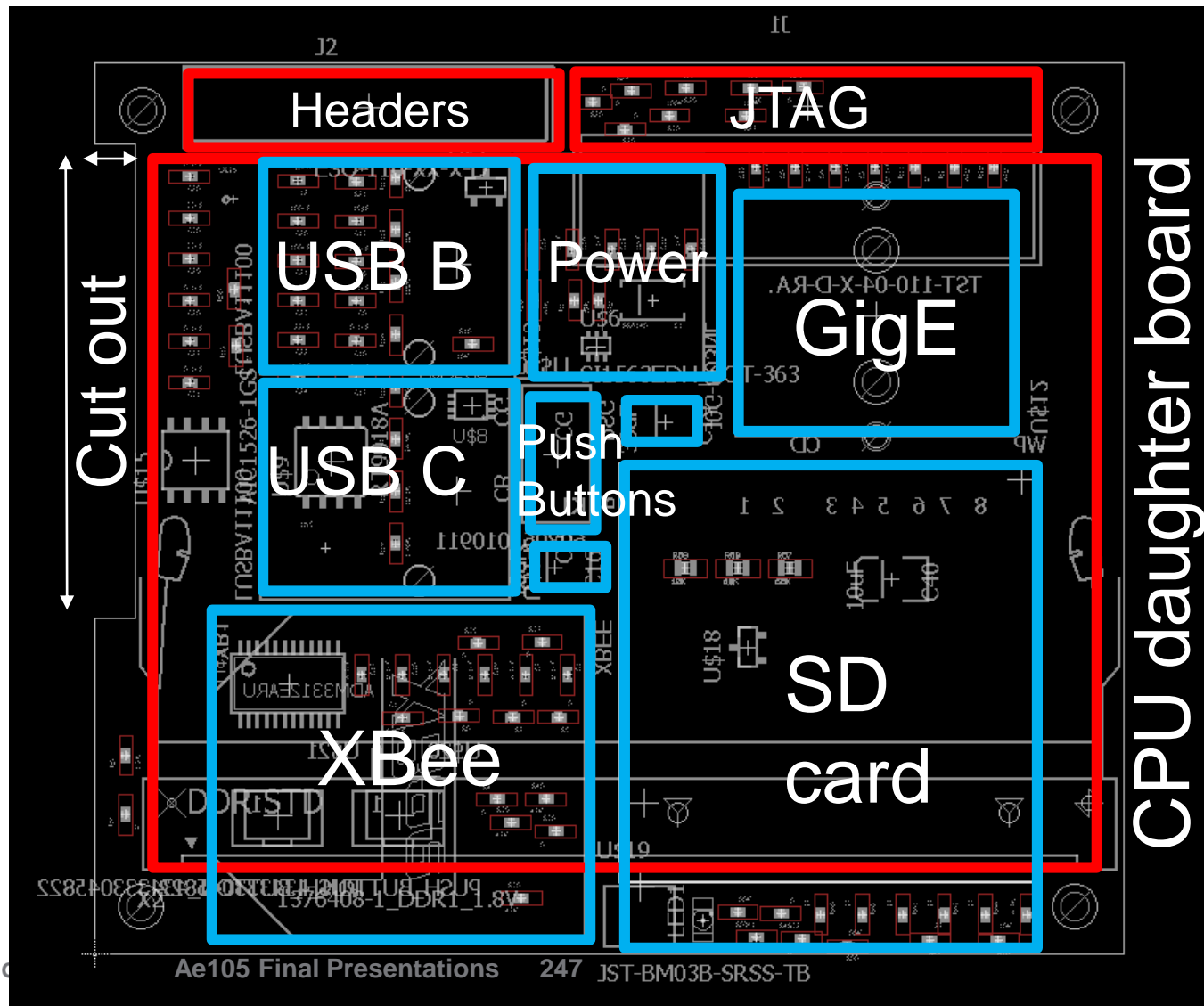


65 mm



Requirement for AAReST

Motherboard - Layout of Components



Components:

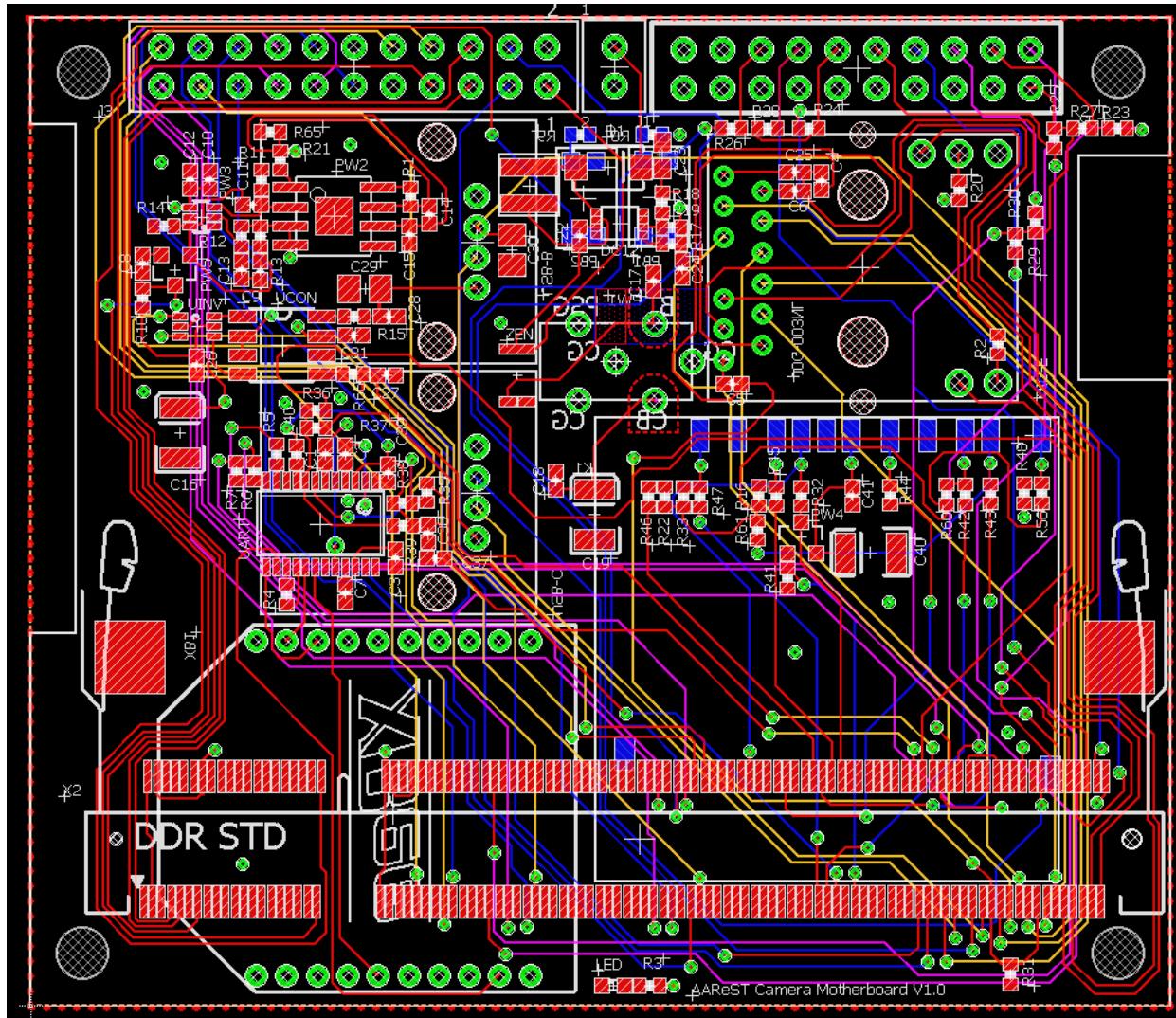
- 22 + 2 pin headers to interact with SHWS
- USB B & USB C to communicate with imaging & boom inspection cameras
- Power management circuit
- GigE for baumer camera
- 2 push buttons
- SD card
- XBee module
- JTAG headers
- CPU daughter board



Top side
Bottom side

Caltech

Motherboard – Final Look

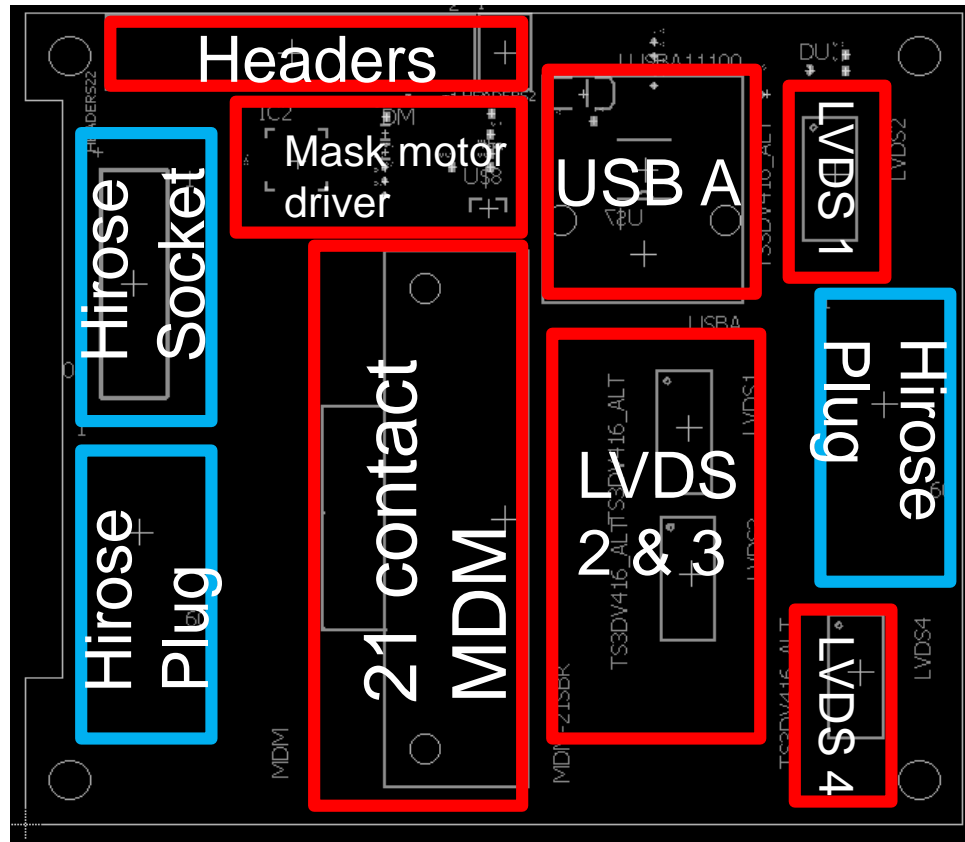


- Final board with completed routing
- 4 layer board
- Has been sent for fabrication

Task List

- Ramp up on camera, previous work done & EAGLE tool for PCB layout
- LVDS (Low Voltage Differential Signal) switch selection, ordering & testing
- **PCB design & layout**
 - Motherboard
 - **SHWS module board**
- PCB fabrication
- PCB testing

SHWS – Layout of Components



Top side

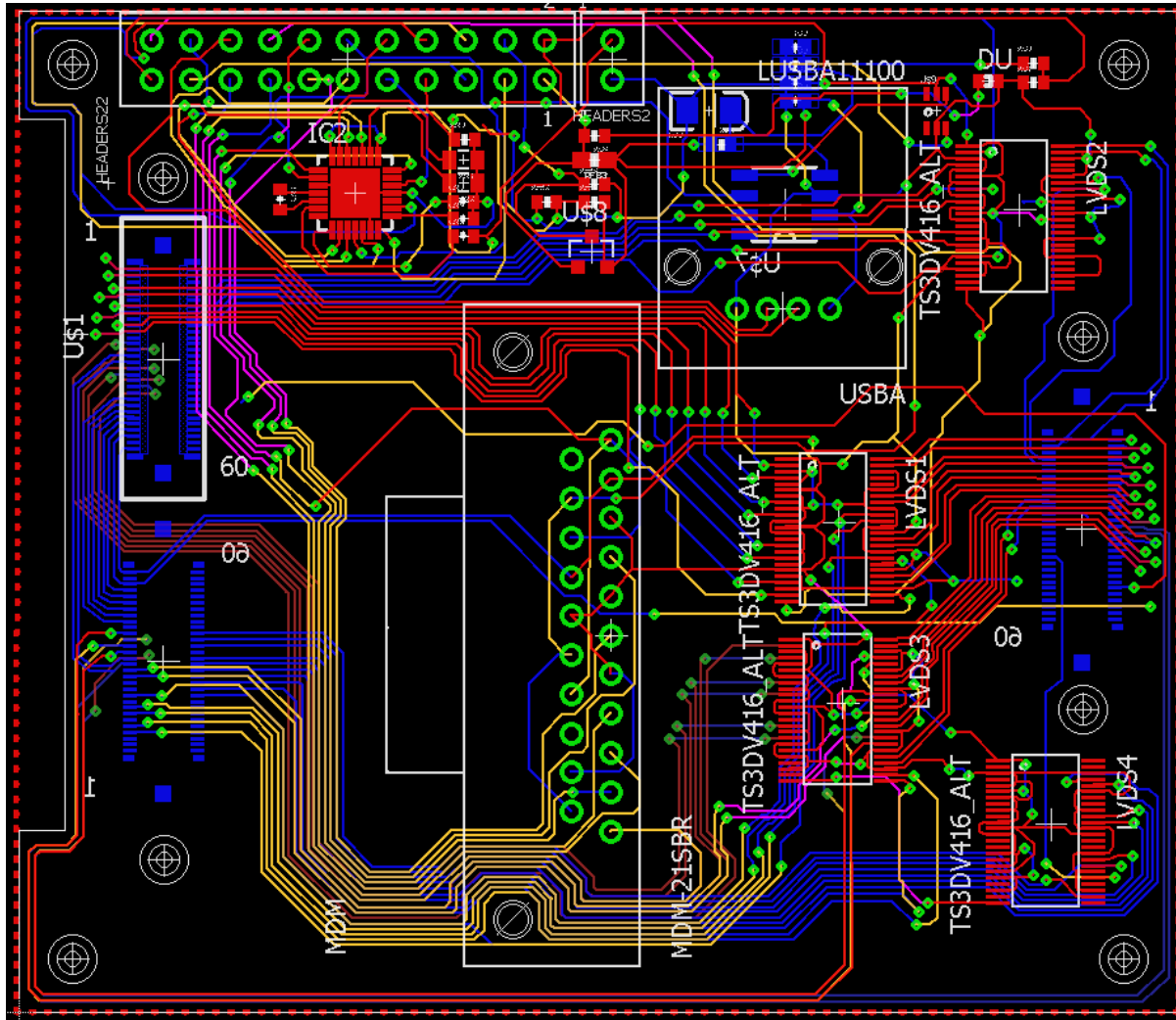


Bottom side

Components:

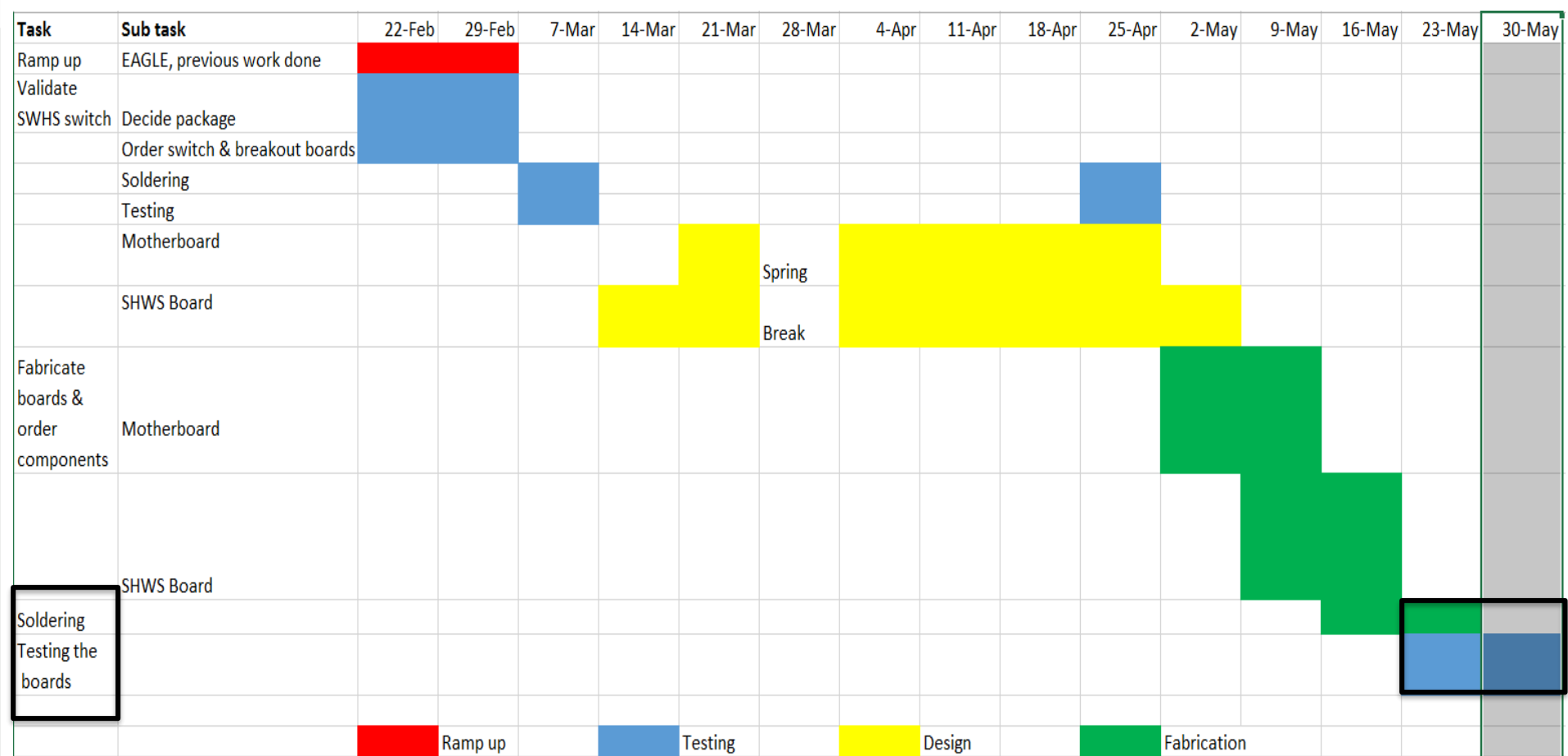
- 22 + 2 pin headers to interact with MB
- USB A to communicate with spacecraft
- 2 Hirose Plugs to receive SHWS signals
- 1 Hirose Receptacle for Baumer camera
- 21 pin MDM connector for mask motor, contact detectors, 3 temperature sensors
- 4 LVDS switches
- Mask motor driver circuit

SHWS Board



- Current board
- 4 layer board
- Some changes being made before sending it out for fabrication

Schedule



AAReST Electronics

Thank you for your attention!

Questions

Andre Sukernik

Saumya Vij

Mentors:

Ashish Goel

Stephen Bongiorno